

TLE9012DQU, TLE9015DQU

Z8F80064984

Preface

Scope and purpose

This document describes the usage of the multi-cell monitoring and balancing IC TLE9012DQU and the transceiver TLE9015DQU designed for Li-ion battery packs used in hybrid electric vehicles (HEV), plug-in hybrid electric vehicles (PHEV), battery electric vehicles (BEV) as well as in stationary Lithium-Ion batteries.

Please also refer to the corresponding datasheets.

Intended audience

This document is intended for engineers who develop applications.

Table of contents

	Preface	1
	Table of contents	2
1	Demo kit	5
1.1	Getting started	5
1.1.1	Hardware elements of the demo kit	5
1.1.2	Hardware connection	5
1.1.3	13-wire setup	8
1.1.4	Flashing the AURIX hardware kit	9
1.1.4.1	DAS tool	9
1.1.4.2	MemTool	9
1.1.4.3	Aurix flashing	9
1.1.4.4	Terminal	16
2	Hardware guideline	19
2.1	Application schematic of one Cell Supervision Circuit (CSC)	19
2.1.1	BOM - EMC, filter and balancing circuit	19
2.1.2	BOM - communication circuit between Cell Supervision Circuits	21
2.1.3	BOM - other supporting components for Cell Supervision Circuits	22
2.1.4	BOM - iso UART termination network	24
2.1.5	Layout guideline	24
2.1.6	Guidance for unused pins	26
2.1.6.1	Unused input pins	26
2.1.6.2	Unused output pins	27
2.1.7	Use of CSC with less than 12 cells	27
2.2	Application schematic transceiver circuit	29
2.2.1	BOM - communication circuit	29
2.2.2	BOM - other supporting components	30
2.3	CSC evaluation board	31
2.4	Transceiver evaluation board	32
2.5	Typical chip performance	33
2.6	EEPROM	36
2.7	13-wire setup	37
2.8	iso UART communication interface	38
2.8.1	Introduction	38
2.8.2	Physical layer overview	38
2.8.3	iso UART measurement point	39
2.8.4	Capacitive coupled signal	40
2.8.5	Transformer coupled signals	41
3	Software guideline	49

Table of contents

3.1	Initialization	49
3.1.1	CRC	51
3.1.2	Read back of configuration registers	52
3.2	Configuration	52
3.2.1	Partitioning config	52
3.2.2	Cell voltage thresholds	52
3.2.3	Open load diagnostics	53
3.2.4	NTC temperature measurement configuration	54
3.2.5	Balancing current thresholds	54
3.3	Cell voltage measurement	55
3.3.1	Primary cell voltage measurement	55
3.3.2	Block voltage measurement	56
3.3.3	Bipolar auxiliary voltage measurement	56
3.4	Calculations	57
3.4.1	Voltage, PCVM, SCVM, BVM	57
3.4.2	Temperature measurement unit	58
3.5	Balancing	58
3.6	Sleep mode and register reset	59
3.6.1	Sleep mode	59
3.6.2	Sleep mode registers reset	59
4	Registers	61
4.1	Registers overview	61
4.2	Registers overview - REG (ascending offset address)	61
4.3	Partitioning config (supplied in sleep)	64
4.4	Cell voltage thresholds (supplied in sleep)	65
4.5	Cell voltage thresholds (supplied in sleep)	66
4.6	Temperature measurement configuration (supplied in sleep)	67
4.7	Internal temperature measurement configuration (supplied in sleep)	68
4.8	Round robin ERR counters (supplied in sleep)	69
4.9	Round robin configuration (supplied in sleep)	70
4.10	ERR pin / EMM mask (supplied in sleep)	72
4.11	General diagnostics (supplied in sleep)	74
4.12	Cell voltage supervision warning flags UV (supplied in sleep)	77
4.13	Cell voltage supervision warning flags OV (supplied in sleep)	78
4.14	External overtemperature warning flags (supplied in sleep)	79
4.15	Diagnostics open load (supplied in sleep)	81
4.16	REG_CRC_ERR (supplied in sleep)	82
4.17	Cell voltage supervision warning flags UV (supplied in sleep)	83
4.18	Cell voltage supervision warning flags OV (supplied in sleep)	84
4.19	Operation mode	85
4.20	Balancing current thresholds	86
4.21	Balance settings	87

Table of contents

4.22	Auxiliary voltage measurement configuration	88
4.23	Measurement control	90
4.24	Primary cell voltage measurement i	92
4.25	SCVM highest cell voltage	93
4.26	SCVM lowest cell voltage	94
4.27	Stress correction PCVM	95
4.28	Block voltage measurement	96
4.29	Temp result 0	97
4.30	Temp result 1	98
4.31	Temp result 2	99
4.32	Temp result 3	100
4.33	Temp result 4	101
4.34	Temp result R diagnose	102
4.35	Chip temperature	103
4.36	Multiread command	104
4.37	Multiread configuration	105
4.38	Passive balancing diagnostics OVERCURRENT	106
4.39	Passive balancing diagnostics UNDERCURRENT	107
4.40	Chip temperature 2	108
4.41	Configuration	109
4.42	General purpose input / output	110
4.43	PWM settings	112
4.44	IC version and manufacturing ID	113
4.45	Mailbox register	114
4.46	Customer ID 0	115
4.47	Customer ID 1	116
4.48	Watchdog counter	117
4.49	SCVM configuration	118
4.50	Stress correction AUX	119
4.51	Balancing PWM	120
4.52	Balancing counter register 0	121
4.53	Balancing counter register 1	122
4.54	Balancing counter register 2	123
4.55	Balancing counter register 3	124
	Revision history	125
	Disclaimer	126

1 Demo kit

1 Demo kit

1.1 Getting started

1.1.1 Hardware elements of the demo kit

Note: All different versions of the evaluation boards are compatible to each other and can be used in the same daisy chain.

The following hardware is necessary to start with the TLE9012DQU demo kit:

- TLE9012DQU demo board
- At least 1x iso UART cable
- TLE9015DQU transceiver board
- AURIX™ TC265 TFT application kit
- 12 V power supply
- Micro USB cable
- Power supply for the resistor ladder (5 V - 60 V)
- Optional: 12 Li-Ion cells (instead of resistor ladder)

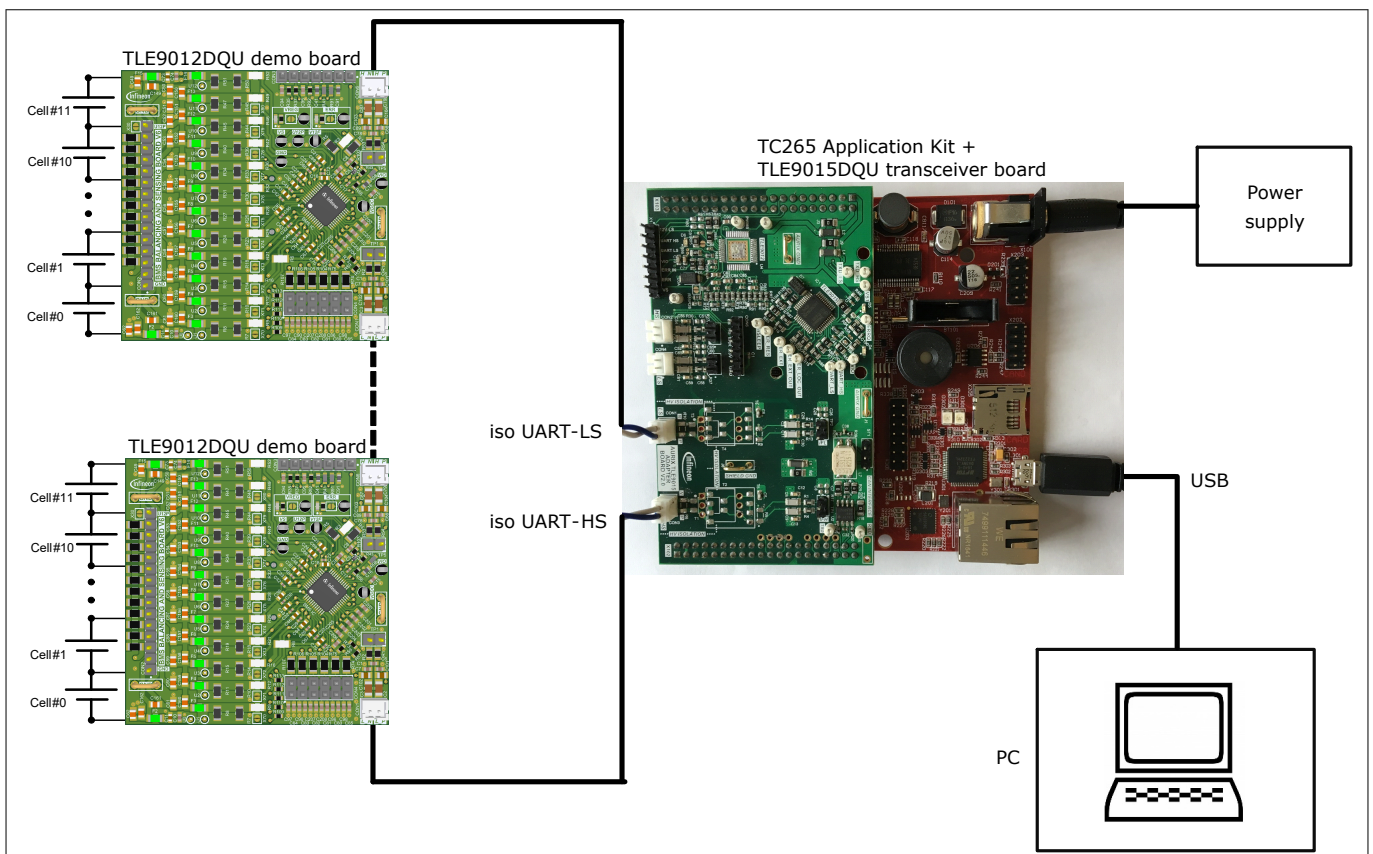


Figure 1 Demo kit BMS

1.1.2 Hardware connection

The hardware is connected as follows:

- The TLE9015DQU transceiver board is plugged onto the AURIX™ board (orientation as in figure [Demo kit BMS](#)).
- A resistor ladder is included on the sensing IC demo board and already connected through a solder bridge.
- The sensing IC demo board must be supplied with a voltage between 5 V - 60 V.

1 Demo kit

- The AURIX™ board must be supplied with a 12 V power supply and connected to a PC via a USB cable.
- The iso UART cable (blue/white) cable connects the transceiver board with the sensing board.

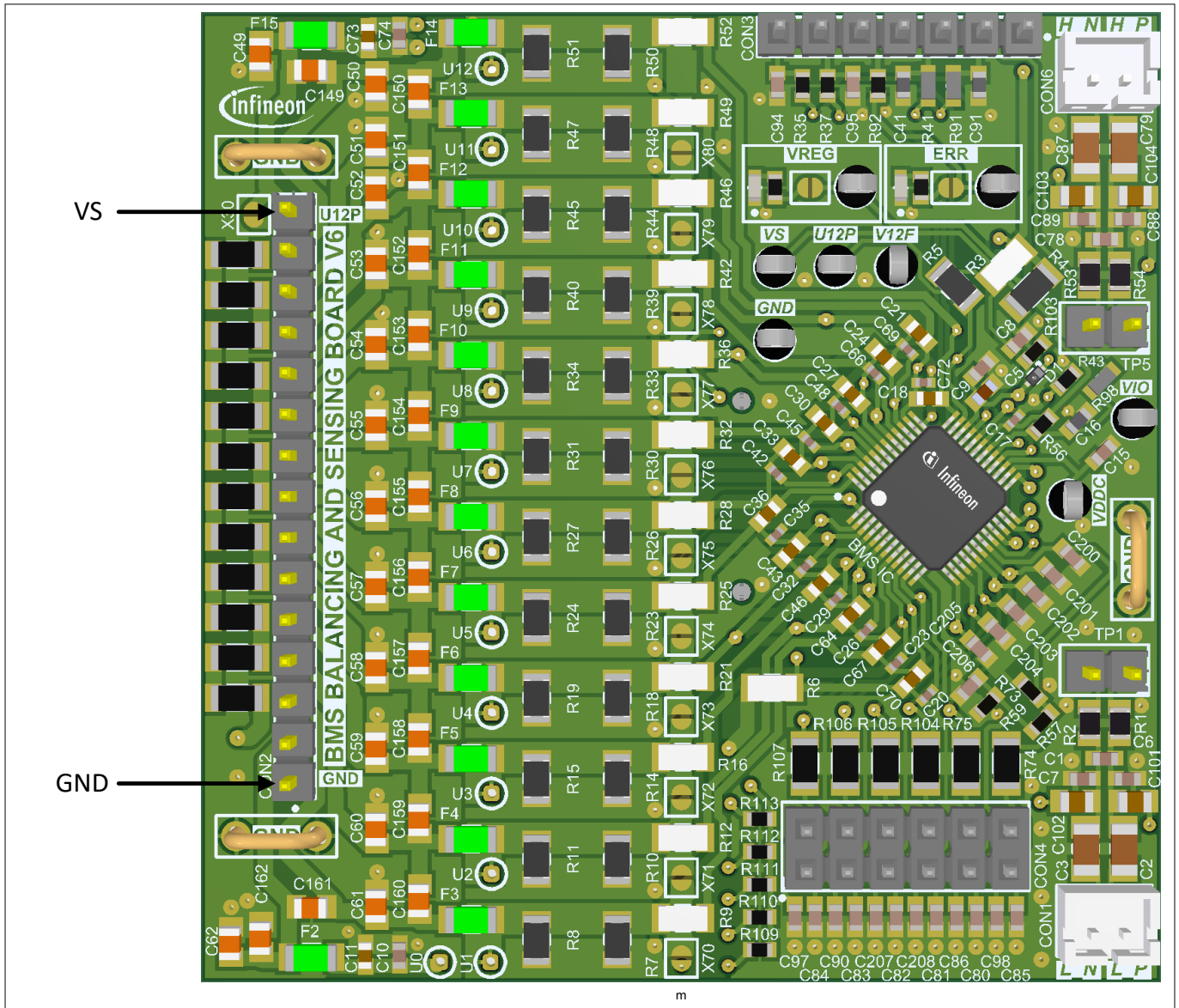


Figure 2 Sensing IC demo board

Note: The sensing IC demo board can be connected either to cells (if the board should be connected to a battery pack, the solder bridges need to be removed see figure [Sensing IC demo board solder bridge](#)) or to a power supply using the on-board resistor ladder. If the resistor ladder is used, an open load error is wrongly detected and the corresponding bit in the general diagnostics register (GEN_DIAG) is set. This is because the internal resistance of Li-Ion cells is much smaller than the resistance of the resistor ladder. The open load error can be deactivated by setting the bitfields OL_OV_THR.OL_THR_MAX and OL_UV_THR.OL_THR_MIN to 00_H. All other functions such as cell voltage measurement, temperature etc. are possible without limitation.

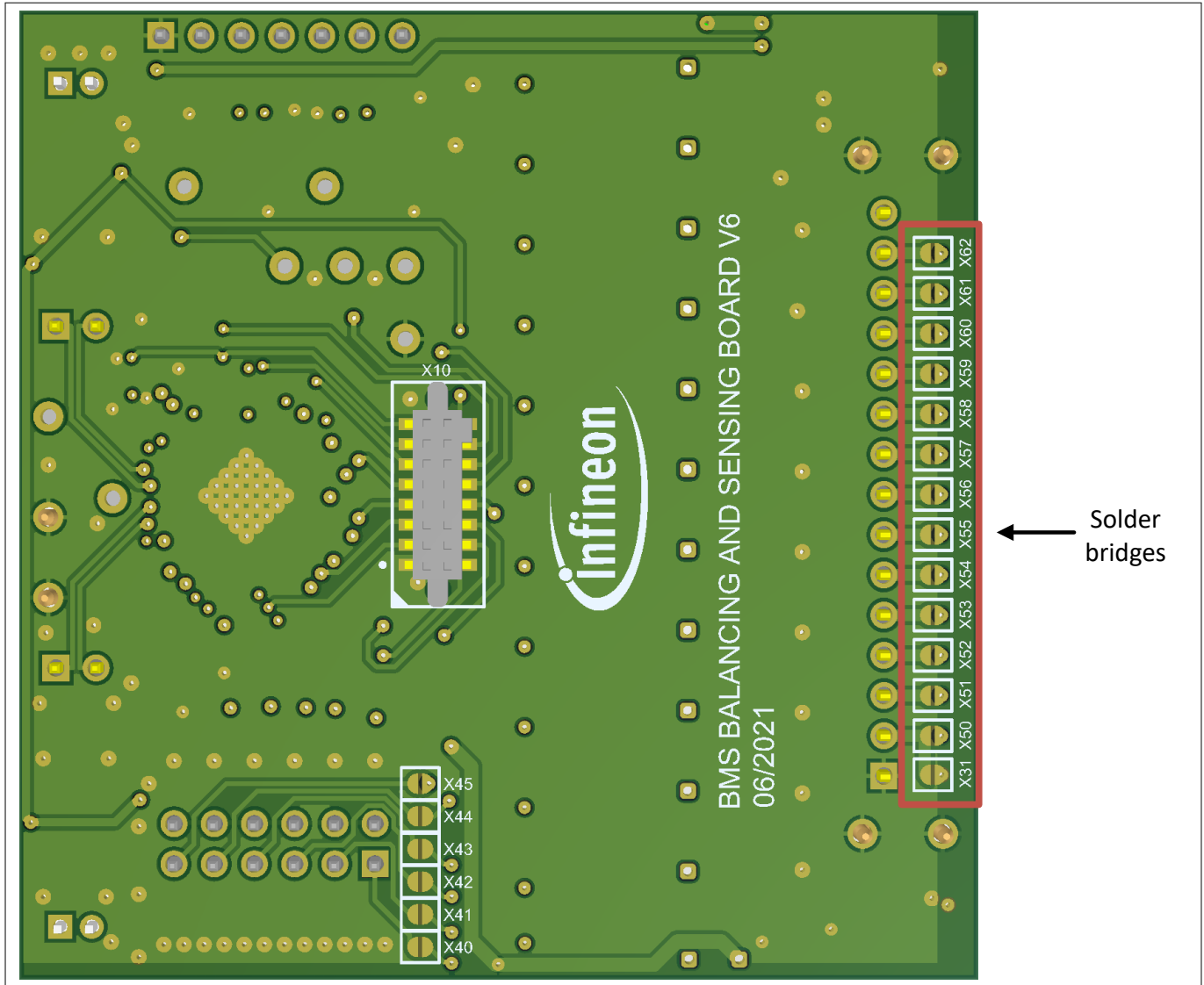


Figure 3 Sensing IC demo board solder bridges

Note: The transceiver IC demo board can be supplemented with additional transformers. In order to be able to use the demo board with transformers, the 0 Ω resistors R99, R100, R101 and R102 must be removed and the transformers have to be place at Tx depending on the footprint (see figure below).

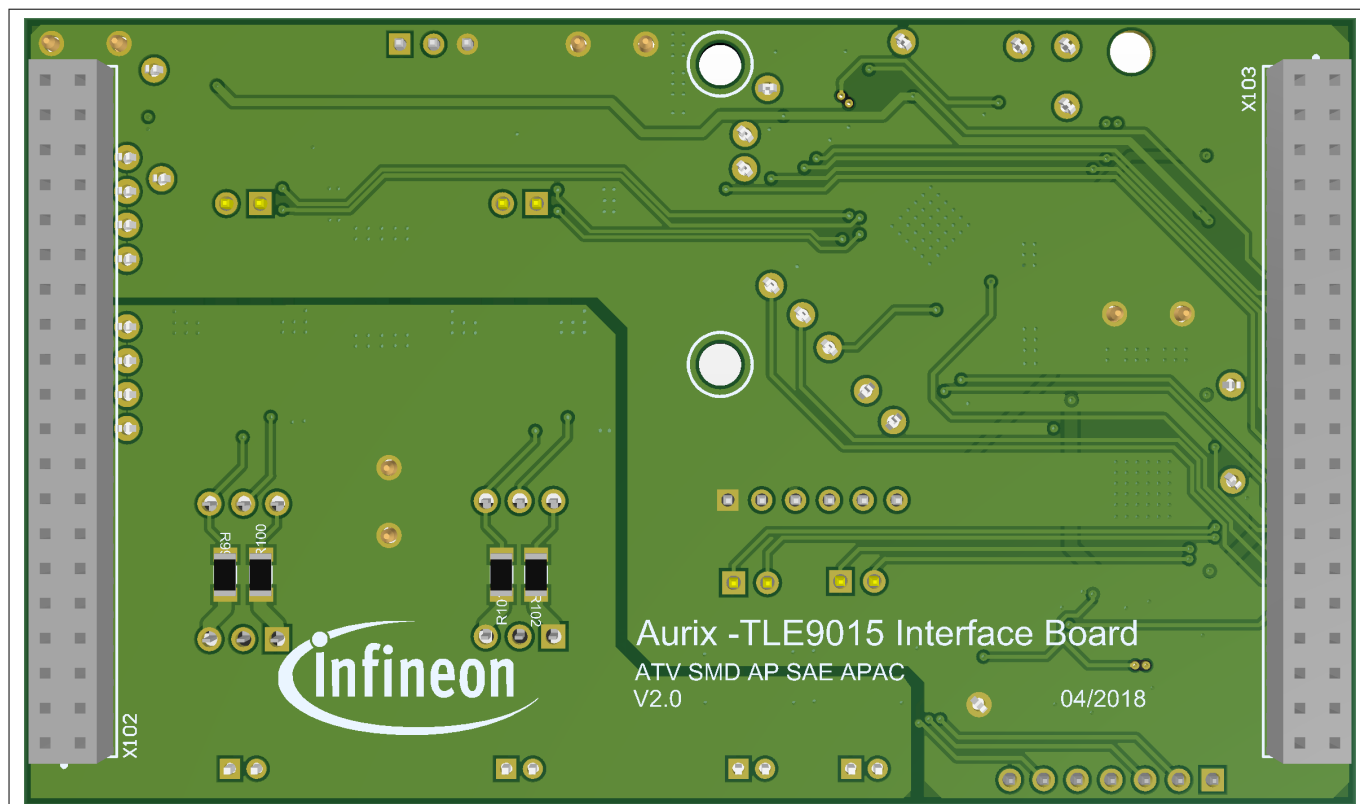


Figure 4 Transceiver IC demo board bottom

1.1.3 13-wire setup

The BMS sensing board can be used in a 13-wire or 15-wire configuration (see [13-wire setup](#)). For a 13-wire setup, the solder bridges X30 and X31 must be soldered.

1 Demo kit

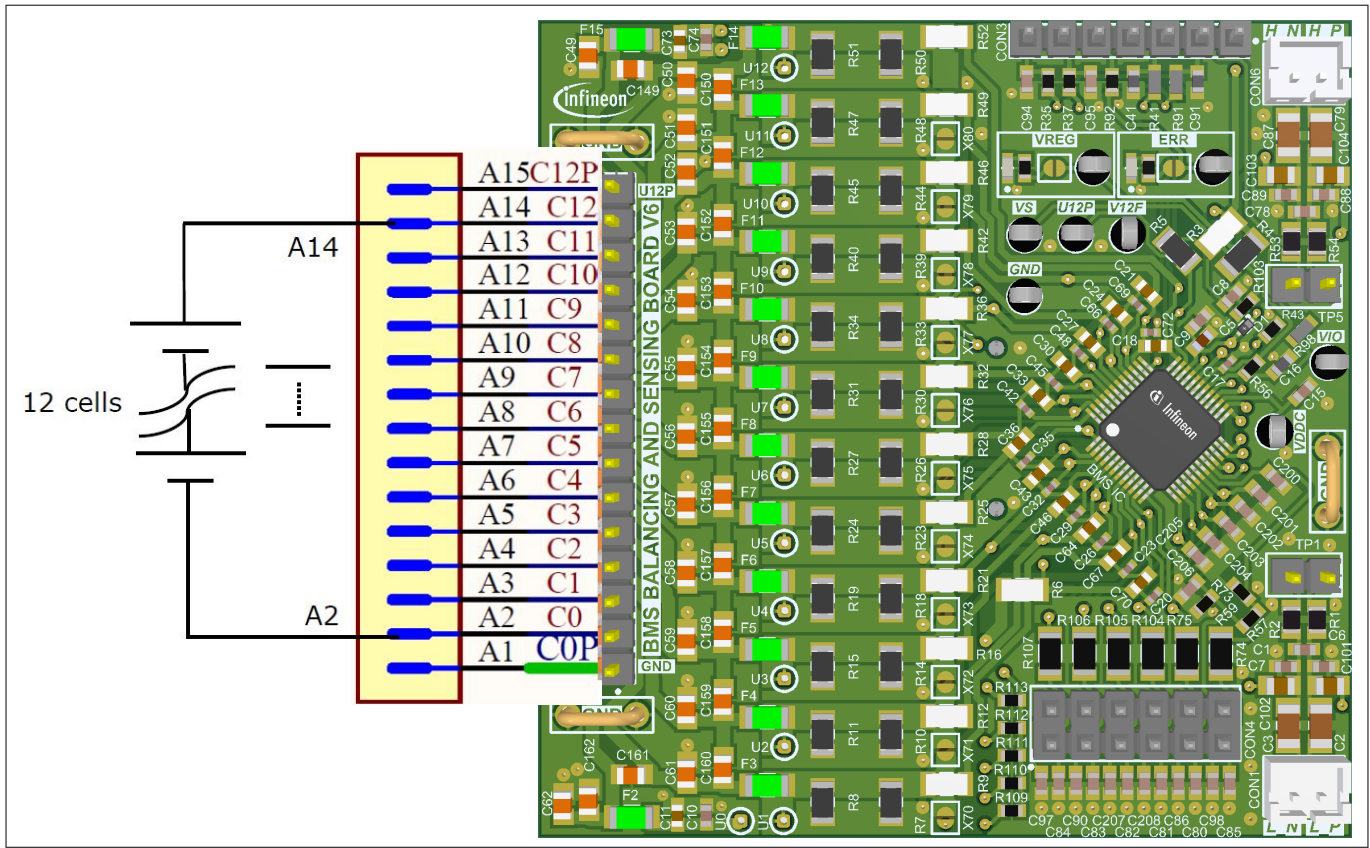


Figure 5 13-wire setup

1.1.4 Flashing the AURIX hardware kit

The following steps are required to setup the framework for the demo kit.

1.1.4.1 DAS tool

The DAS tool is a USB driver software provided by Infineon. It is required to connect the AURIX™ hardware kit to the PC environment. The latest version can be found here: [Link to DAS tool](#)

DAS tool

To start the installation, administrator privileges are requirement and the terms of use need to be accepted. After the successful installation of DAS, the PC should be able to detect the AURIX™ kit under the COM port settings in the device manager.

1.1.4.2 MemTool

The MemTool is a software from Infineon for on-chip flash programming. The latest version can be found here: [Link to MemTool](#)

MemTool

Click “Accept & Open” to download the software and run the installation afterwards.

1.1.4.3 Aurix flashing

The AURIX™ kit needs to be connected to a 12 V power supply. A USB cable connects the board to the PC.

1 Demo kit

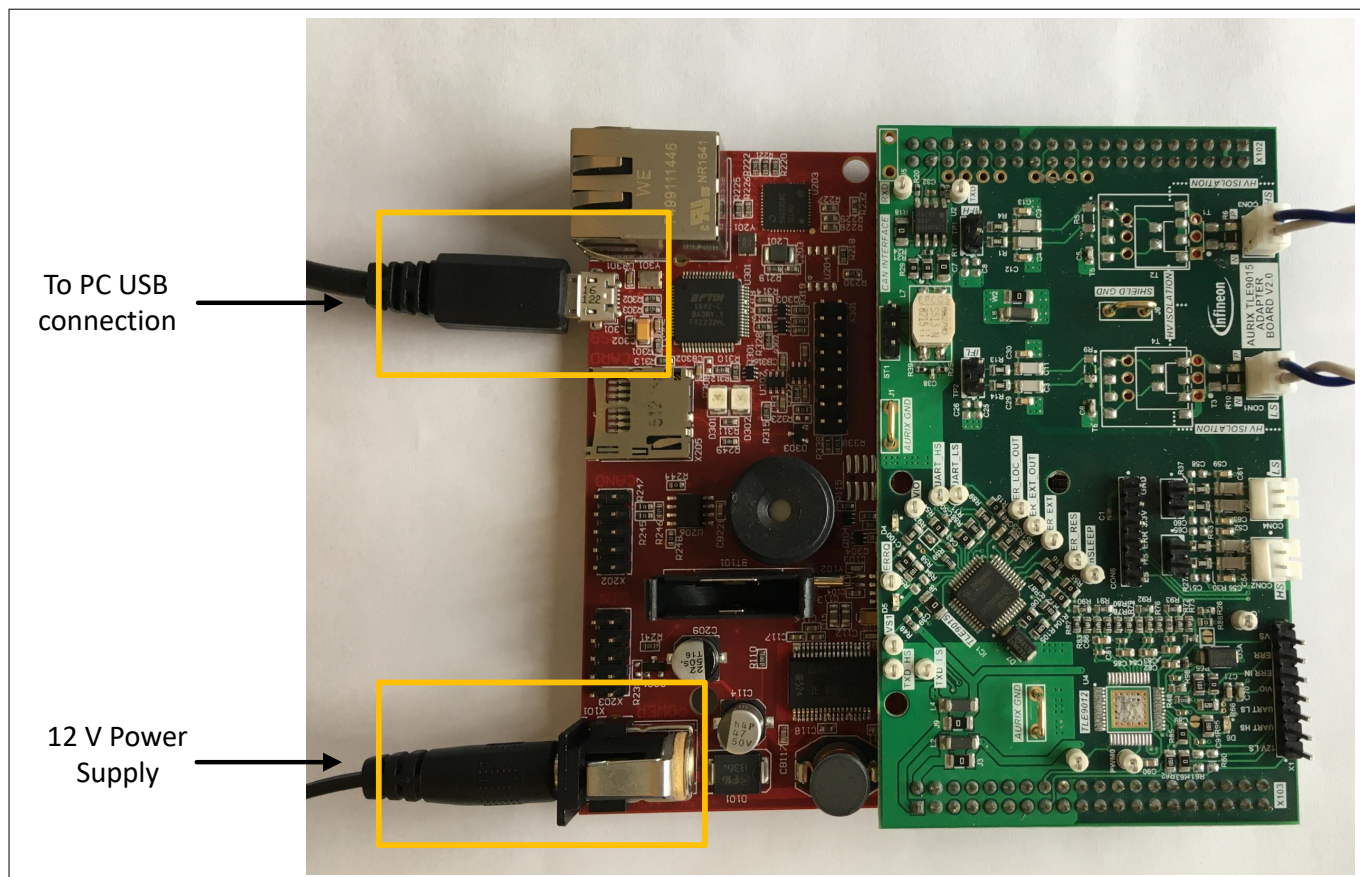


Figure 6 AURIX™ power supply and USB connection

Press the “START” button to initialize. When LED D10 lights up, the AURIX™ has started up successfully.

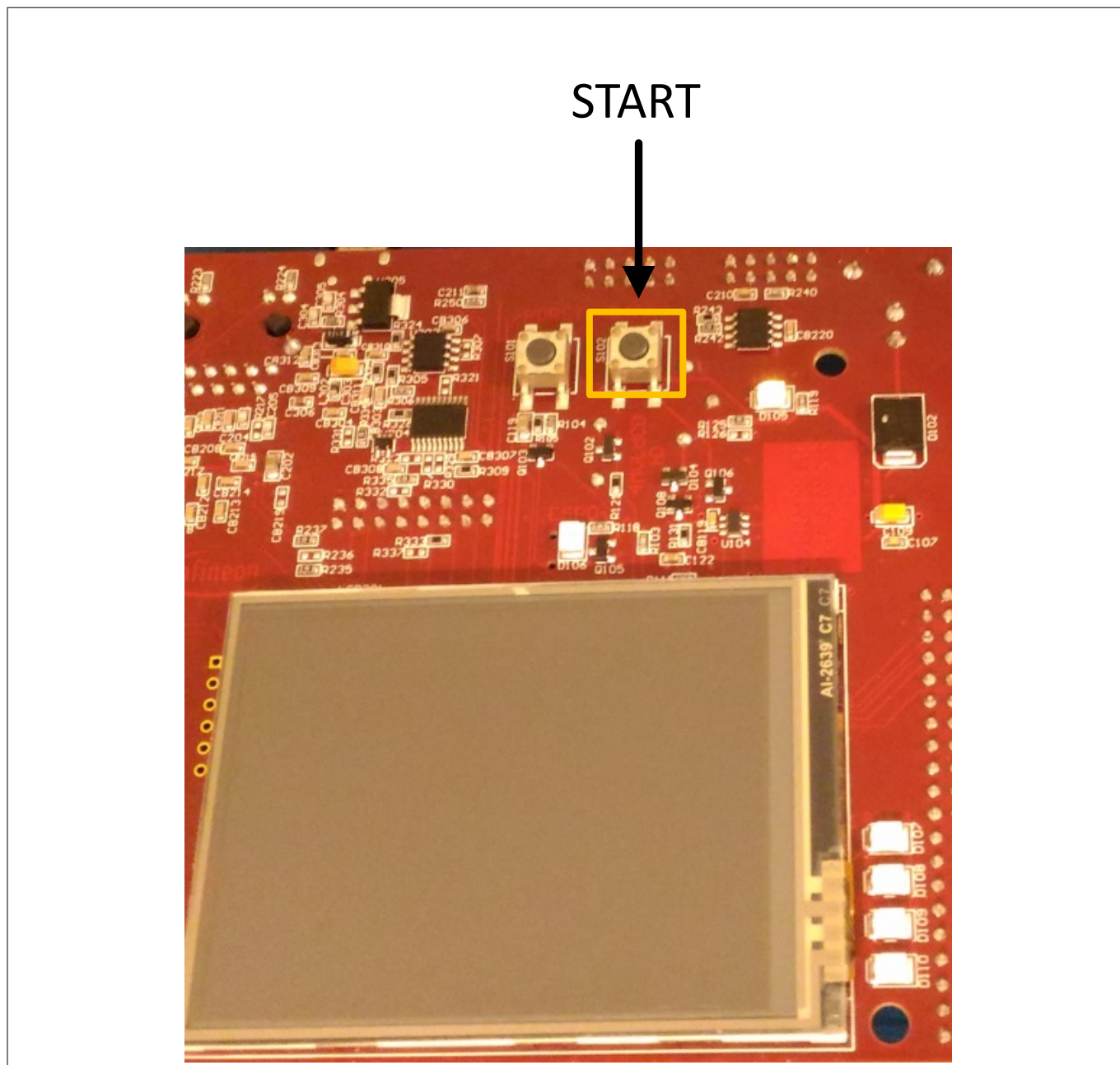


Figure 7 **AURIX initialize**

Open the device manager and expand “Universal Serial Bus controllers”. Right click on “Infineon DAS JDS COM” to open the properties. Select the tab “Advanced”, check “Load VCP” and click “OK”.

1 Demo kit

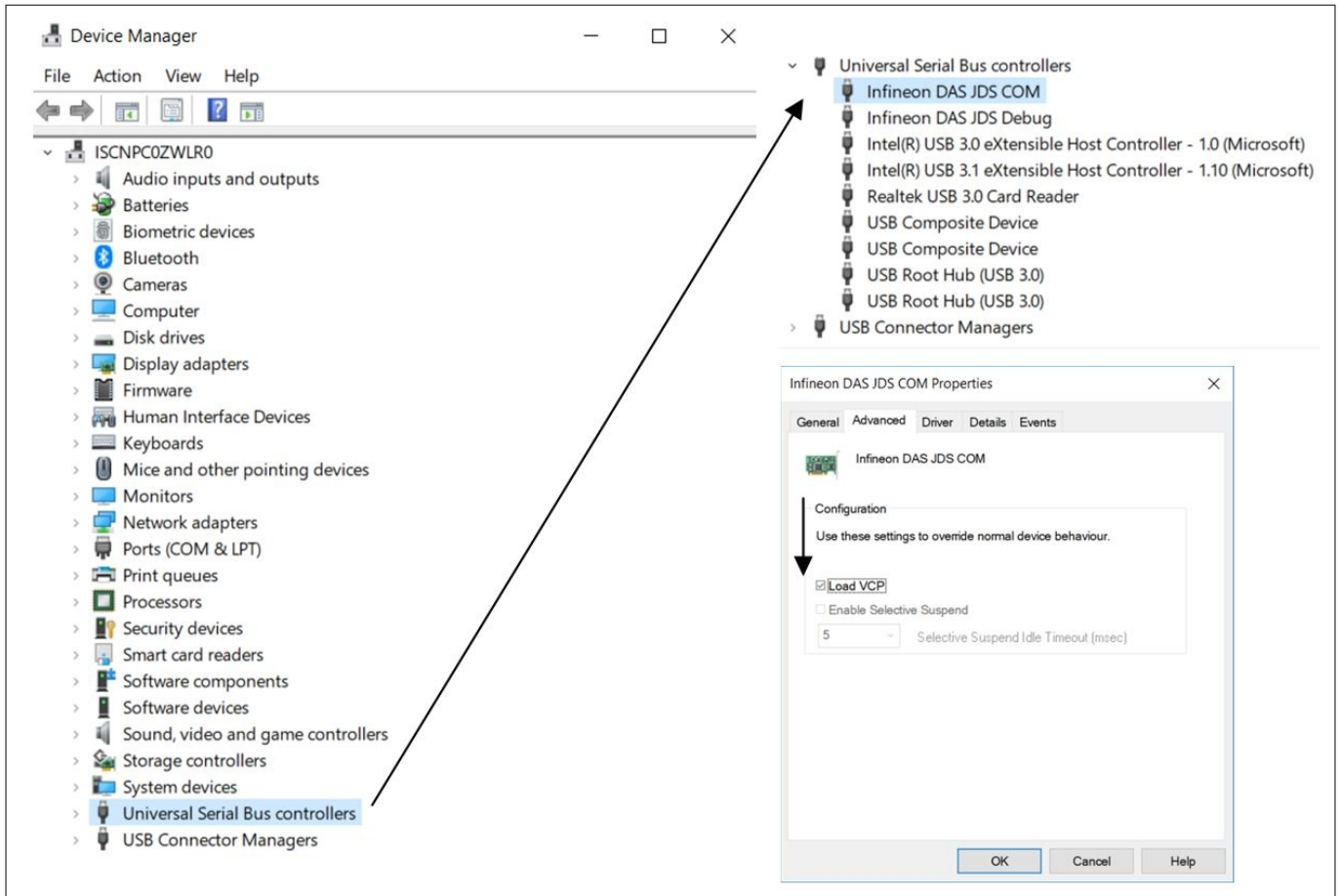


Figure 8 Configuration of the COM port

Disconnect the USB cable and power supply and reconnect. After pressing “START”, check the COM port number in the device manager by expanding “Ports (COM & LPT)”. A port number is assigned to the AURIX™ kit.

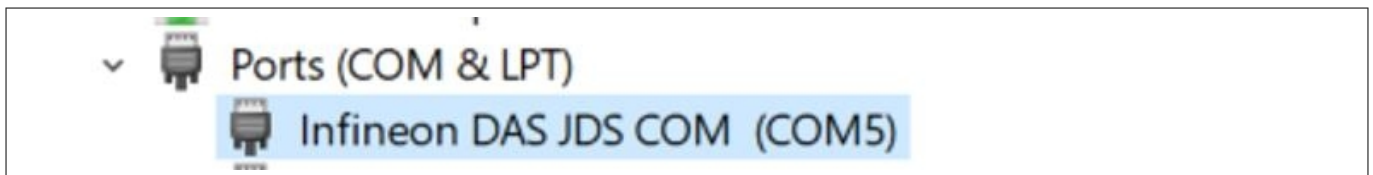


Figure 9 Infineon DAS JDS COM port

Open the MemTool and go to “Target” → “Change...”.

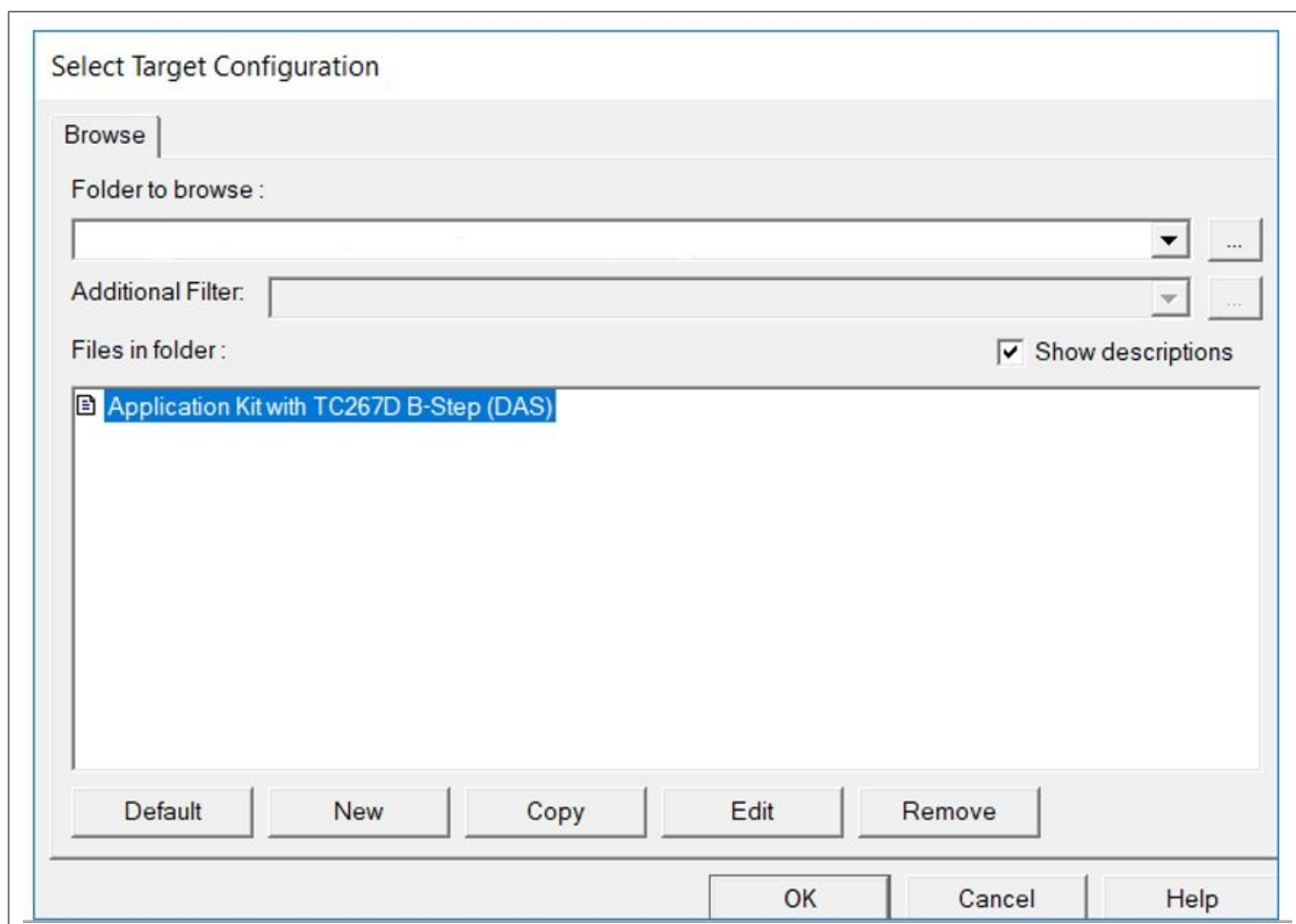


Figure 10 **Select target configuration**

Click on “New” and select “Use a default target configuration”. Expand “TriCore Aurix” → “Application Kits (DAS)”. Select “Application Kit with TC267D B-Step(DAS)” as shown in figure [Create or use default](#).

1 Demo kit

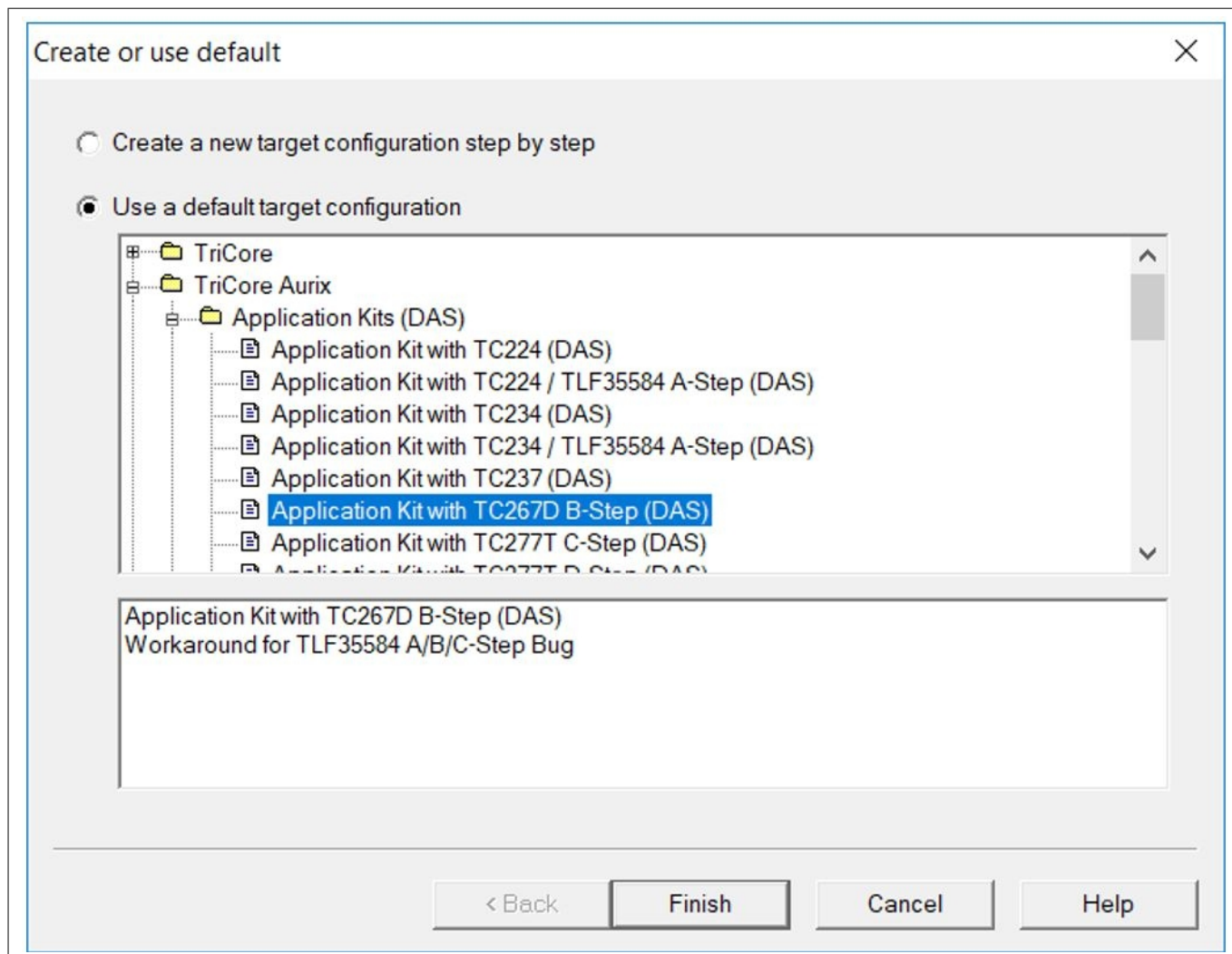


Figure 11 Create or use default

Click “Finish” and save the target configuration file, then select “OK”. After selecting the target configuration, click on “Connect”. If the connection is successful, you will be able to see this message “ready for MemTool Command”. Click on “Open File ...”.

1 Demo kit

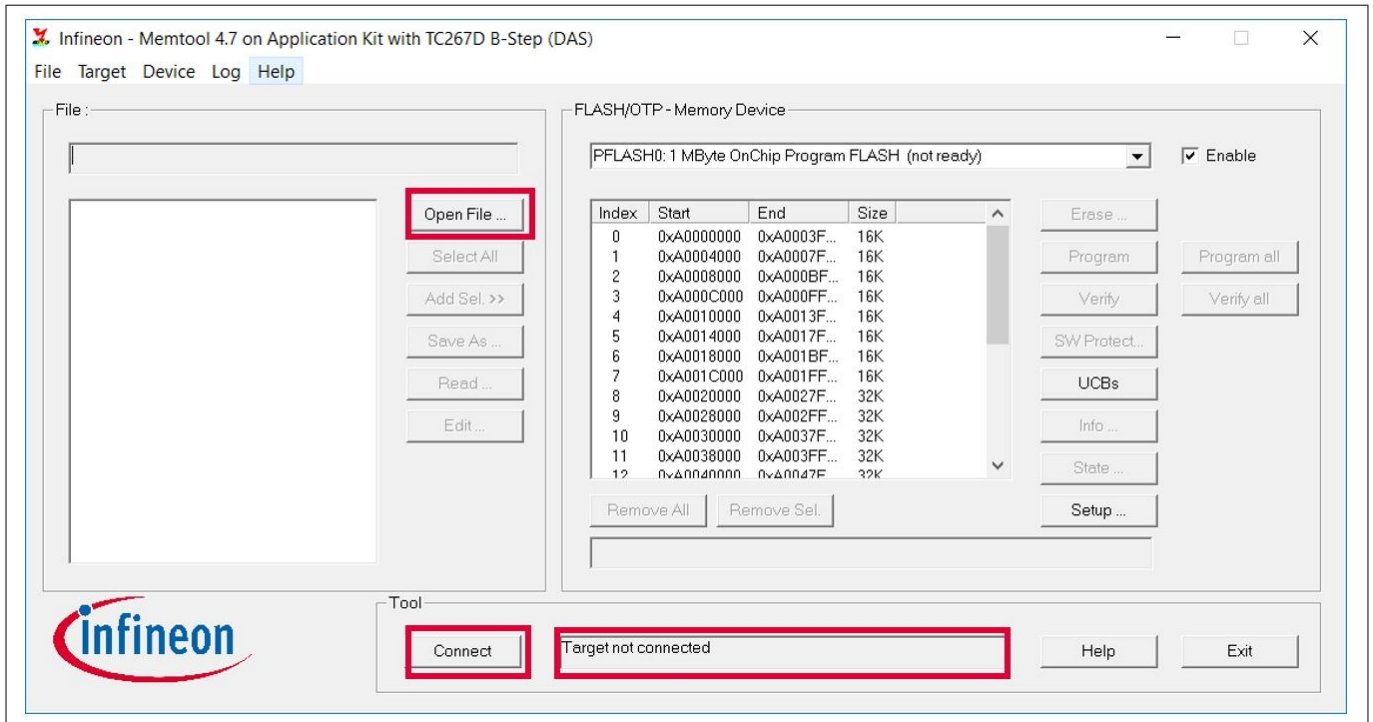


Figure 12 MemTool

Select the *.hex file “Infineon_TLE9015DQU_TLE9012DQU_TC265.hex” stored on MyICP. Click “Select All” and afterwards “Add Sel”. To flash the AURIX™, select “Program all”. Once successful, you can see the message shown in figure [Execute MemTool command](#).

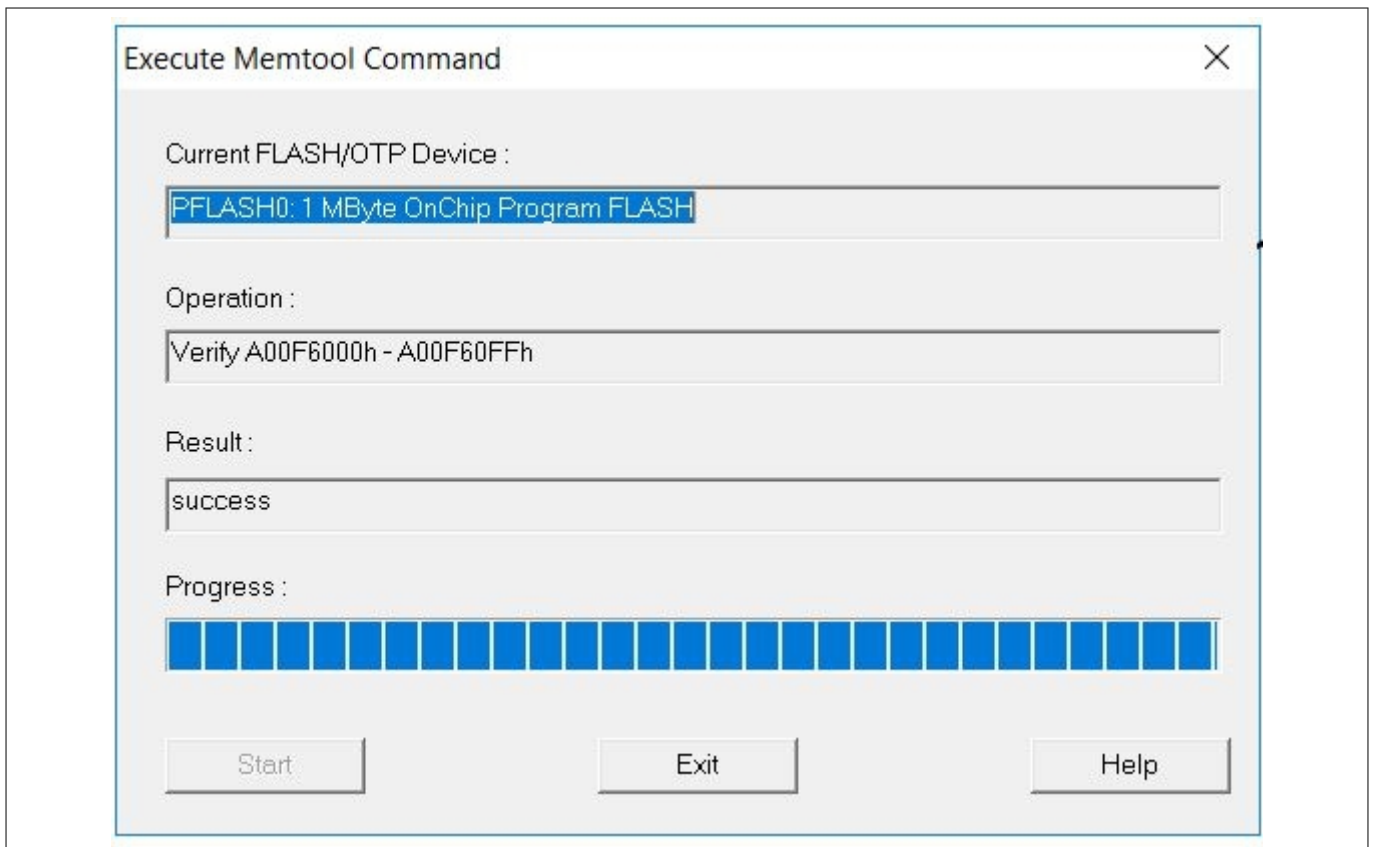


Figure 13 Execute MemTool command

1 Demo kit

Note: For further details or support on how to flash the AURIX™ TFT kit, please refer to <https://www.infineon.com/aurix>

1.1.4.4 Terminal

A terminal program (e.g. TeraTerm) can be used to communicate with the BMS IC. The configuration of the serial port is shown in figure [Serial port setup](#).

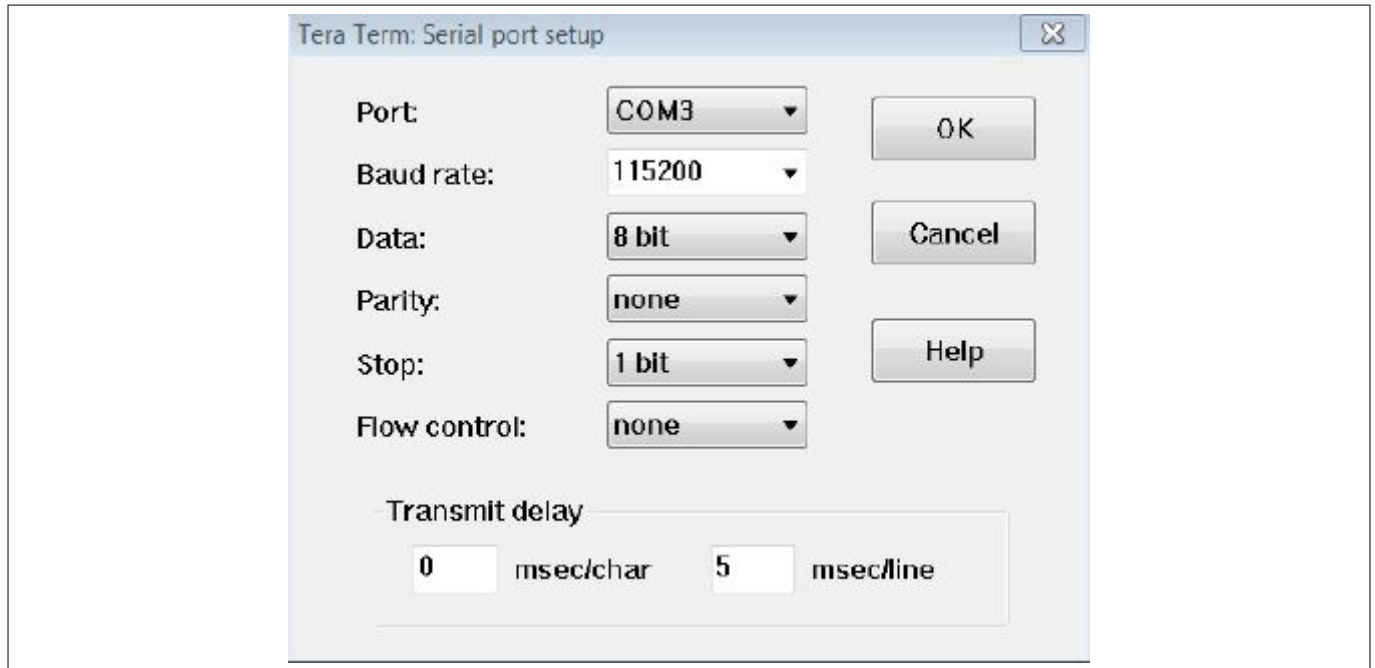


Figure 14 Serial port setup

After successful configuration, a user manual is available by sending “?”.

1 Demo kit

```

COM7 - Tera Term VT
File Edit Setup Control Window Help
?
TLE9012 Sensing IC evaluation(Uer v3.0)
=====
CS) Change UART communication speed eg CS 1000000 -->UART badurate change to 1Mb
ps
CU) CU 2 -->B11 ; CU 1-->A11
IL) Power up transceiver and wakeup from low side
IH) Power up transceiver and wakeup from high side
D) Power down transceiver and sensing IC and disable IBCB Communication
SN) Set number of slaves for broadcast read command E.g. SN 3 will set 3 slaves
in the chain
K) Set kicking time for watchdog (ms). E.g K 10
ERRQR) Reset Transceiver error E.g ERRQR 0, set Low. After error reset,remember
to set ERRQR to high
nsleep) Put Transceiver to sleep E.g nsleep 0, set Low
error) report transceiver error pins status
RL) single register read data from low side
RH) single register read data from high side
    RL ID ADD E.g. RL 1 e ==> Read device 1 address e
WL) single register write data from low side
WH) single register write data from high side
    WL ID AA DDDD E.g. WL 0 e 0201 ==> Write data to device 0 of address E
BRL) Broadcast read command from low side
BRH) Broadcast read command from high side
    BRL 0 ADD E.g. BRL 0 e ==> Read all devices at address from low side
BWL) Broadcast write command from low side
BWH) Broadcast write command from high side
    BWL 0 ADD DDDD E.g. BWL 0 2e 1234==> write data 1234 into all devices at ad
dress 2E from low side
    
```

Figure 15 TeraTerm user manual

There is the possibility to load a script into the terminal, which will perform several lines of commands. Drag & drop can be used to load the script in the terminal. A script, which reads out all the cell voltage is provided on MyICP “TC265TFT_BMS_init_CVM_1_Slave_Terminal.txt”.

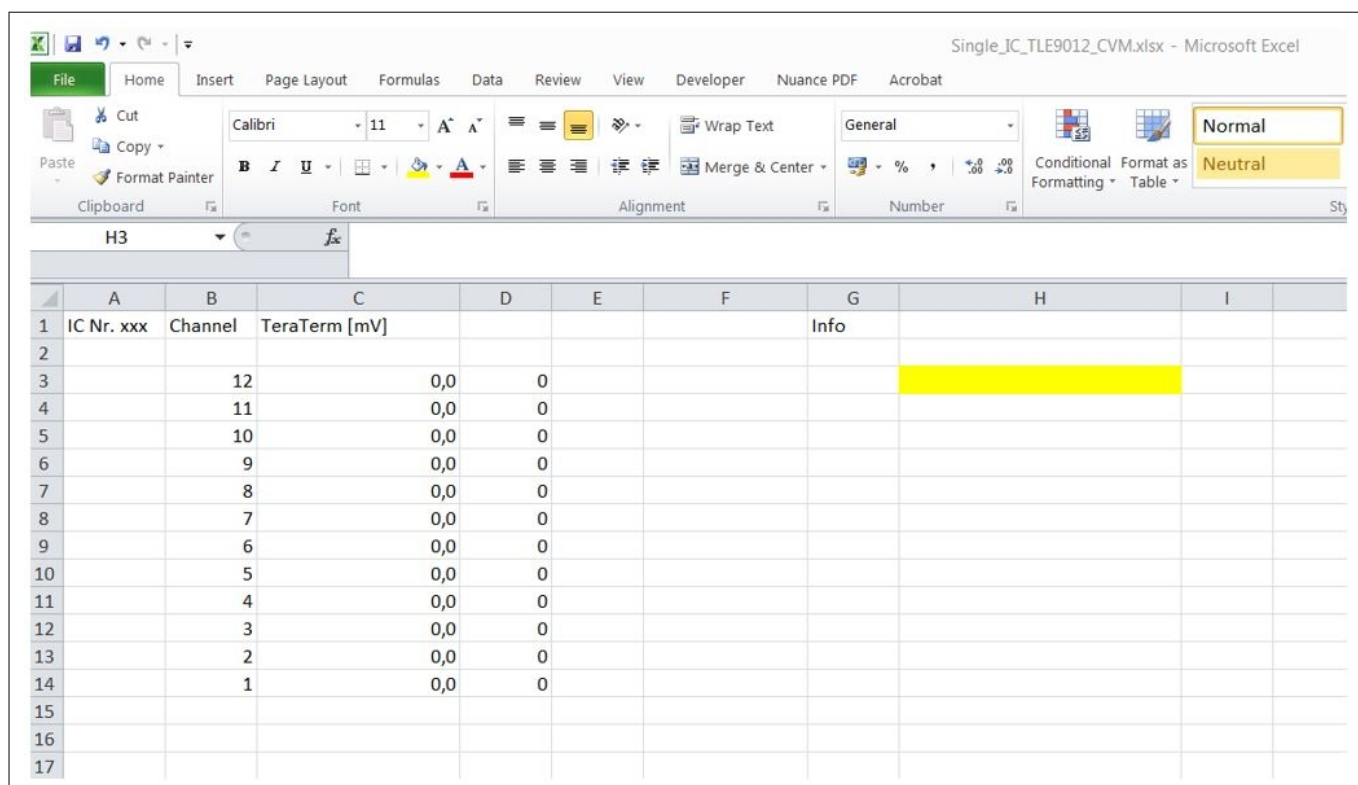
```

IL
IL OK
K 500
Watchdog kicking time change to 500 ms
WL 0 36 0001
WL 0 36 00000b OK 0002
WL 1 1 0FFf
WL 1 01 00000b OK 0002
WL 1 b 0000
WL 1 0b 000000 OK 0000
WL 1 b
RL 1 0b 000002 OK 0000
WL 1 18 ee21
WL 1 18 000000 OK 0000
WL 1 24
RL 1 24 0055a7 OK 0000
WL 1 23
RL 1 23 0055b2 OK 0000
WL 1 22
RL 1 22 005586 OK 0000
WL 1 21
RL 1 21 0055a7 OK 0000
WL 1 20
RL 1 20 005594 OK 0000
WL 1 1f
RL 1 1f 0055ad OK 0000
WL 1 1e
RL 1 1e 00559c OK 0000
WL 1 1d
RL 1 1d 00558b OK 0000
WL 1 1c
RL 1 1c 005593 OK 0000
WL 1 1b
RL 1 1b 0055b6 OK 0000
WL 1 1a
RL 1 1a 0055ab OK 0000
WL 1 19
RL 1 19 0055a0 OK 0000
    
```

Figure 16 Terminal script to read out all PCVMs

The result registers can be copied into an Excel sheet to calculate the cell voltages (in mV) out of the hex register values. Therefore, the lines shown in figure [Terminal script to read out all PCVMs](#) need to be marked and copied by selecting “Edit” → “Copy table”. Based on the “TC265TFT_BMS_init_PCVM_1_Slave_Terminal.txt” file is an Excel sheet at the Infineon BMS MyICP available to convert the received register results to cell voltages in mV. The Excel sheet is shown in figure [TLE9012DQU_CVM.xlsx Excel sheet to calculate the cell voltages in mV](#). The copied data has to be pasted at the indicated cell H3.

1 Demo kit



	A	B	C	D	E	F	G	H	I
1	IC Nr. xxx	Channel	TeraTerm [mV]				Info		
2									
3		12	0,0	0					
4		11	0,0	0					
5		10	0,0	0					
6		9	0,0	0					
7		8	0,0	0					
8		7	0,0	0					
9		6	0,0	0					
10		5	0,0	0					
11		4	0,0	0					
12		3	0,0	0					
13		2	0,0	0					
14		1	0,0	0					
15									
16									
17									

Figure 17 TLE9012DQU_CVM.xlsx Excel sheet to calculate the cell voltages in mV

2 Hardware guideline

2 Hardware guideline

2.1 Application schematic of one Cell Supervision Circuit (CSC)

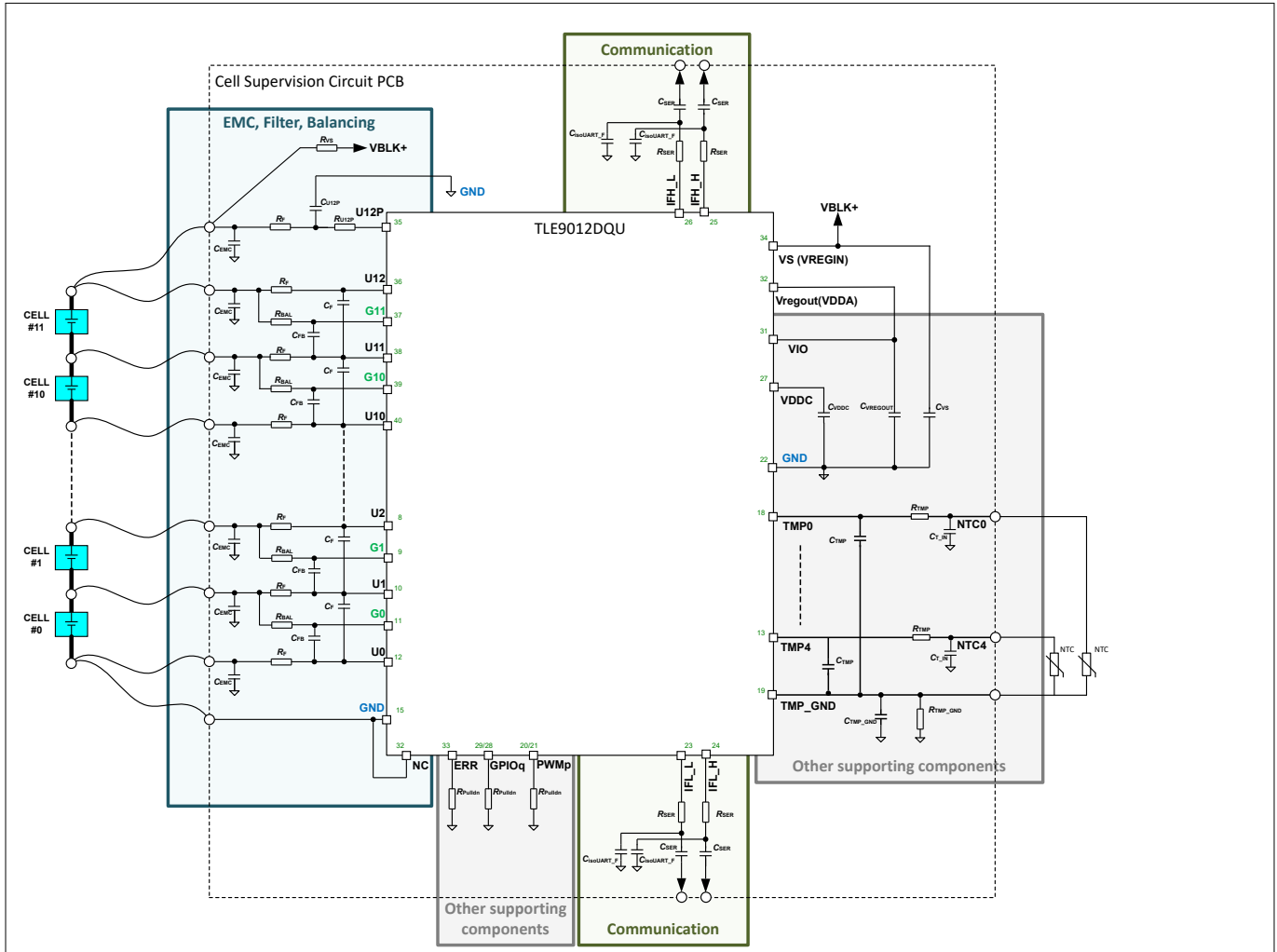


Figure 18 Schematic of one CSC

2.1.1 BOM - EMC, filter and balancing circuit

Table 1 BOM - EMC, filter and balancing circuit

Name	Symbol	Min.	Typ.	Max.	Unit	Status as is on evaluation board			Possible optimization	Layout hints and general comments
						Package	Characteristics	Value		
(table continues...)										

2 Hardware guideline

Table 1 (continued) BOM - EMC, filter and balancing circuit

Filter capacitor or U_{n+1}/U_n	C_F	50	330	1000	nF	SM0603	16 V, open mode principal preferred	330 nF	Other voltage rating e.g. 10 V also possible and can be reduced to e.g. 0402.	Should be placed as close as possible to the Un pins, especially important for C_F between U11 and U12 (see Layout guideline)
Filter capacitor or G_n/U_n	C_{FB}	11	100	500	nF	SM0402	50 V, open mode principal preferred	100 nF	Other voltage rating e.g. 10 V also possible.	Please adjust this capacitor value accordingly if you want to change the balancing resistor value to keep τ constant.
Filter resistor U_n	R_F	3	10	62	Ω	SM1206	Anti surge	10 Ω	Can be reduced to e.g. 0805. Please take maximum peak currents during hot plug events into account when choosing resistor package and type.	ADC input impedance during measurement conversion is typically 200 k Ω . This value can be used to calculate the voltage drop over that resistor during measurement conversion.
Filter resistor U12P	R_{U12P}	4.5	5.1	5.6	Ω	SM1206	Anti surge	5.1 Ω	Can be reduced to e.g. 0805. Please take maximum peak currents during hot plug event in account when choosing resistor package and type.	-
Buffer capacitor or U12P	C_{U12P}	50	100	130	nF	SM0603	100 V, open mode principal preferred	100 nF	-	-

(table continues...)

2 Hardware guideline

Table 1 (continued) BOM - EMC, filter and balancing circuit

EMC network capacitor	C_{EMC}	0	1	5	nF	SM0805	100 V, open mode principal preferred	1 nF	Can be reduced to e.g. 0603	This component is optional but it can improve the EMC robustness. It depends on the system setup including PCB layout, BCI injection point etc. whether the component is needed. The component should be placed close to the connector of the sensing wire.
Balancing resistor	R_{BAL}	18	41	200	Ω	SM1206	-	41 Ω	Resistor value in parallel setup is made for max. ~100 mA balancing current. Can be optimized based on balancing current requirement.	-
Filter resistor VS	R_{VS}	4.5	33	100	Ω	SM1206	Anti surge	5.1 Ω	Can be reduced to e.g. 0805. Please take maximum peak currents during hot plug event into account when choosing resistor package and type.	-

2.1.2 BOM - communication circuit between Cell Supervision Circuits

Table 2 BOM - communication circuit between Cell Supervision Circuits

Name	Symbol	Min.	Typ.	Max.	Unit	Status as is on evaluation board			Possible optimization	Layout hints and general comments
						Package	Characteristics	Value		
(table continues...)										

2 Hardware guideline

Table 2 (continued) BOM - communication circuit between Cell Supervision Circuits

HF noise bypass capacitor or ISO UART	$C_{isoUART_F}$	0	220	286	pF	SM0603	50 V	220 pF	Can be reduced to e.g. 10 V and different package e.g. 0402.	Optional, especially in combination with a transformer. The $C_{isoUART_F}$ should be placed close to C_{EMC} (if used) and the common GND path should be as short as possible.
ISO UART series resistor	R_{SER}	37.05	39	40.95	Ω	SM0805	–	39 Ω	–	Should be placed close to the IC.
ISO UART series capacitor	C_{SER}	0.95	1	1.05	nF	SM1206	630 V	1 nF	Can be reduced to e.g. 0805. It depends on the battery system requirement whether a ≥ 500 V voltage rating is needed. With no additional battery system requirement 100 V is sufficient.	Symmetric routing of communication lines improves the EMC robustness. For an improved EMC robustness we propose C0G capacitors with $\pm 5\%$ tolerance.

2.1.3 BOM - other supporting components for Cell Supervision Circuits

Table 3 BOM - other supporting components for Cell Supervision Circuit

Name	Symbol	Min.	Typ.	Max.	Unit	Status as is on evaluation board			Possible optimization	Layout hints and general comments
						Package	Characteristics	Value		
(table continues...)										

2 Hardware guideline

Table 3 (continued) BOM - other supporting components for Cell Supervision Circuit

Buffer capacitor VS	C_{VS}	50	100	130	nF	SM0603	100 V	100 nF	–	Should be placed as close as possible to the VS pin.
Buffer capacitor VDDC	C_{VDDC}	165	330	430	nF	SM0603	16 V	330 nF	Can be reduced to e.g. 10 V and can be reduced to e.g. 0402.	Should be placed as close as possible to the VDDC pin.
Buffer capacitor VREGOUT	$C_{VREGOUT}$	50	100	130	nF	SM0402	50 V	100 nF	Can be reduced to e.g. 10 V.	Should be placed as close as possible to the VREGOUT pin.
NTC filter capacitor	C_{T_IN}	0	4.7	13	nF	SM0603	50 V	4.7 nF	Can be reduced to e.g. 10 V and can be reduced to e.g. 0402.	Should be placed as close as possible to the NTC connector pins.
Temperature capacitor TMP_GND	C_{TMP_GND}	–	10	–	nF	SM0603	50 V	10 nF	Can be reduced to e.g. 10 V and can be reduced to e.g. 0402.	Should be placed as close as possible to the TMP_GND pin.
Temperature resistor TMP_GND	R_{TMP_GND}	–	100	–	Ω	SM0603	–	100 Ω	Can be reduced to e.g. 0402.	–
NTC filter resistor	R_{TMP}	0	100	1000	Ω	SM1206	–	100 Ω	Optional temperature filter resistor. Can be reduced to e.g. 0402.	–
Input capacitor TMP	C_{TMP}	0	10	13	nF	SM0603	50 V	10 nF	Optional temperature filter capacitor. Can be reduced to e.g. 0402, 10 V.	Should be placed as close as possible to the TMPx pins.
Pull down resistor	R_{PullDn}	–	33	–	k Ω	–	–	–	–	–

2 Hardware guideline

2.1.4 BOM - iso UART termination network

For power-balanced communication, a termination network is required for the last node in the daisy chain. The figure below shows the termination network. The termination network is not required for proper functionality of the device.

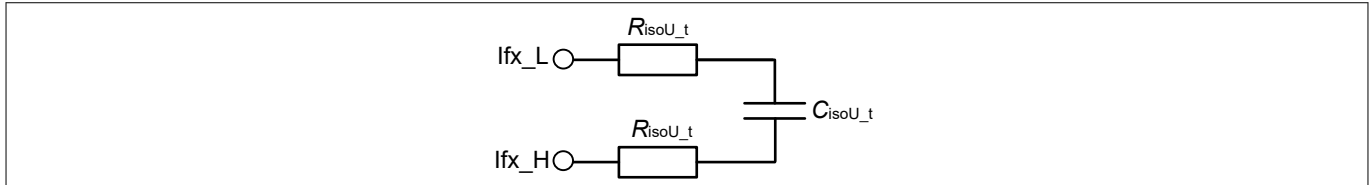


Figure 19 iso UART termination network

Table 4 BOM - iso UART termination network

Name	Symbol	Min.	Typ.	Max.	Unit	Status as is on evaluation board			Possible optimization	Layout hints and general comments
						Package	Characteristics	Value		
Termination resistor	R_{isoU_t}	-	100	-	Ω	-	-	-	-	-
Termination capacitor	C_{isoU_t}	-	250	-	pF	-	-	-	-	-

2.1.5 Layout guideline

The filter capacitors C_F should be placed as close as possible to the IC pins. This is especially important for channel #11 to enable an accurate voltage measurement. The figure below shows an example where the filter capacitor should be placed next to the IC pins (U11, U12).

2 Hardware guideline

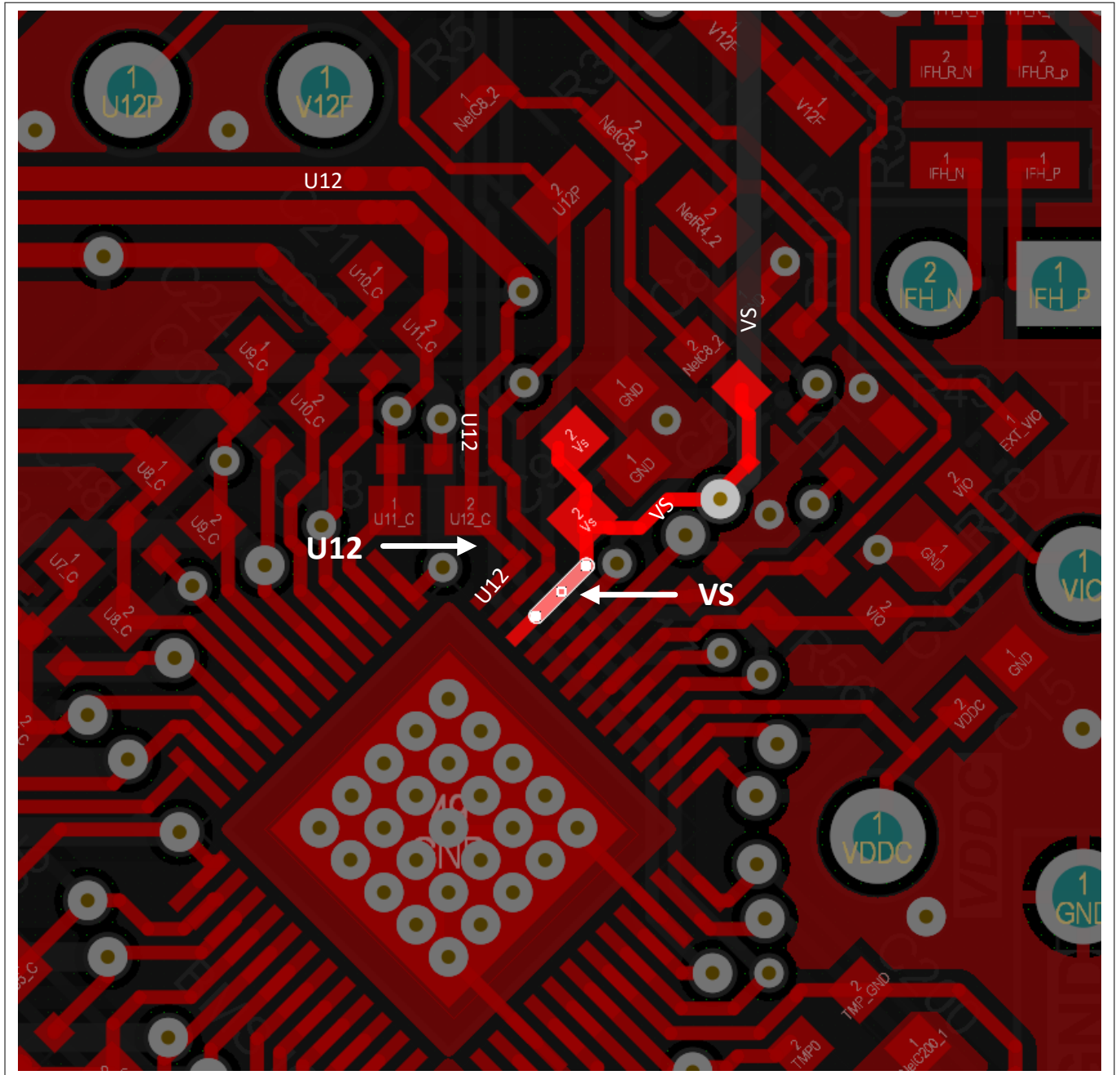


Figure 21 Routing VS and U12P

2.1.6 Guidance for unused pins

Note: The n.c. pin 32 shall be connected to GND.

2.1.6.1 Unused input pins

All unused input pins should be connected to GND:

- TMP0, TMP1, TMP2, TMP3, TMP4: directly to GND
- PWM1, PWM0: 33 kΩ to GND (package size e.g. 0603), resistor can be shared.
- GPIO0/UART_LS, GPIO1/UART_HS: 33 kΩ to GND (package size e.g. 0603), resistor from PWM0, PWM1 can be shared.

2 Hardware guideline

2.1.6.2 Unused output pins

All unused output pins should remain open.

- ERR

2.1.7 Use of CSC with less than 12 cells

Unused channels shall be connected to the negative potential of the lowest used cell. The connection can be made either directly at the pin or at the connector.

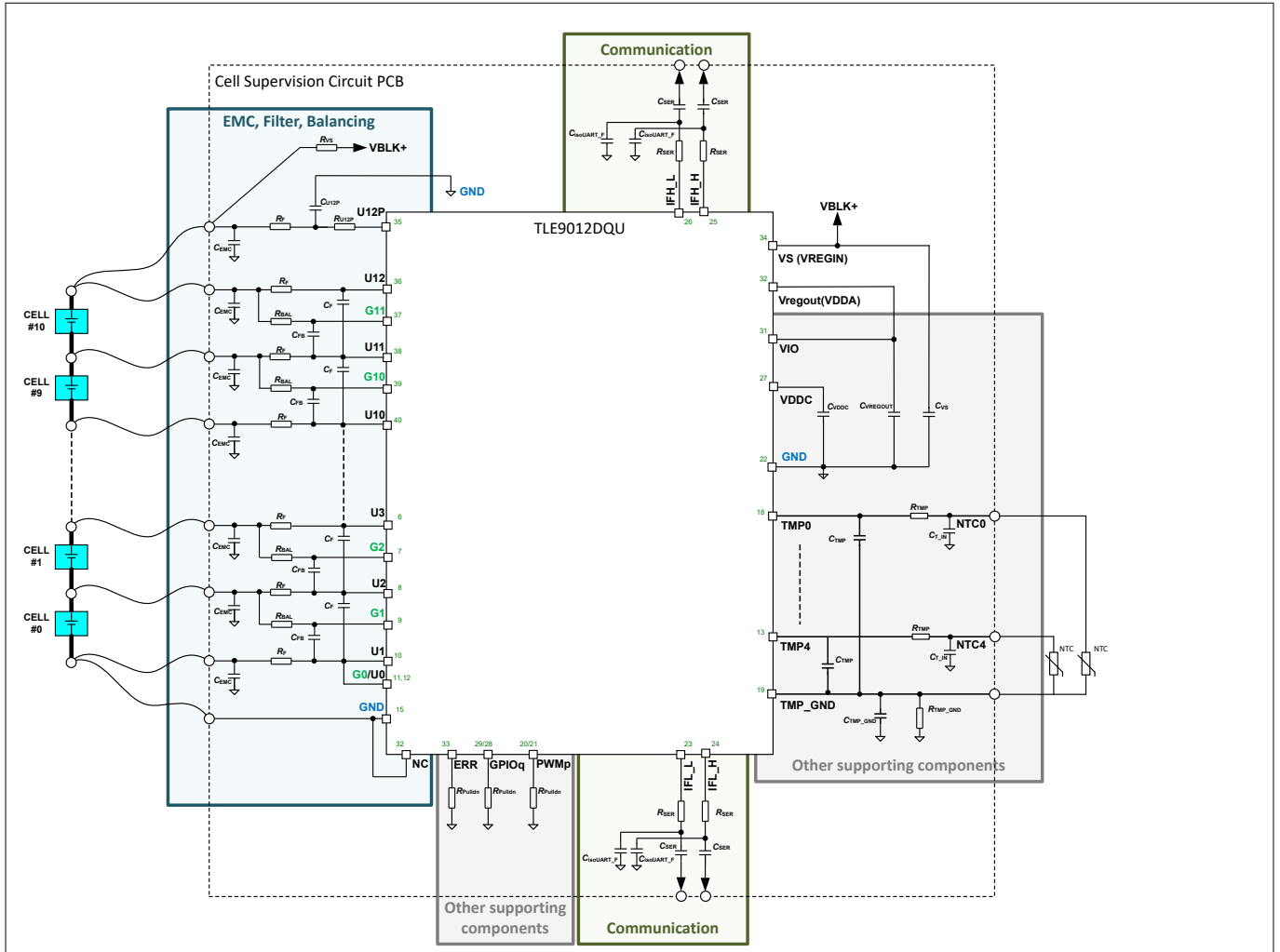


Figure 22 TLE9012DQU (12 channel) CSC connected to 11 cells (pin)

2 Hardware guideline

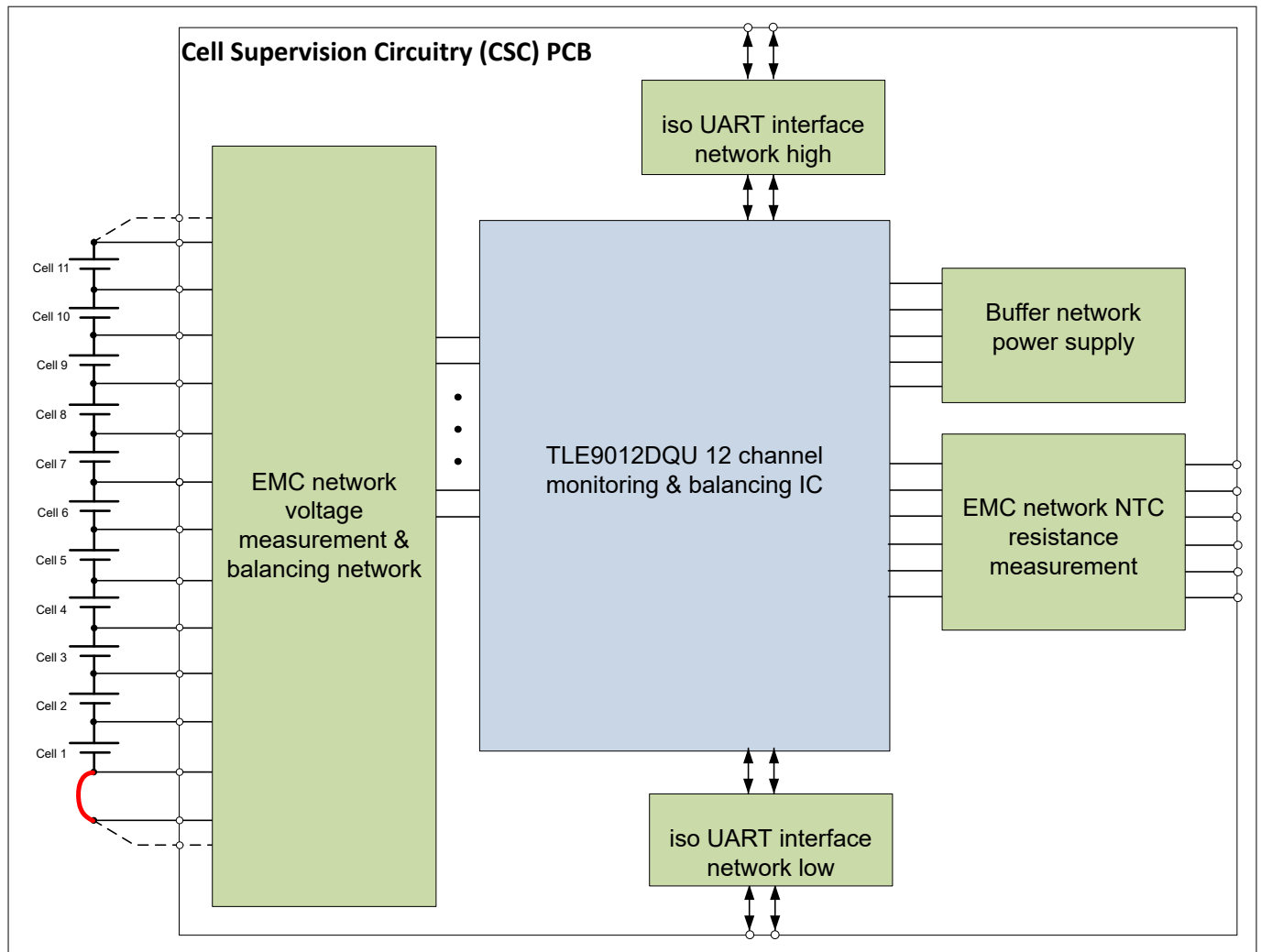


Figure 23 TLE9012DQU (12 channel) CSC connected to 11 cells (connector)

2 Hardware guideline

2.2 Application schematic transceiver circuit

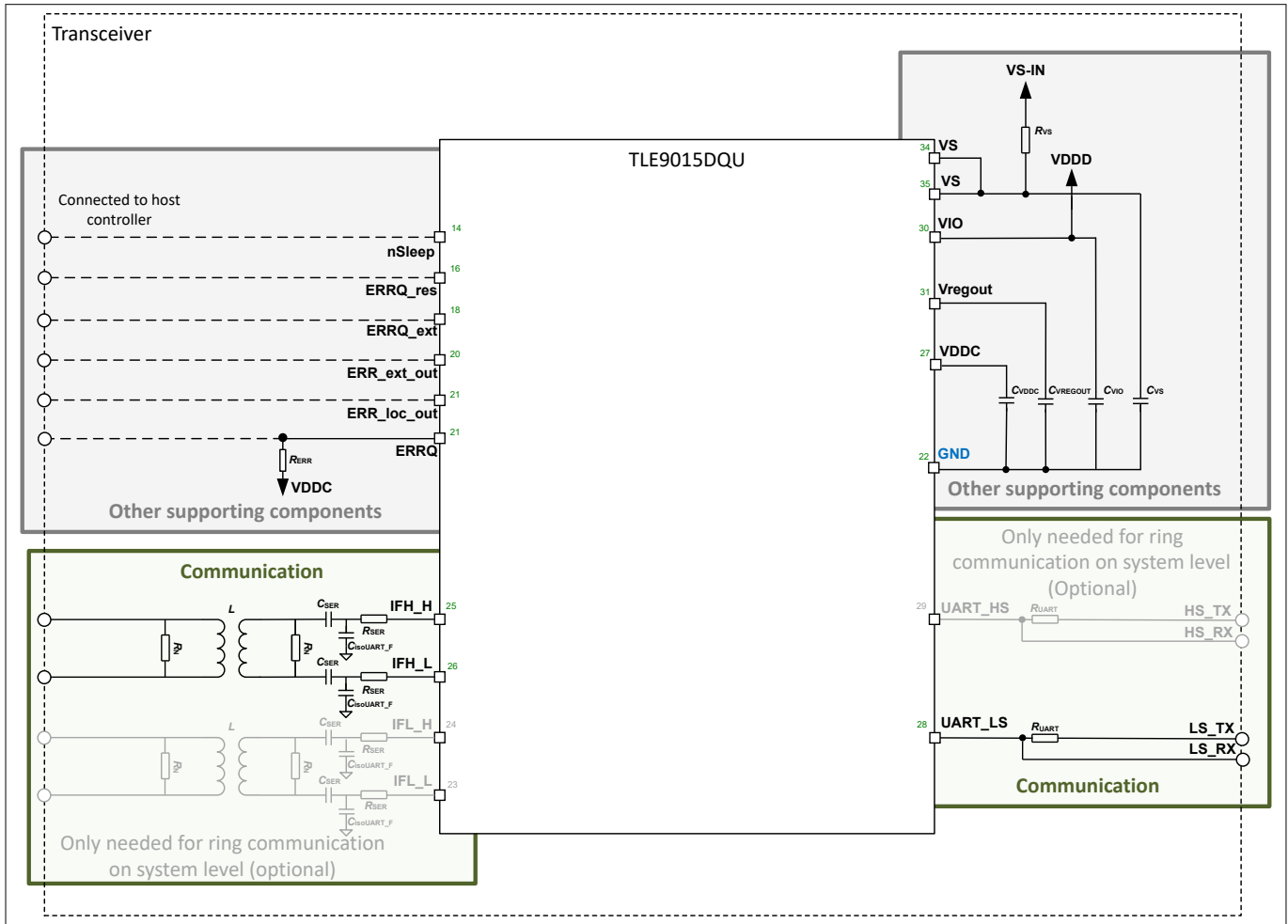


Figure 24 Schematic of the transceiver TLE9015DQU

2.2.1 BOM - communication circuit

Table 5 BOM - communication circuit

Name	Symbol	Min.	Typ	Max	Unit	Status as is on evaluation board			Possible optimization	Layout hints and general comments
						Package	Characteristics	Value		
iso UART series resistor	R_{SER}	37.5	39	40.95	Ω	SM0805	-	39 Ω	-	-

(table continues...)

2 Hardware guideline

Table 5 (continued) BOM - communication circuit

iso UART series capacitor	C_{SER}	0.95	1	1.05	nF	SM1206	500 V	1 nF	100 V can be used because the transformer takes over the galvanic isolation and a 0805 package can be used.	-
HF noise bypass capacitor iso UART	$C_{isoUART_F}$	0	220	286	pF	SM0603	50 V	220 pF	Can be reduced to e.g. 10 V and different package e.g. 0402.	Optional, especially in combination with a transformer. The $C_{isoUART_F}$ should be placed close to C_{EMC} (if used) and the common GND path should be as short as possible.
Damping resistor	R_N	-	-	-	-	SM0805	-	240 Ω	-	Depends on used transformer e.g. 1 k Ω with Pulse HM2116ANL transformer.
Transformer	L	-	-	-	-	Available footprint for e.g. <ul style="list-style-type: none"> • Sumida CEP99P • Pulse HM2106ZNL • Pulse HM2116ANL 		-	-	
UART network	R_{UART}	0.82	1	5	k Ω	SM0805	-	1.5 k Ω	-	$\tau \leq 50$ ns

2.2.2 BOM - other supporting components

Table 6 BOM - other supporting components

Name	Symbol	Min.	Typ.	Max.	Unit	Status as is on evaluation board			Possible optimization	Layout hints and general comments
						Package	Characteristics	Value		
(table continues...)										

2 Hardware guideline

Table 6 (continued) BOM - other supporting components

Buffer capacitor VREGOUT	$C_{VREGOUT}$	50	100	130	nF	SM0402	50 V	100 nF	–	Should be placed as close as possible to the VREGOUT pin.
Buffer capacitor VDDC	C_{VDDC}	165	330	430	nF	SM0603	16 V	330 nF	Can be reduced to e.g. 10 V and can be reduced to e.g. 0402.	Should be placed as close as possible to the VDDC pin.
Buffer capacitor VIO	C_{VIO}	50	100	130	nF	SM0402	50 V	100 nF	Can be reduced to e.g. 10 V	Should be placed as close as possible to the VIO pin. If VIO is connected to VREGOUT, then C_{VIO} is omitted.
Buffer capacitor	C_{VS}	50	100	130	nF	SM0402	50 V	100 nF	–	Should be placed as close as possible to the VS pin.
Filtering resistor	R_{VS}	4.5	5.1	100	Ω	SM0603	–	5.1 Ω	–	–
Error output	R_{ERR}	–	1.5	–	k Ω	–	–	–	A 0402 package can be used.	–

2.3 CSC evaluation board

Physical dimensions: (6.1 x 6.0) cm

2 Hardware guideline

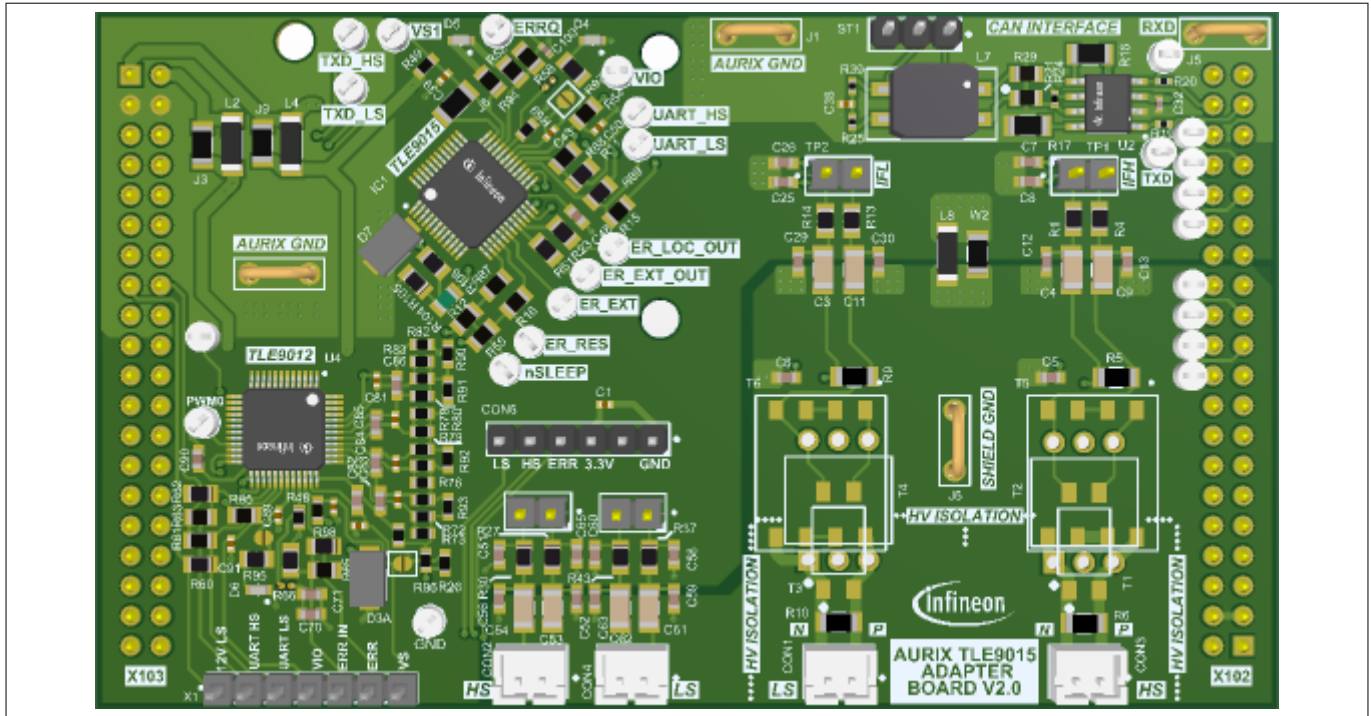


Figure 26 3D image of transceiver evaluation board

2.5 Typical chip performance

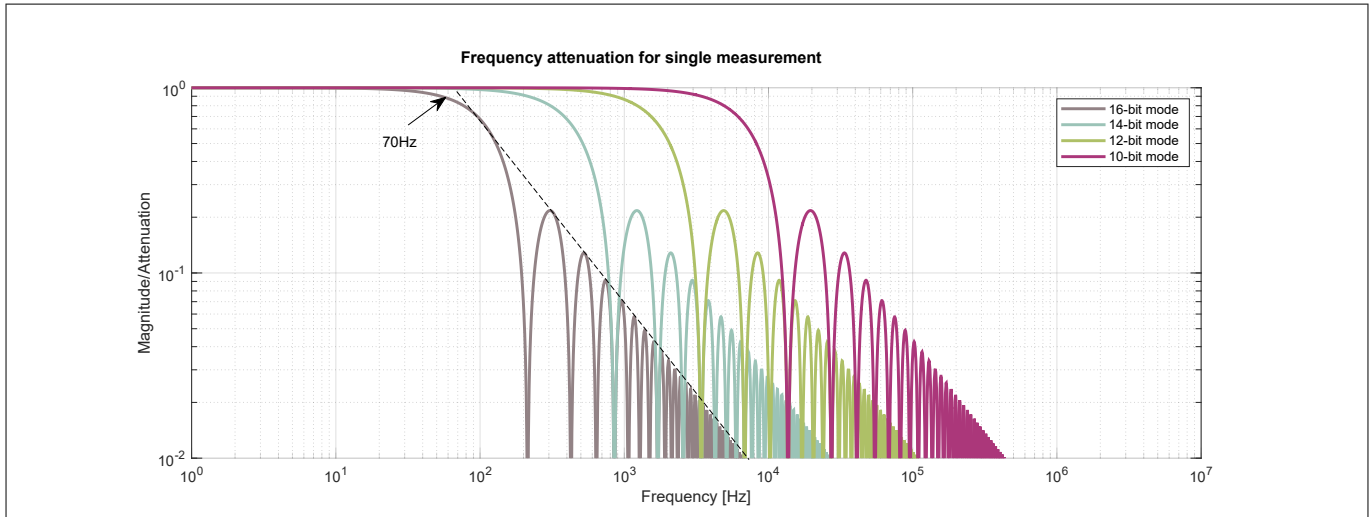


Figure 27 Digital noise filter response for 16-bit, 14-bit, 12-bit and 10-bit mode

2 Hardware guideline

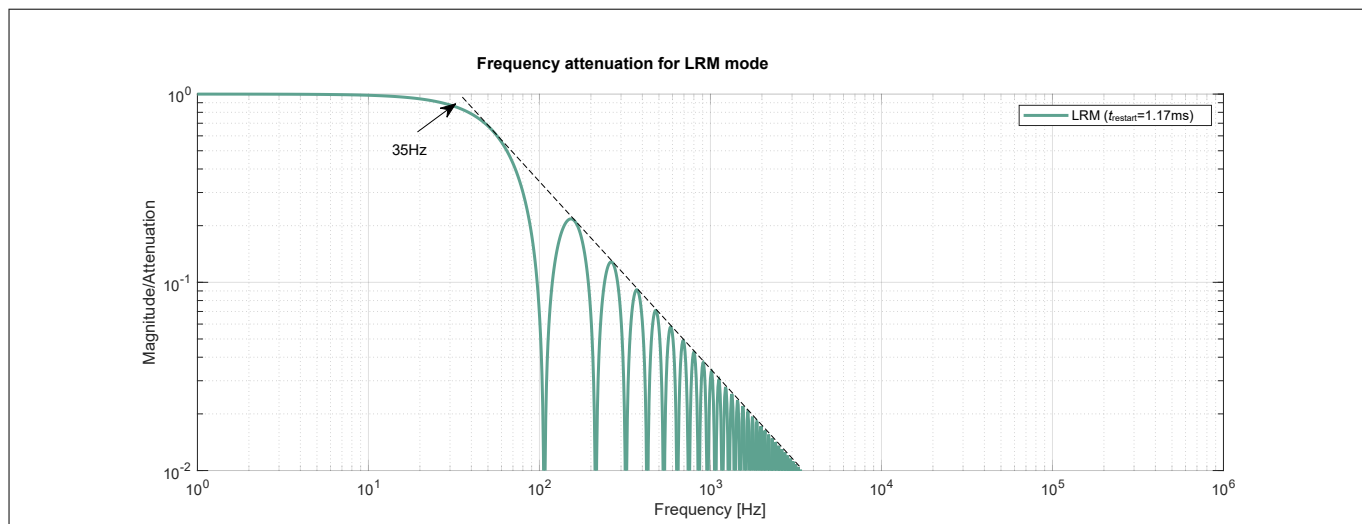


Figure 28 Digital noise filter response for long running mode ($t_{\text{restart}} = 1.17\text{ ms}$)

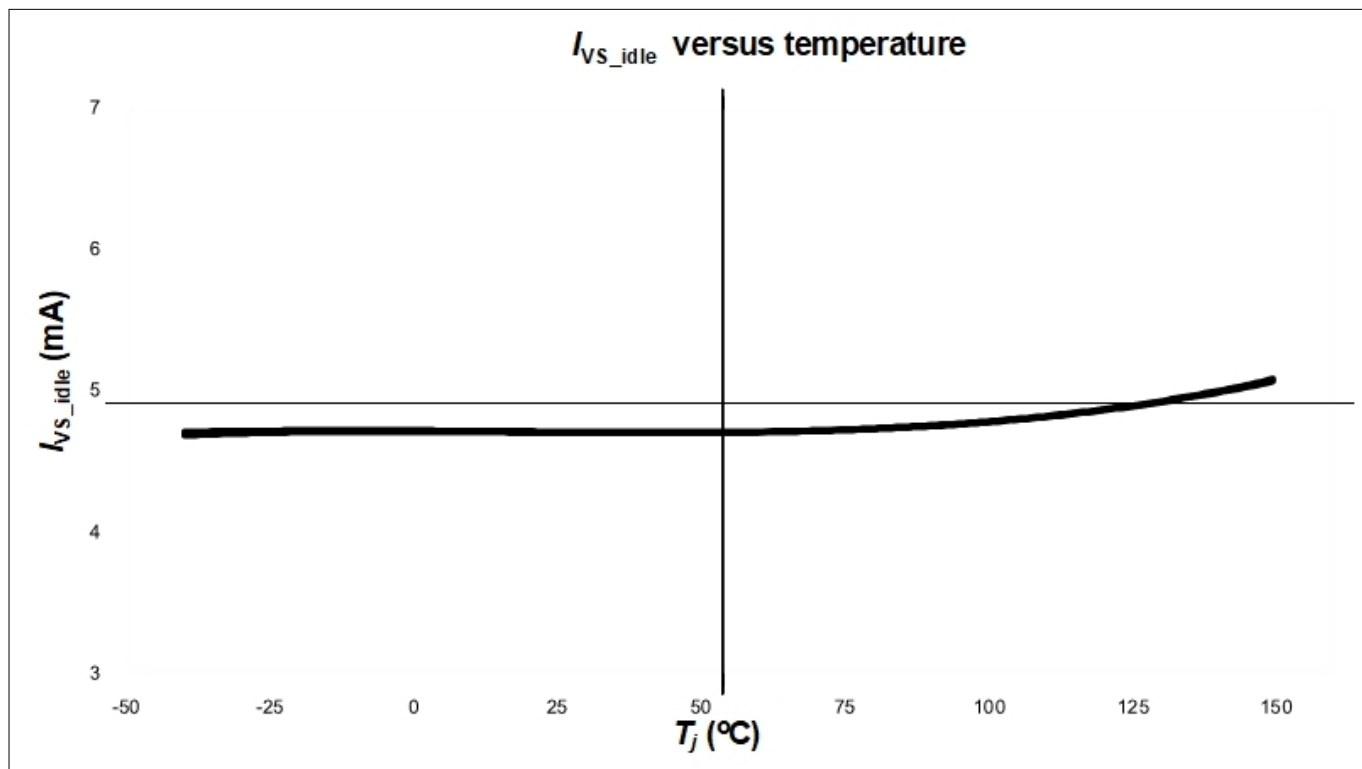


Figure 29 Typical VS idle current $I_{\text{VS_sleep}}$ versus temperature

2 Hardware guideline

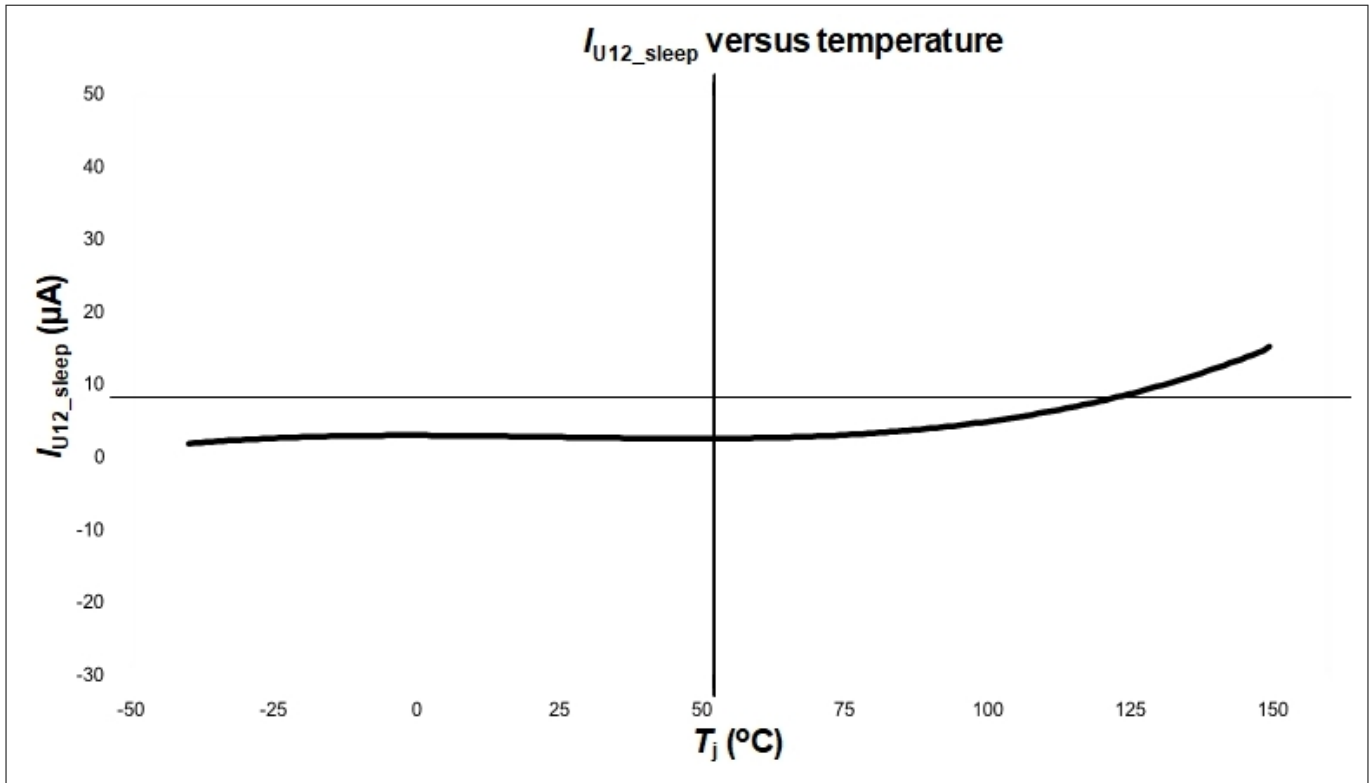


Figure 30 Typical U12P sleep mode current versus temperature

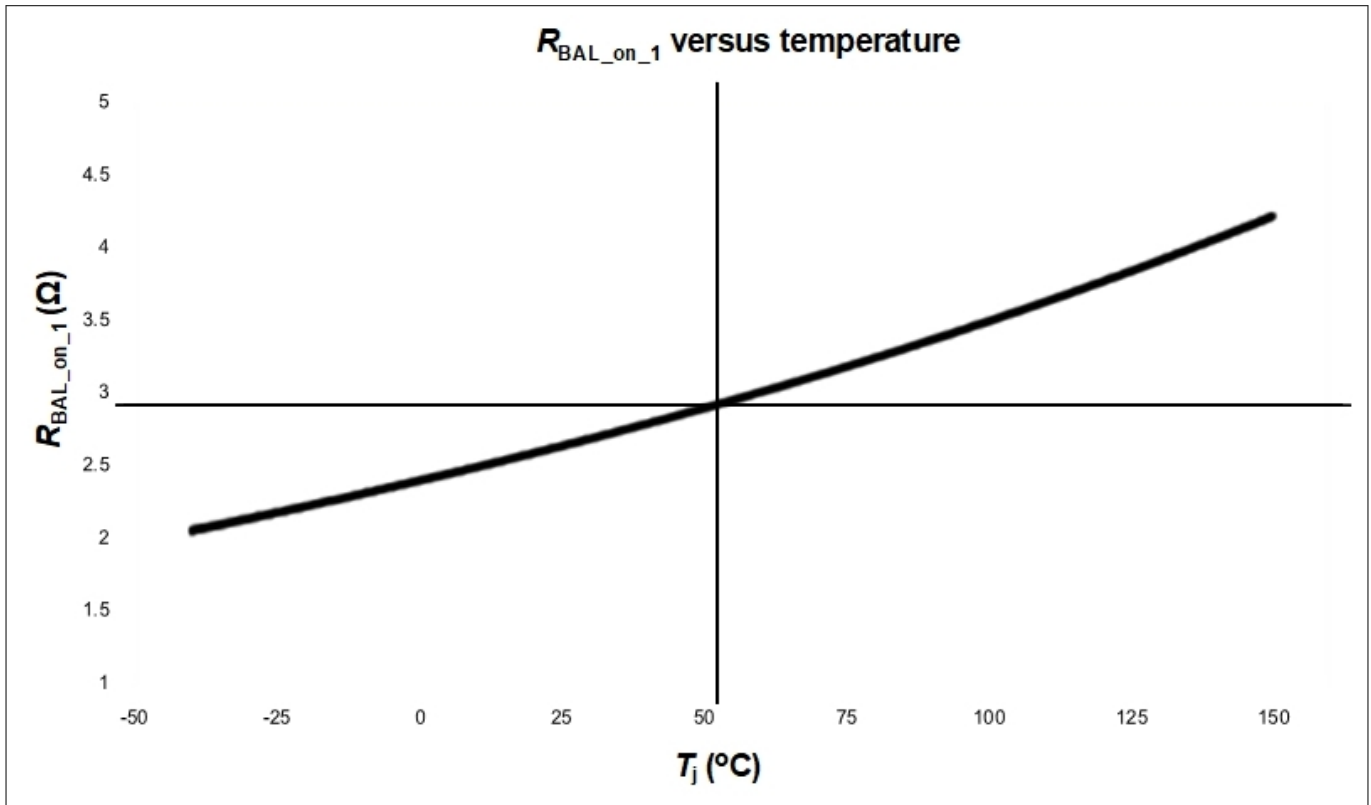


Figure 31 Typical CB balancing switch on-state resistance - 1 versus temperature

2 Hardware guideline

2.6 EEPROM

If an additional memory is required, an EEPROM can be connected to the TLE9012DQU. The two GPIO pins of the TLE9012DQU can be used for the communication with the memory. For this purpose, the GPIO pins are set and sampled accordingly in order to emulate I2C. Memory requirements:

- I2C interface
- Max. operating current: I_{VIO_comm}
- Supply voltage: $V_{VREGOUT}$
- The minimum clock frequency must be taken into account when choosing the memory. Since the emulation of I2C using bit banging is slow, the minimum clock frequency of the memory should be small.

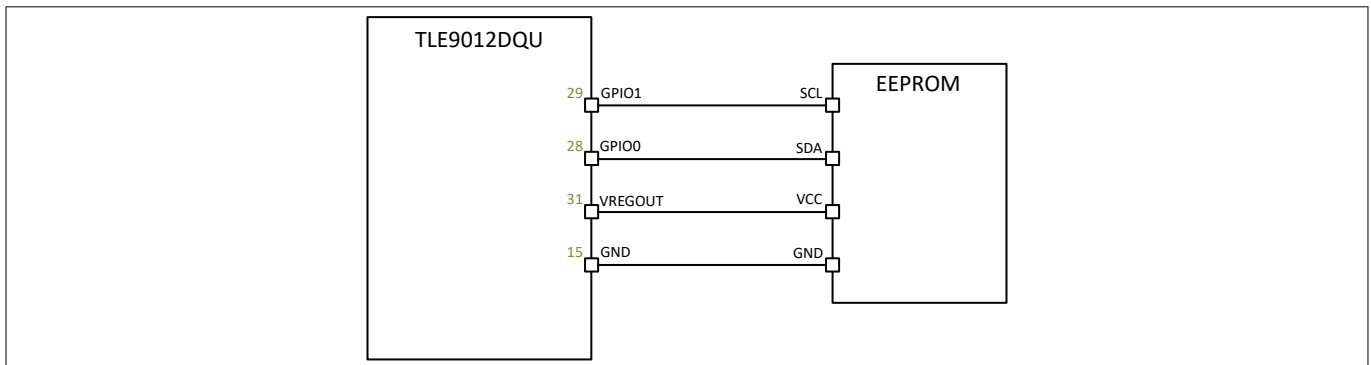


Figure 32 TLE9012DQU connected to EEPROM

Note: Instead of using the VREGOUT pin to supply the EEPROM, a third GPIO pin (e.g. PWM0) can be used to supply the memory. When the pin is set to HIGH, the memory is supplied. Otherwise the memory device is switched off. This is beneficial to reduce the supply current.

Depending on the EEPROM used, a defined bit sequence as well as the memory address and the data to be stored must be sent. An example sequence for a write is shown in the figure below.

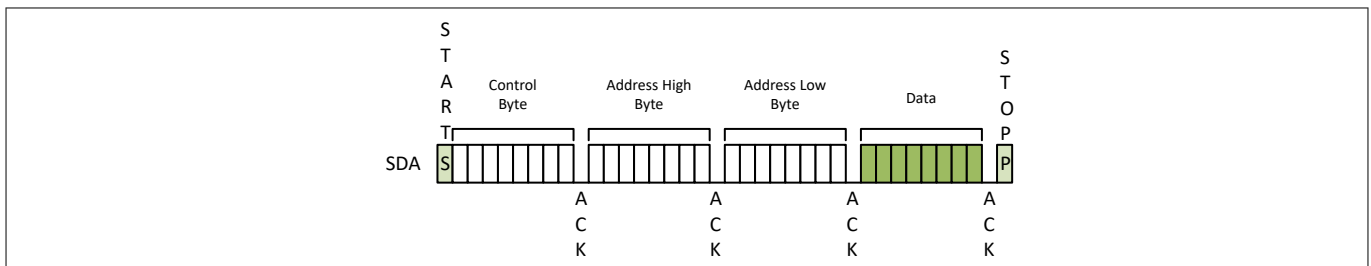


Figure 33 SDA sequence to write one byte

The control byte and the address bytes depend on the used memory. With the shown sequence, it takes ~ 15 ms to write one byte. The bit sequence to read one byte is similar to the write sequence. After the memory specific control byte and address bytes, the memory responds with the control byte and the requested data.

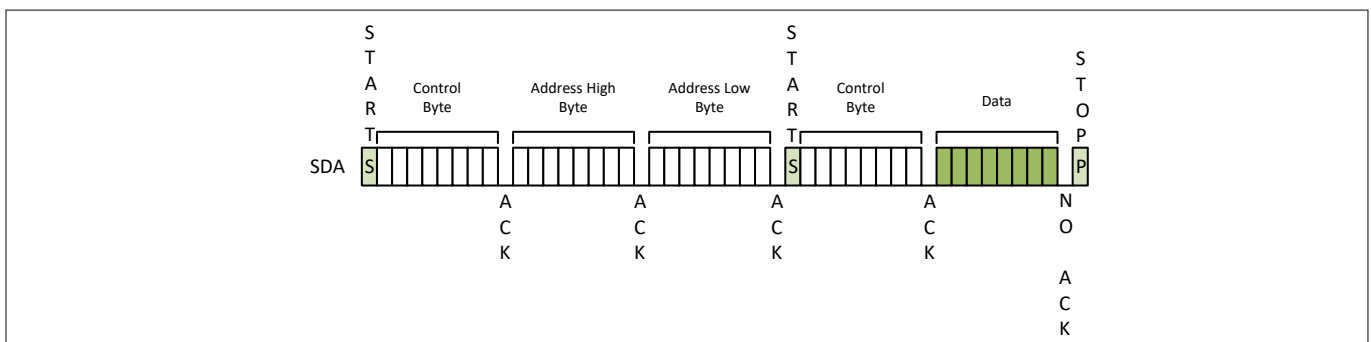


Figure 34 SDA sequence to read on byte

2 Hardware guideline

With the shown sequence, it takes ~ 18 ms to read one byte.

2.7 13-wire setup

The TLE9012DQU can be also used in a 13-wire setup (the 15-wire setup is shown in [Schematic of CSC](#)). In a 13-wire setup, supply and sensing current share one wire for the top and bottom cell. The 13-wire setup influences the PCVM accuracy of the top and bottom cell due to the additional voltage drop forced by the supply current over these wires. A real 15-wire setup (sensing and supply current have separate wires) is used as a reference measurement to have a reference setpoint for PCVM accuracy. For the required voltage stability (dynamic & static), real Li-Ion cells (LFP cells with $R_i < 10 \text{ m}\Omega$) are used. The intrinsic setup accuracy is 0.5 mV. The figure below shows the difference between the 13-wire and the 15-wire setup for the PCVM accuracy. The cable length from the Li-Ion cells to the BMS Demo Board is 20 cm (3 BMS Demo Board were tested).

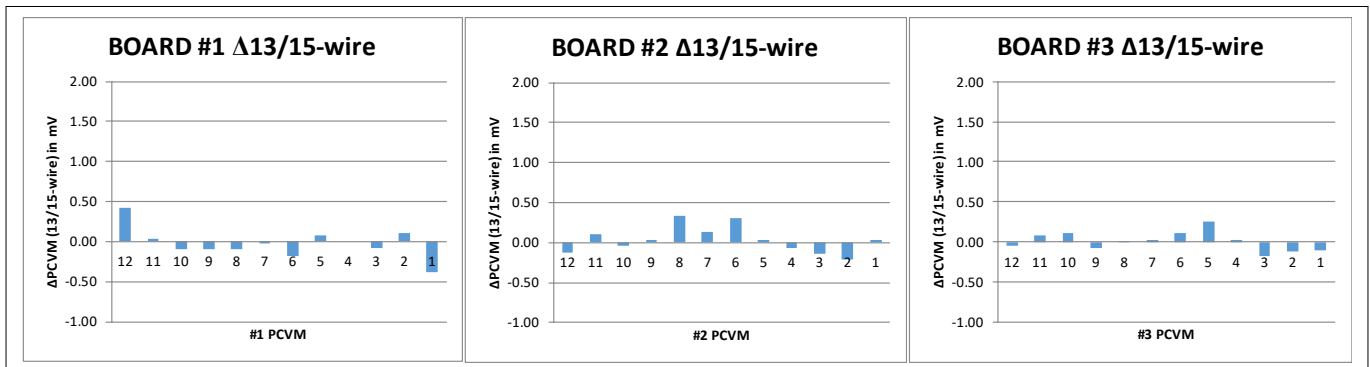


Figure 35 PCVM accuracy Δ 13/15-wire setup with 20 cm cable length

Due to the setup, the differences for a 13 and 15-wire setup are virtually negligible (difference in the range of setup accuracy). As the path from cell to Demo Board is very low ohmic, the supply current has virtually no influence.

The figure below shows the PCVM results for the Demo Board #2 with an increased cable length (cell-to-board) of 1.5 m.

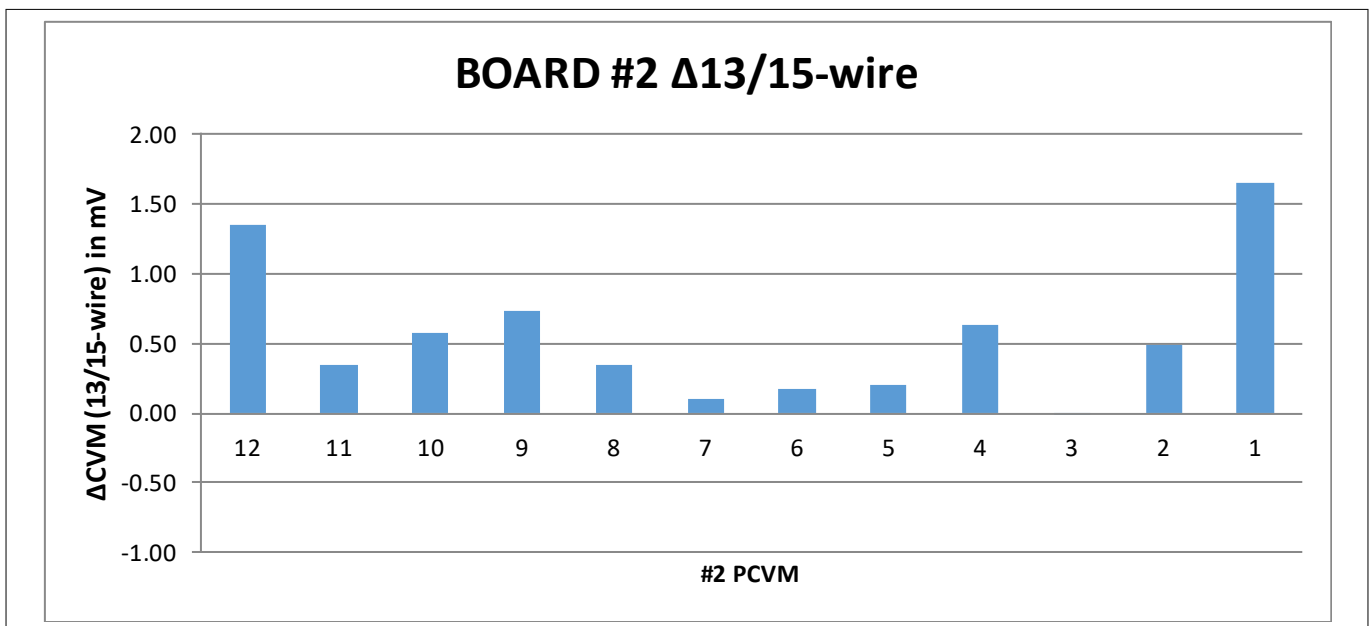


Figure 36 PCVM accuracy Δ 13/15-wire setup with 1.5 m cable length

The comparison of both figures is showing the corner channel effect clearly on channel 1 and channel 12. The effect due to the 13-wire setup (voltage drop over cable) is measurable and equal for the top and bottom channels. To which extent this effect can be observed depends on the setup (cable length, connectors, fuses, voltage stability of source, etc.) and needs to be verified in the real application (in a real car battery). If the

2 Hardware guideline

offset at the top and bottom cells in the real car battery is too large to accept, it could also be compensated at the microcontroller as the offset is fixed by system characteristics.

2.8 iso UART communication interface

2.8.1 Introduction

The iso UART protocol is based on a two wire, differential, half duplex physical layer, which the ICs use to communicate between slaves. A more detailed description can be found in the device datasheet. The following section discusses the datasheet specs and how to interpret the iso UART waveforms at different points on the iso UART circuitry for robust communication between the slaves.

2.8.2 Physical layer overview

The datasheet specification states the threshold levels for the iso UART analog receiver interface to convert the analog signals of the physical layer to useful digital signals for the bus timing protocol:

- iso UART current threshold "high" $I_{isoU_th_high}$ indicates the positive edge level to trigger a digital "1" signal.
- iso UART current threshold "low" $I_{isoU_th_low}$ indicates the negative edge level to trigger a digital "0" signal.

The figure below shows how the iso UART interfaces are configured in the Primary on Bottom (PoB) topology. In this topology, the low side interface is configured as receiver mode (RX) which receives the iso UART physical signals and translates them to digital signals for further interpretation. The high side interface is then configured to transmitter mode (TX) which drives the digital signal on the physical link.

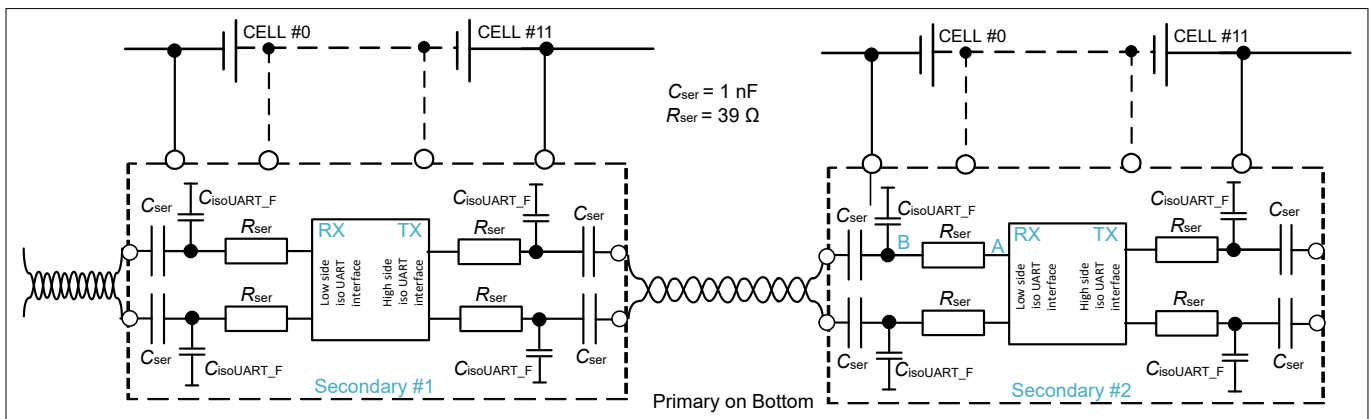


Figure 37 Primary on Bottom communication

The physical and digital signals are illustrated as an example below.

2 Hardware guideline

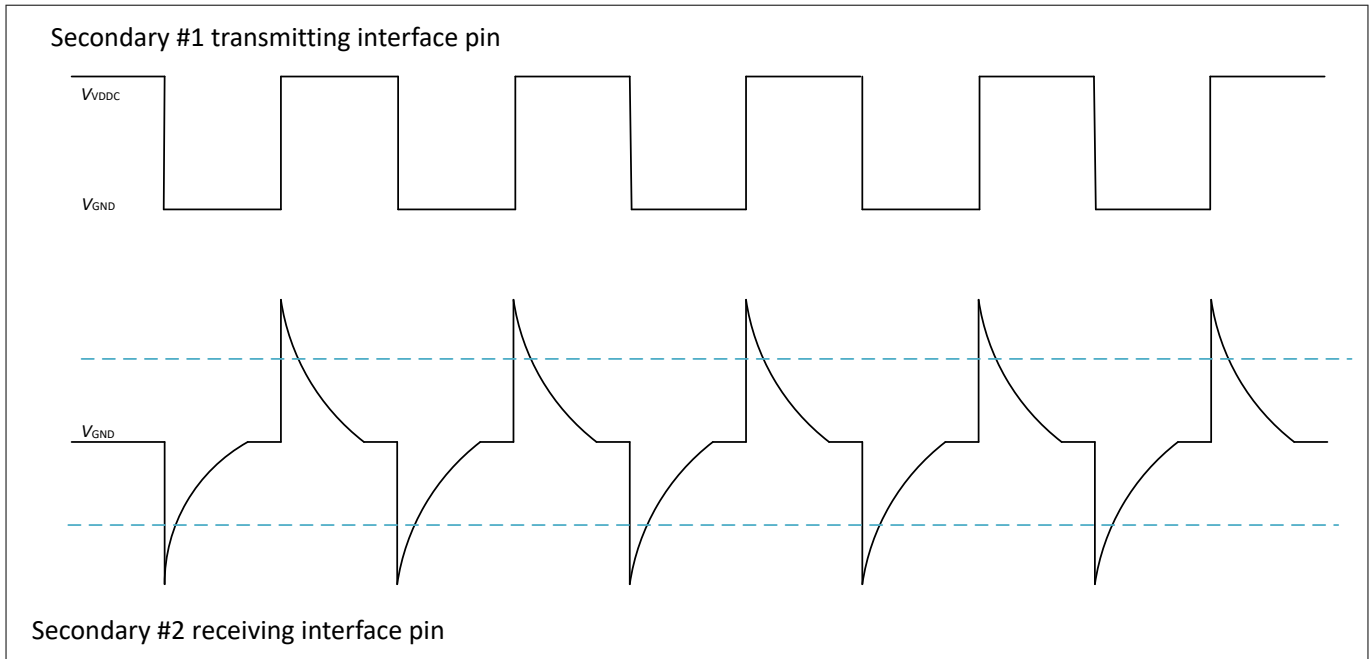


Figure 38 iso UART digital and analog signals

2.8.3 iso UART measurement point

In order to enable the secondary #2 to propagate the correct digital signals at its iso UART TX interface, the analog signals at its RX pins must meet the threshold requirements (blue dash line). Measured at point B with respect to ground as shown in the Figure below, the negative signal must cross the blue line $I_{isoUART_th_low_min} \times (R_{on} + R_{ser})$ to trigger a digital “0”. For a digital “1” to be successfully triggered, the positive edge signal must cross the blue line $I_{isoUART_th_high_max} \times (R_{on} + R_{ser})$.

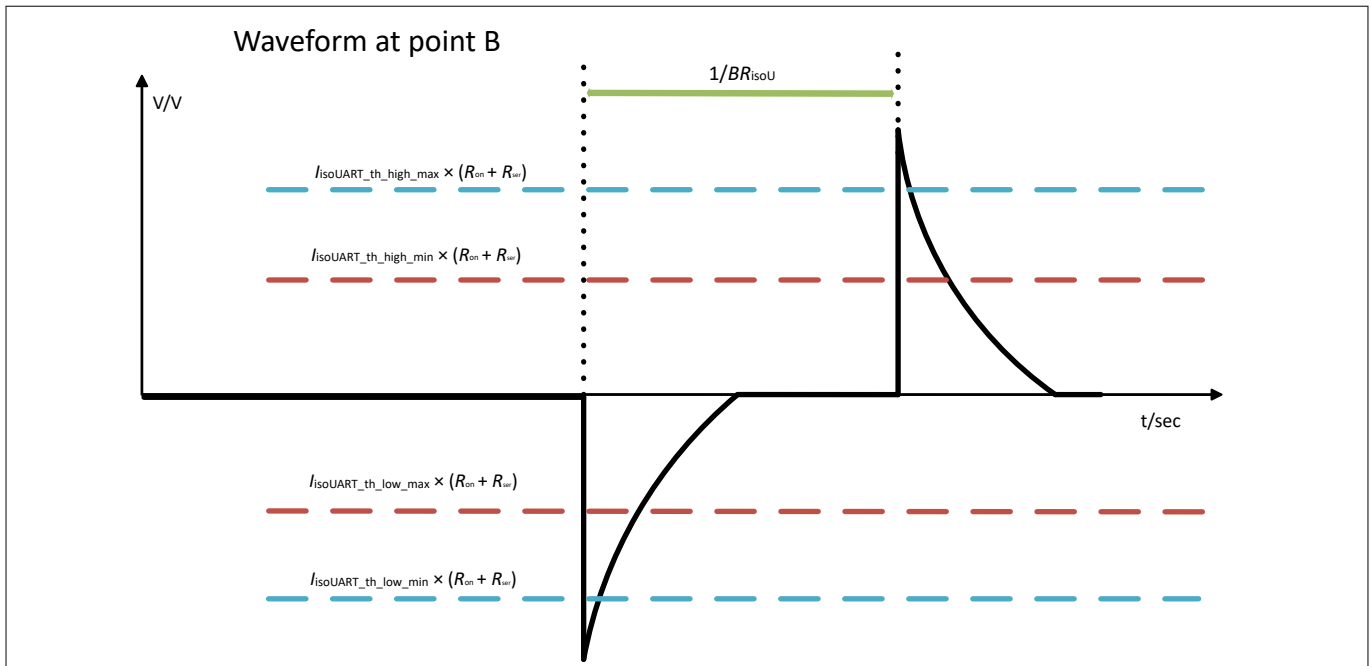


Figure 39 iso UART signal threshold level interpretation at point B

If the signal is measured at Point A (directly at the IC pin) with respect to ground, the threshold level should be reduced by the value R_{ser} (see Figure below).

2 Hardware guideline

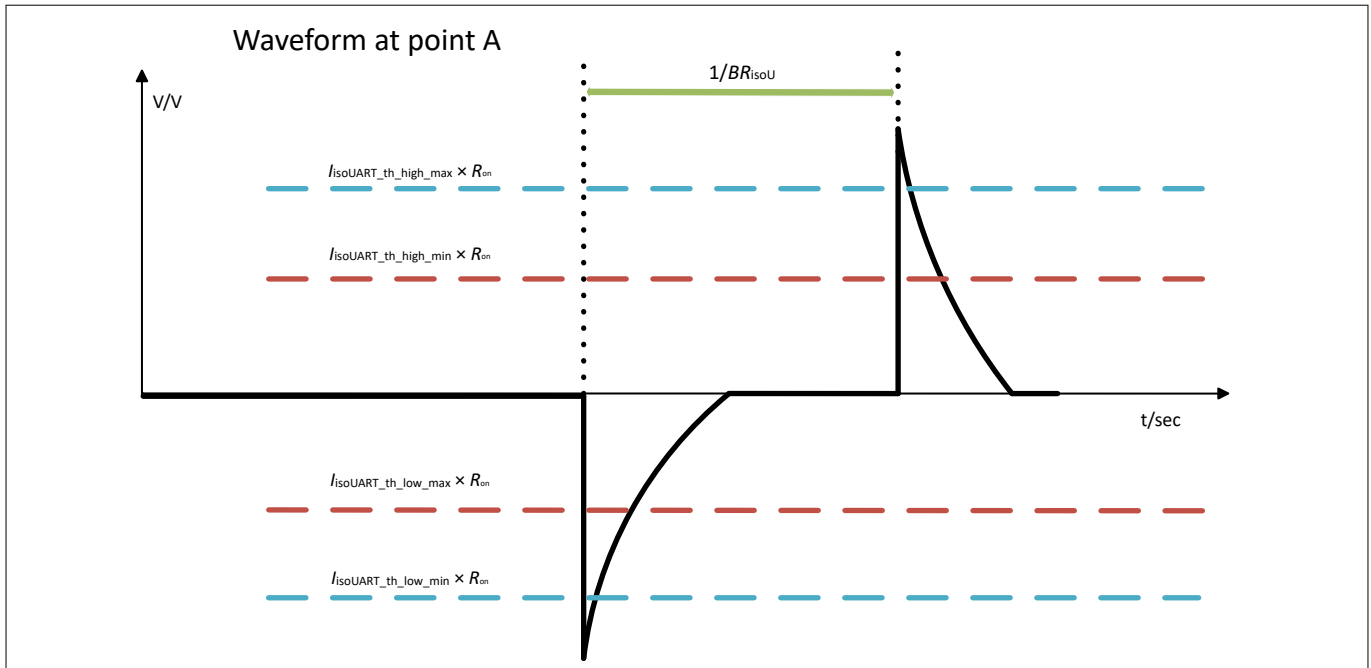


Figure 40 iso UART signal threshold level interpretation at point A

2.8.4 Capacitive coupled signal

For capacitive signals, the guideline is to follow the requirements illustrated in the chapter [iso UART measurement point](#) depending on the measurement point. The figure below gives an example of the typical application use case using the sensing IC evaluation board. The C_{ser} and R_{ser} used is 1 nF and 39 Ω respectively. R_{ser} is preferred to be fixed at 39 Ω and the user can tune the C_{ser} to meet the threshold requirement. This tuning may have an impact on the EMC performance, therefore it should be evaluated to fulfill the EMC system level requirements by the user in the final system. In this figure, the green signal at the secondary iso UART receiver input meets the threshold requirements and the secondary is able to transmit the correct red digital signals at its corresponding iso UART TX interface.

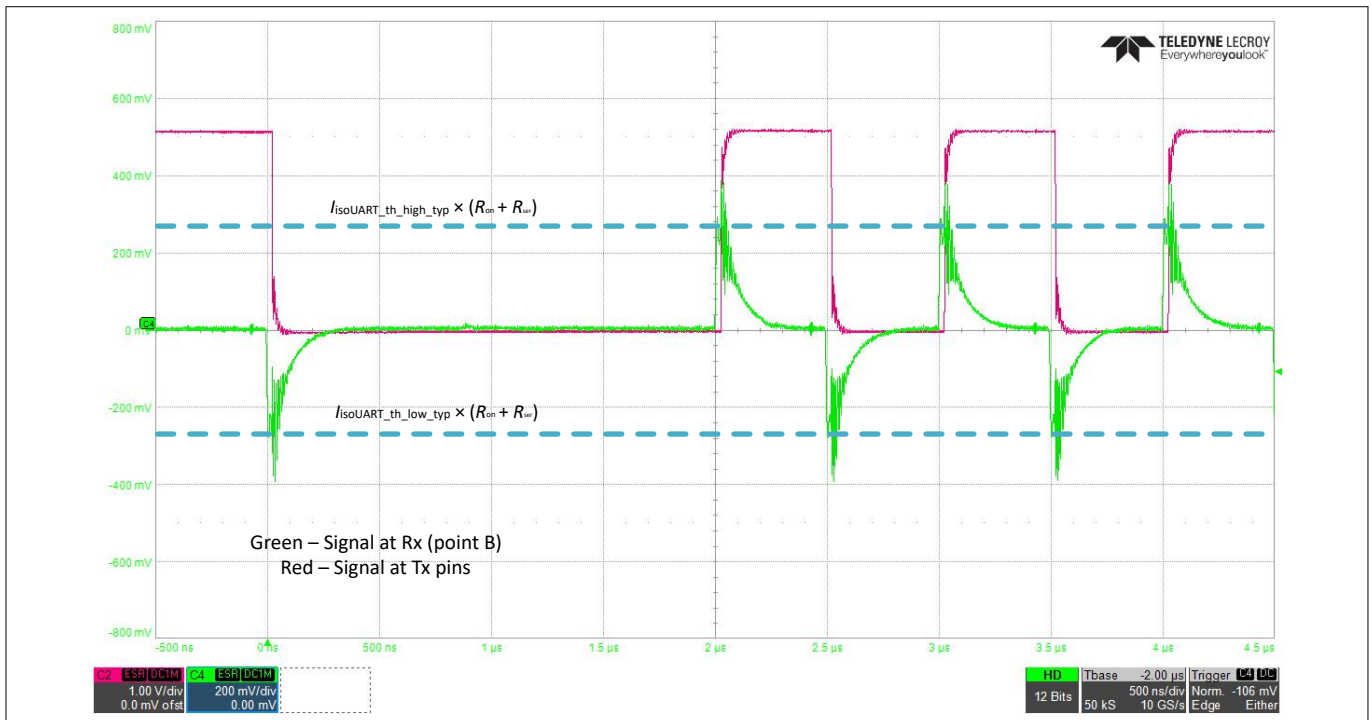


Figure 41 Capacitive coupled iso UART signals between two slave

2 Hardware guideline

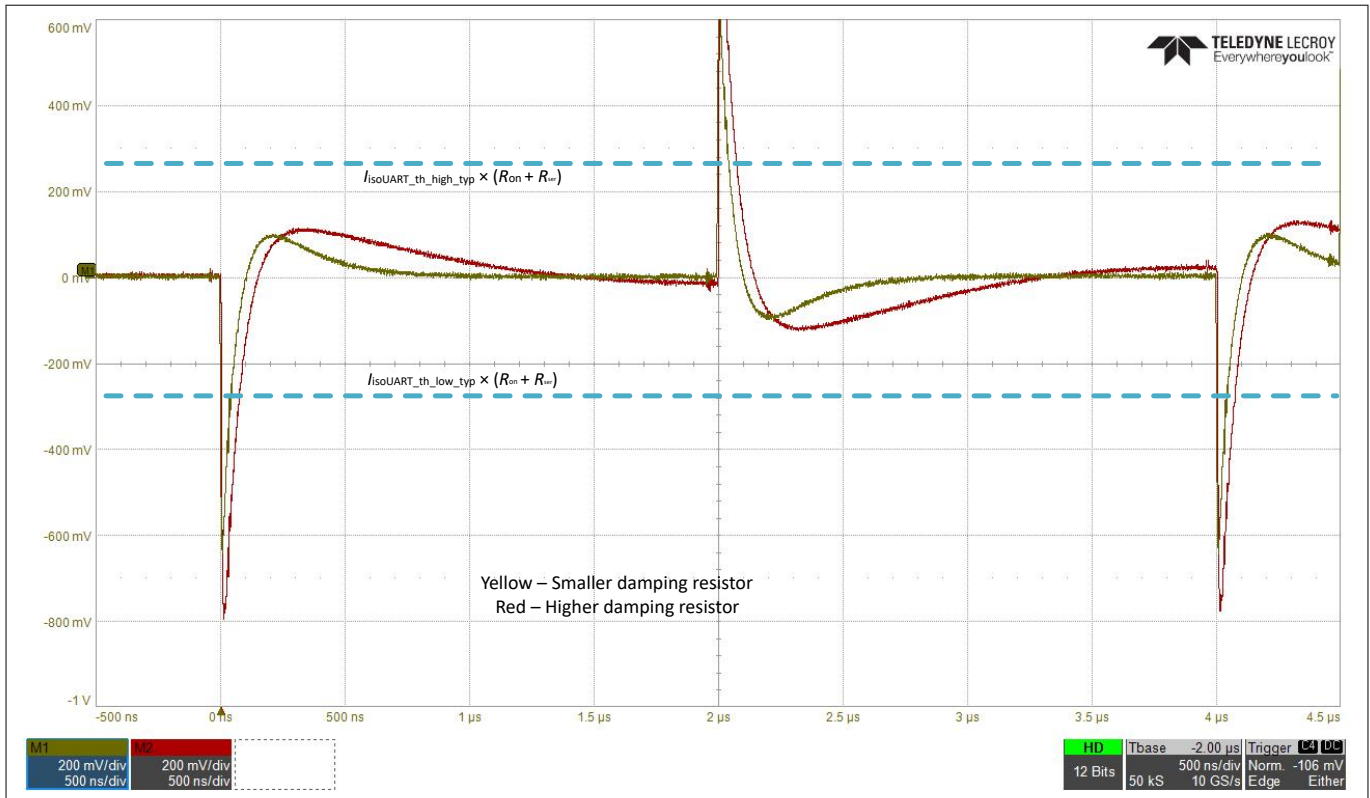


Figure 44 iso UART waveforms with different damping resistors

The iso UART physical layer thresholds ($I_{isoUART_th_high_min}$, $I_{isoUART_th_high_max}$, $I_{isoUART_th_low_min}$, $I_{isoUART_th_low_max}$) are defined in the IC datasheet. A high sensitivity current probe can be used to measure the iso UART current in one of the iso UART communication wires (see figure [Current probe measurement](#)). In cases where an iso UART current measurement is not possible, the iso UART voltage measurement can be realized with normal oscilloscope probes. *Note: A differential voltage measurement at the R_{ser} (39Ω) resistor (the differential voltage needs to be divided by 39Ω) is a good way to measure the current which passes the receiver. If a current probe is used (which is better than just measure the single ended voltage at the iso UART pin), a higher current will be measured (because a part of this current is shorted by EMC caps $C_{isoUART_F}$ and does not pass the receiver).*

2 Hardware guideline

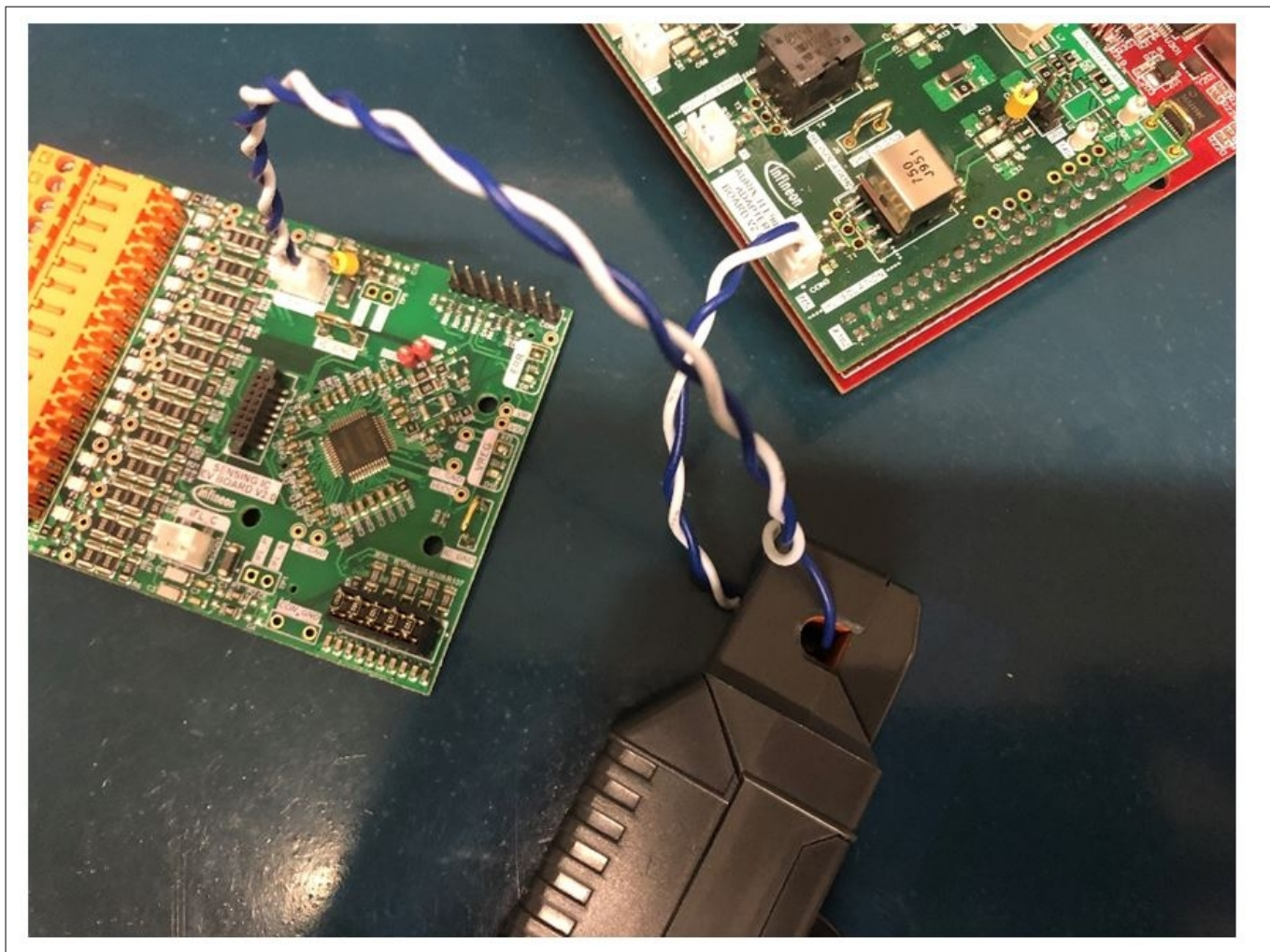


Figure 45 Current probe measurement

The iso UART current waveform can be used to determine the overdrive current I_{od} and the pulse duration t_{pulse} (see figure [iso UART waveform](#)).

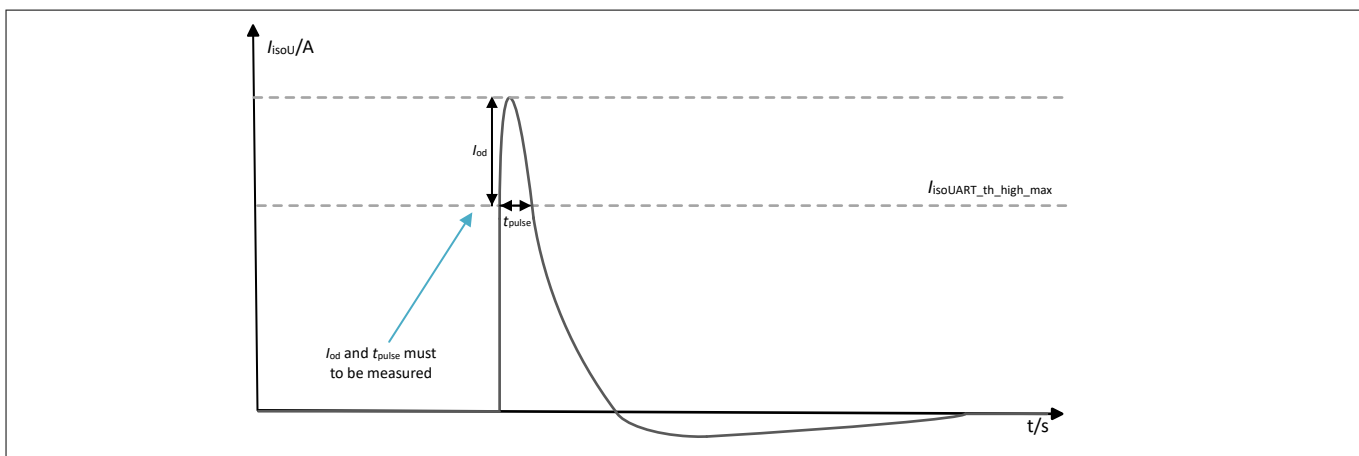


Figure 46 iso UART waveform

The resulting I_{od} should fall on the upper right part of the graph in figure [Overdrive current](#) to ensure that bits are correctly detected.

2 Hardware guideline

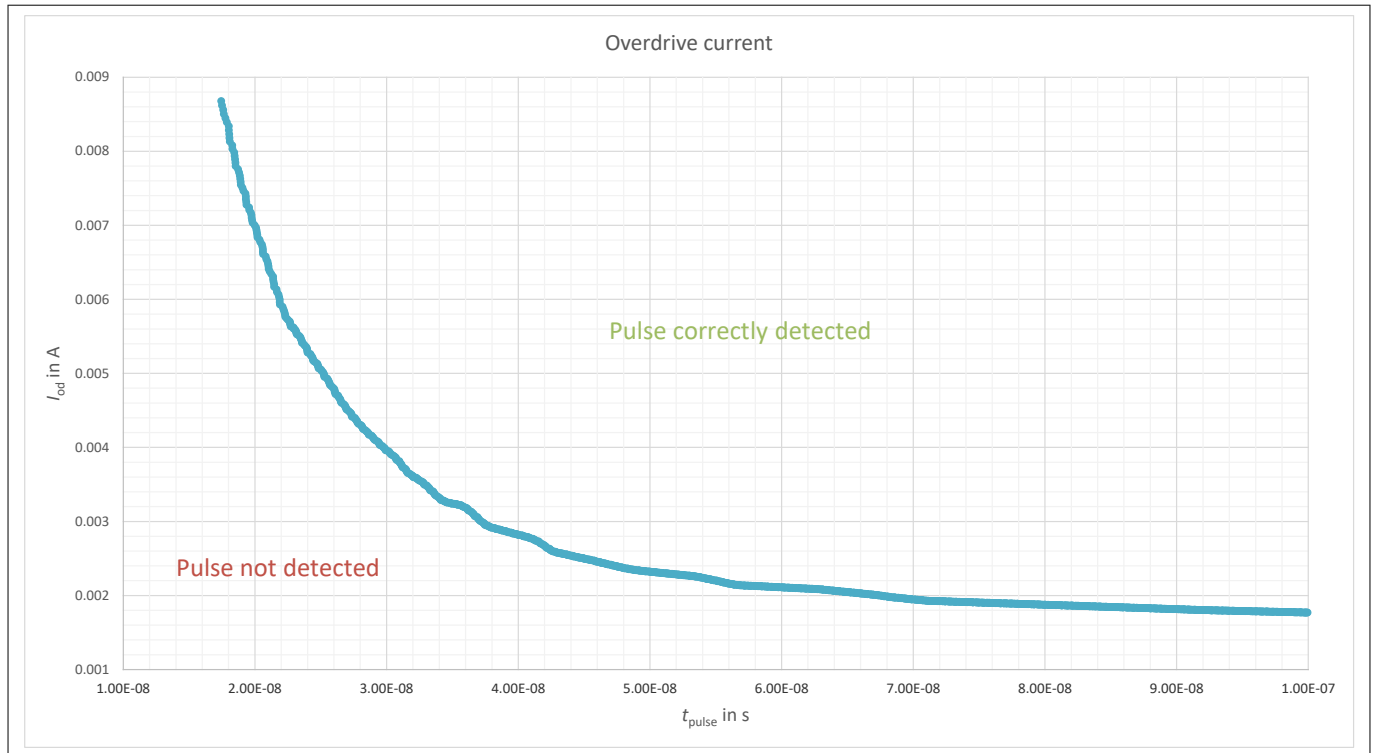


Figure 47 Overdrive current

For example in figure [iso UART current probe measurement - CEP99P \(2x510R\)](#), a peak voltage of 17 mA is measured. It leads to a I_{od} of $(17 - 6.25) \text{ mA} = 10.75 \text{ mA}$ and a pulse duration t_{pulse} of 50 ns. This value is on the upper right side of the graph and the bit will be correctly detected. The iso UART propagation delay increases the closer the overdrive current I_{od} is to the pulse detection curve (figure [Overdrive current](#)). Therefore, the max. $t_{isoU_prop_del}$ for the smallest I_{od} is shown in figure [iso UART propagation delay \$t_{isoU_prop_del_max}\$](#) .

2 Hardware guideline

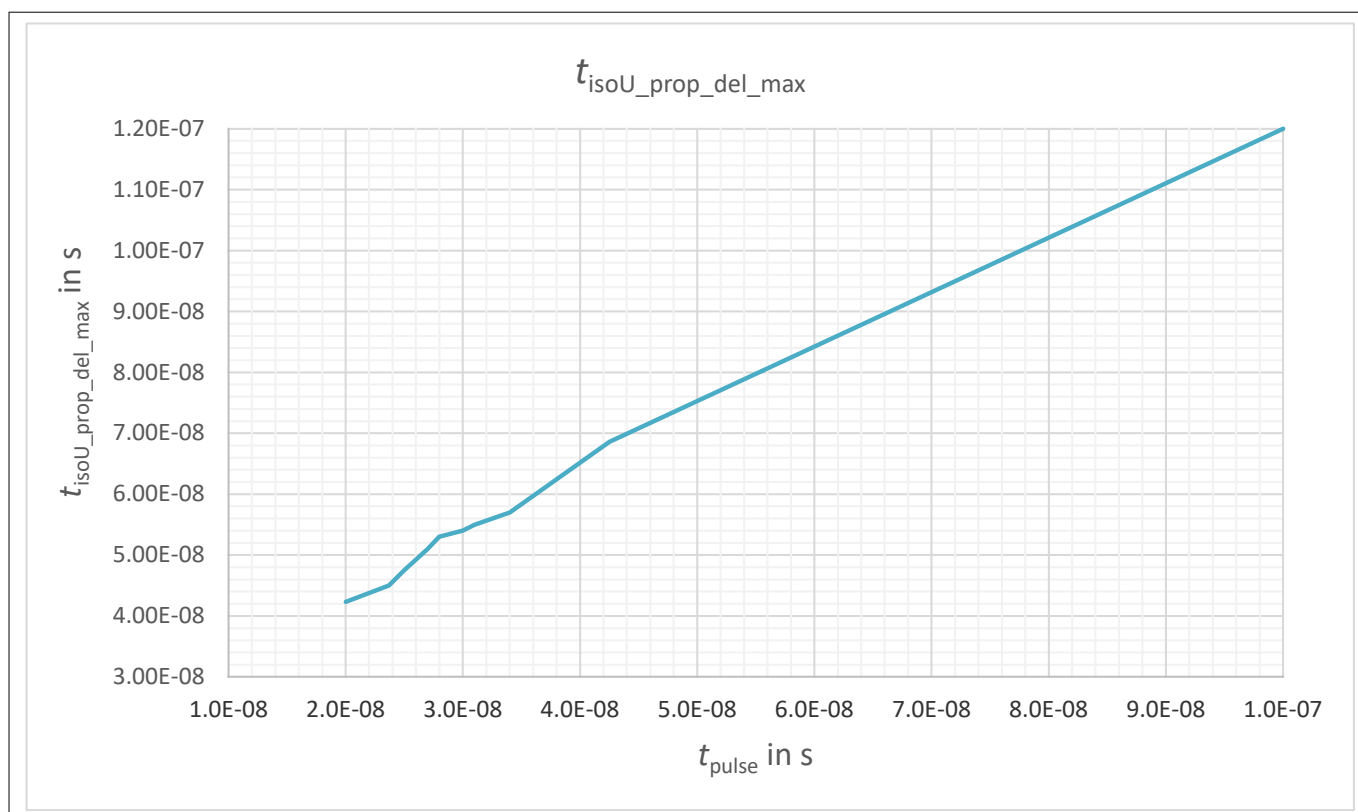


Figure 48 iso UART propagation delay $t_{isoU_prop_del_max}$

Figure [iso UART current probe measurement - CEP99P \(2x510R\)](#) and figure [iso UART current probe measurement - HM2116ANL \(2x510R, without C_isoUART_F\)](#) show the current waveform of the iso UART communication with two different transformers (Sumida CEP99P, Pulse HM2116ANL) and R_N/R_N set to 510Ω ($2 \times 510 \Omega$ damping resistor).

2 Hardware guideline

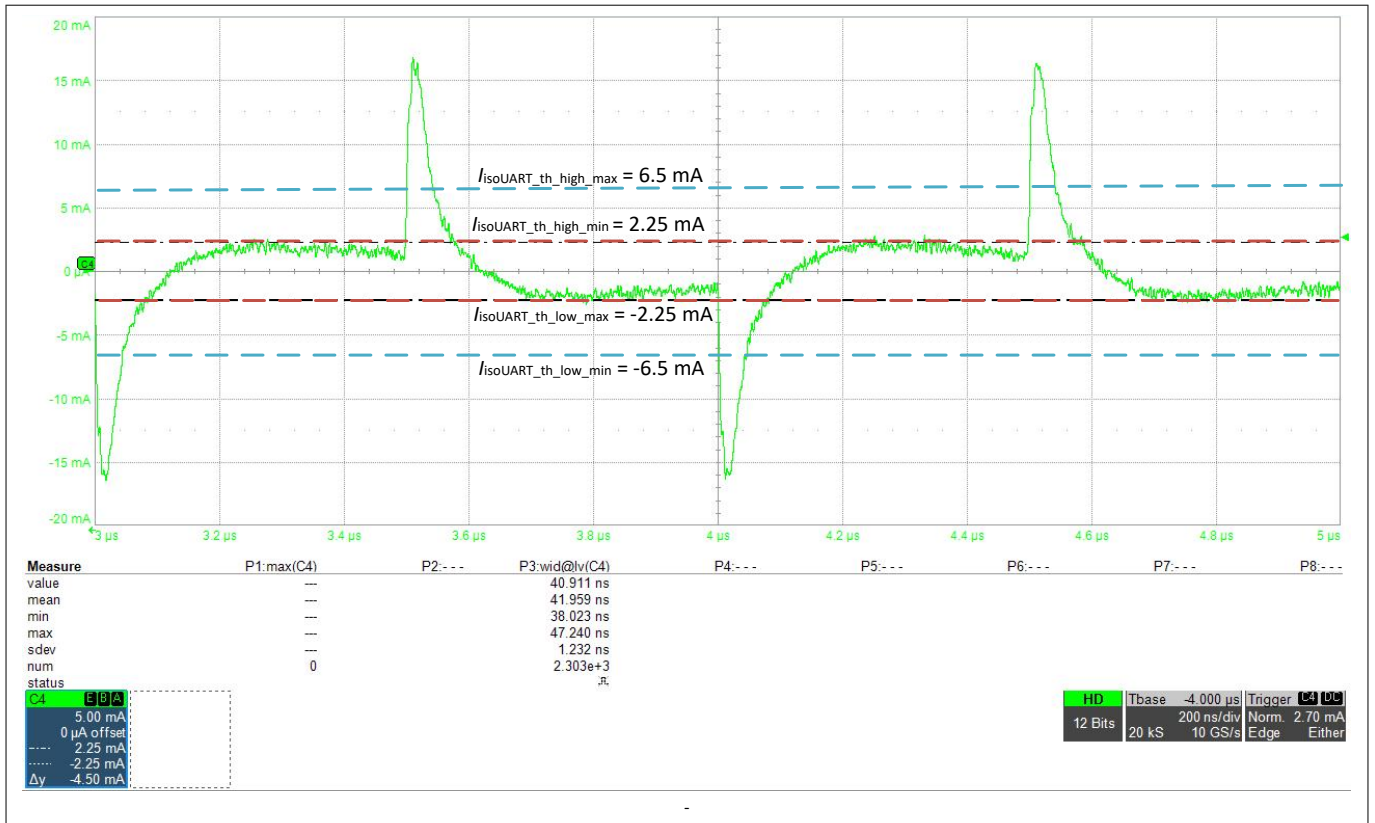


Figure 49 iso UART current probe measurement - CEP99P (2 × 510 Ω)

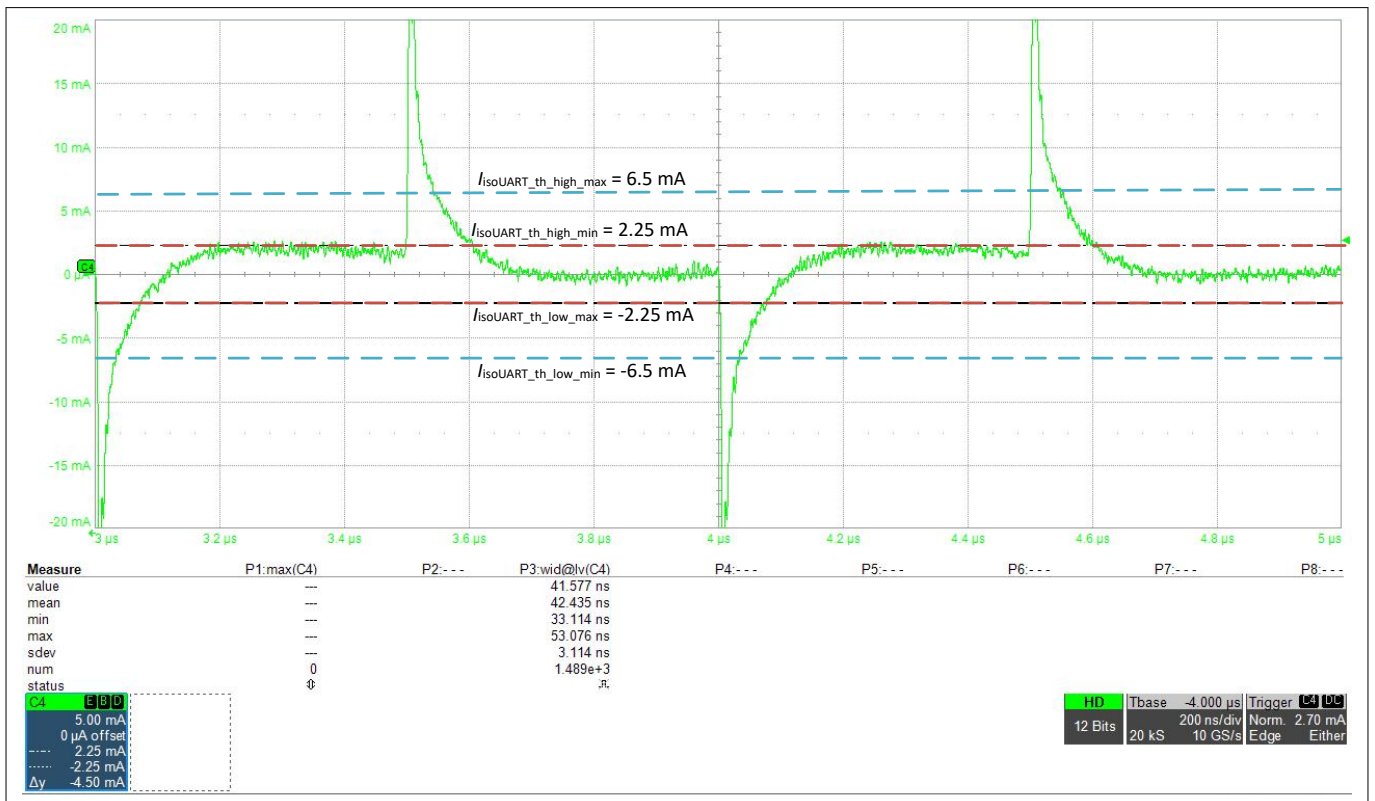


Figure 50 iso UART current probe measurement - HM2116ANL (2 × 510 Ω, without C_{isoUART_F})

2 Hardware guideline

The waveform in figure [Transformer CEP99P with 2x510R damping resistor](#) for the transformer CEP99P from Sumida with $2 \times 510 \Omega$ damping resistor shows the reference waveform which has been tested with corner samples.

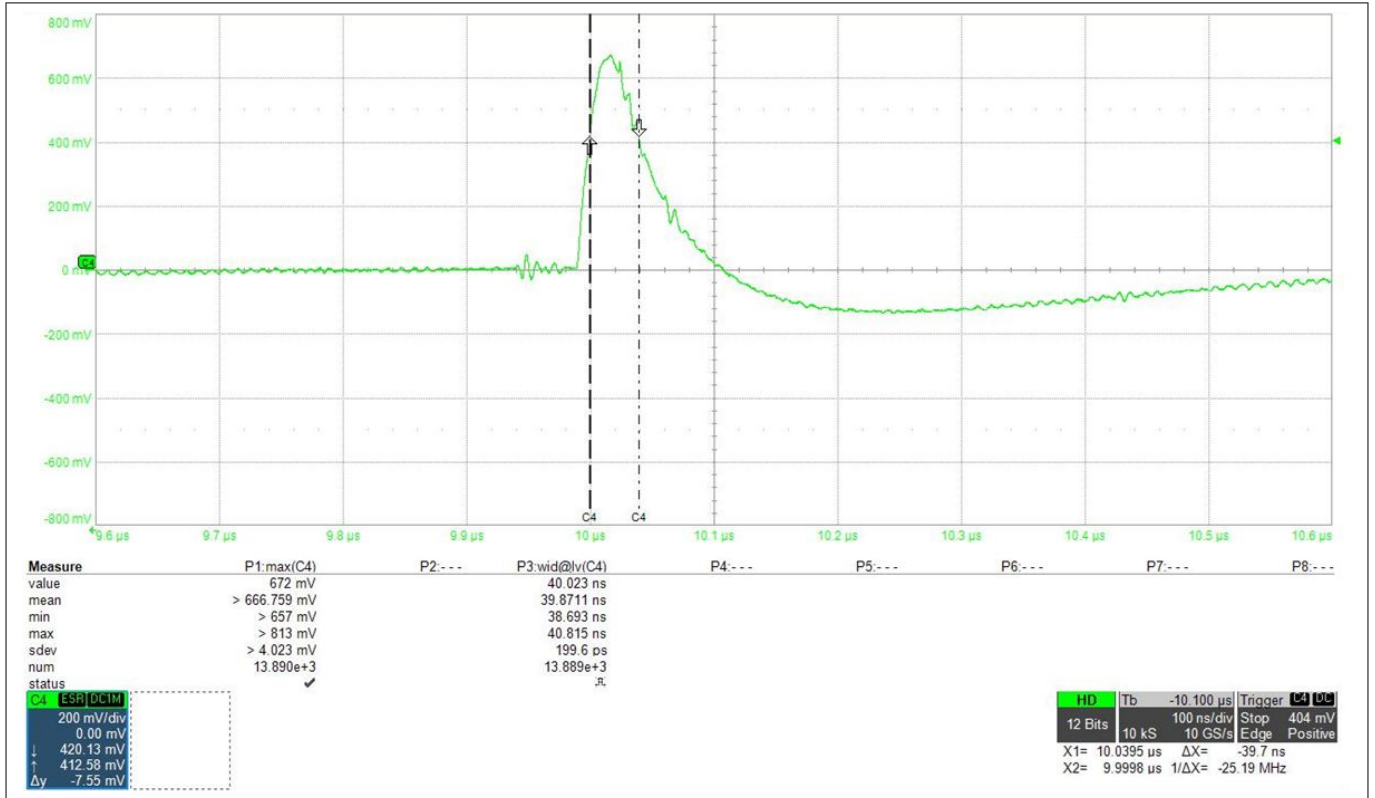


Figure 51 Transformer CEP99P with $2 \times 510 \Omega$ damping resistor

Figure [Transformer HM2116ANL with 2x510R damping resistor, without C_isoUART_F](#) shows the positive pulse with a Pulse HM2116ANL transformer with $2 \times 510 \Omega$. As a guideline, a pulse duration of 40 ns over the temperature range of the application is recommended.

2 Hardware guideline

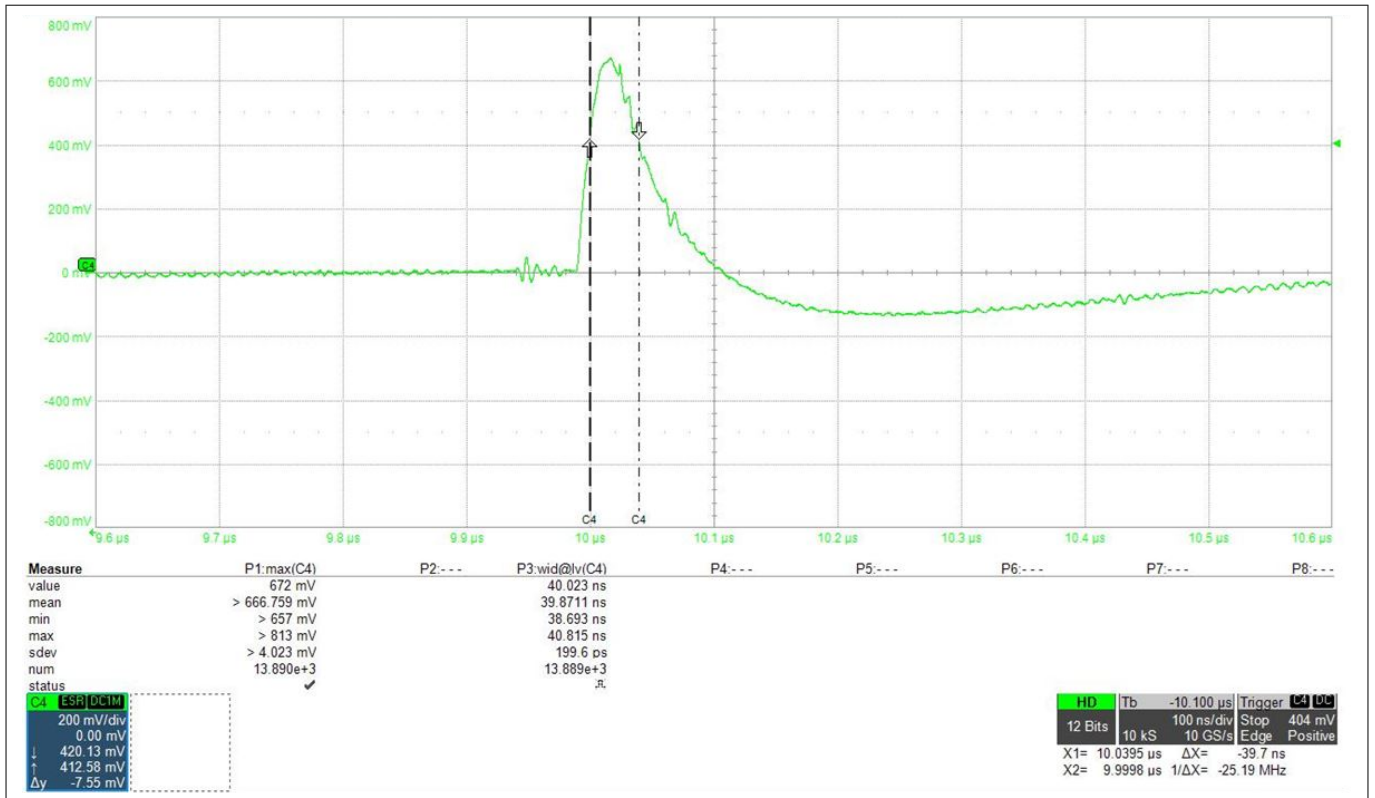


Figure 52 Transformer HM2116ANL with 2 × 510 Ω damping resistor, without C_{isoUART_F}

Figure [Transformer iso UART waveforms comparison](#) shows the iso UART waveform measurement at point B from two different transformer evaluations. The yellow waveform shows the waveform from Pulse HM2116ANL (without C_{isoUART_F}) while the green waveform shows the transformer from Sumida CEP99P. Both transformers have 2 × 510 Ω damping resistor mounted.

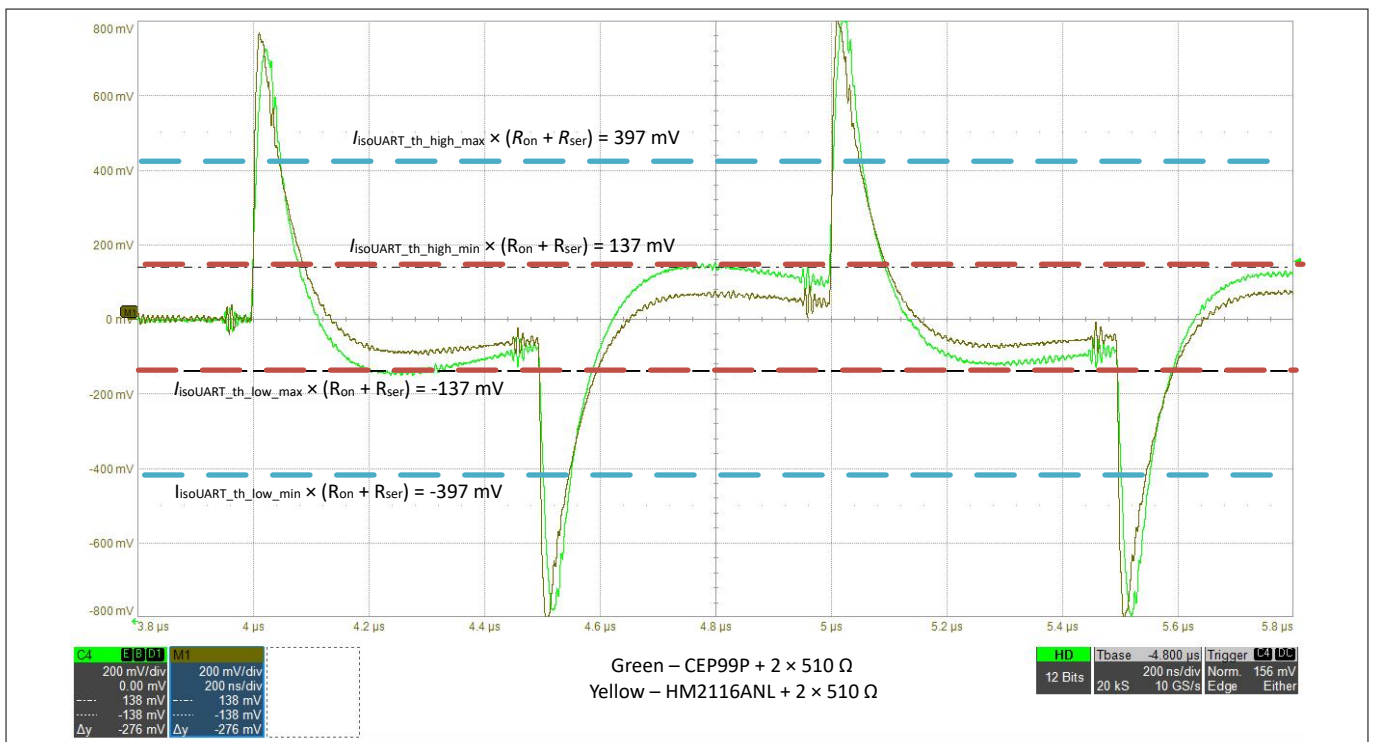


Figure 53 Transformer iso UART waveforms comparison

3 Software guideline

3 Software guideline

3.1 Initialization

In order to be able to communicate with the sensing ICs in the daisy chain, a CONFIG.NODE_ID (36_H) must be assigned. Before the initialization, the NODE_ID of all sensing ICs in the chain is ID = 00_H. If the NODE_ID = 00_H, no iso UART frames are forwarded to the next sensing IC in the chain. The following frame sequence shows an example initialization of four sensing ICs in a chain. The daisy chain is connected to the low-side iso UART interface of the transceiver (see [Primary-on-Top application \(wake-up via low-side interface\)](#)).

Table 7 Initialize first IC with NODE_ID = 01_H

Frame-type	Value	Comment
Synchronization	1E _H	Fixed synchronization frame; necessary to start the communication with a defined scheme.
ID	80 _H	MSB = 1 indicates a write command; 6-bit device ID = 000000 _B .
Address	36 _H	Address of CONFIG register.
Data	0001 _H	Assigns NODE_ID = 01 _H to the first sensing IC in the chain.
CRC	ED _H	CRC-code is based on 8-bit polynomial shown in CRC .

From this point onwards, the sensing IC closest to the transceiver IC has the NODE_ID = 01_H and forwards the messages. Now the next sensing IC in the chain will respond to commands addressed to NODE_ID = 00_H and the aforementioned process must be repeated (see below). *Note: The watchdog for NODE_ID = 01_H must be served if the initialization process takes longer than the predefined watchdog timer (WDOG_CNT.WD_CNT). Otherwise, the sensing IC will go to sleep mode and resets the NODE_ID to 00_H.*

Table 8 Initialize second IC with NODE_ID = 02_H

Frame-type	Value	Comment
Synchronization	1E _H	Fixed synchronization frame; necessary to start the communication with a defined scheme.
ID	80 _H	MSB = 1 indicates a write command; 6-bit device ID = 000000 _B .
Address	36 _H	Address of CONFIG register.
Data	0002 _H	Assigns NODE_ID = 02 _H to the second sensing IC in the chain.
CRC	CA _H	CRC-code is based on 8-bit polynomial shown in CRC .

From this point onwards, the second sensing IC has NODE_ID = 02_H, therefore the same applies as above for IC #1.

Table 9 Initialize third IC with NODE_ID = 03_H

Frame-type	Value	Comment
Synchronization	1E _H	Fixed synchronization frame; necessary to start the communication with a defined scheme.
ID	80 _H	MSB = 1 indicates a write command; 6-bit device ID = 000000 _B .
Address	36 _H	Address of CONFIG register.
Data	0003 _H	Assigns NODE_ID = 03 _H to the third sensing IC in the chain.

(table continues...)

3 Software guideline

Table 9 (continued) Initialize third IC with NODE_ID = 03_H

Frame-type	Value	Comment
CRC	D7 _H	CRC-code is based on 8-bit polynomial shown in CRC .

From this point onwards, the third sensing IC has NODE_ID = 03_H, therefore the same applies as above for IC #1.

Table 10 Initialize fourth IC with NODE_ID = 04_H

Frame-type	Value	Comment
Synchronization	1E _H	Fixed synchronization frame; necessary to start the communication with a defined scheme.
ID	80 _H	MSB = 1 indicates a write command; 6-bit device ID = 000000 _B .
Address	36 _H	Address of CONFIG register.
Data	0804 _H	Final Node FN = 1 _H , otherwise no reply frame is sent on broadcast command (iso UART time-out). NODE_ID = 04 _H assigned to the fourth sensing IC in the chain.
CRC	DE _H	CRC-code is based on 8-bit polynomial shown in CRC .

Note: The initialization process can easily be looped in a software process.

3 Software guideline

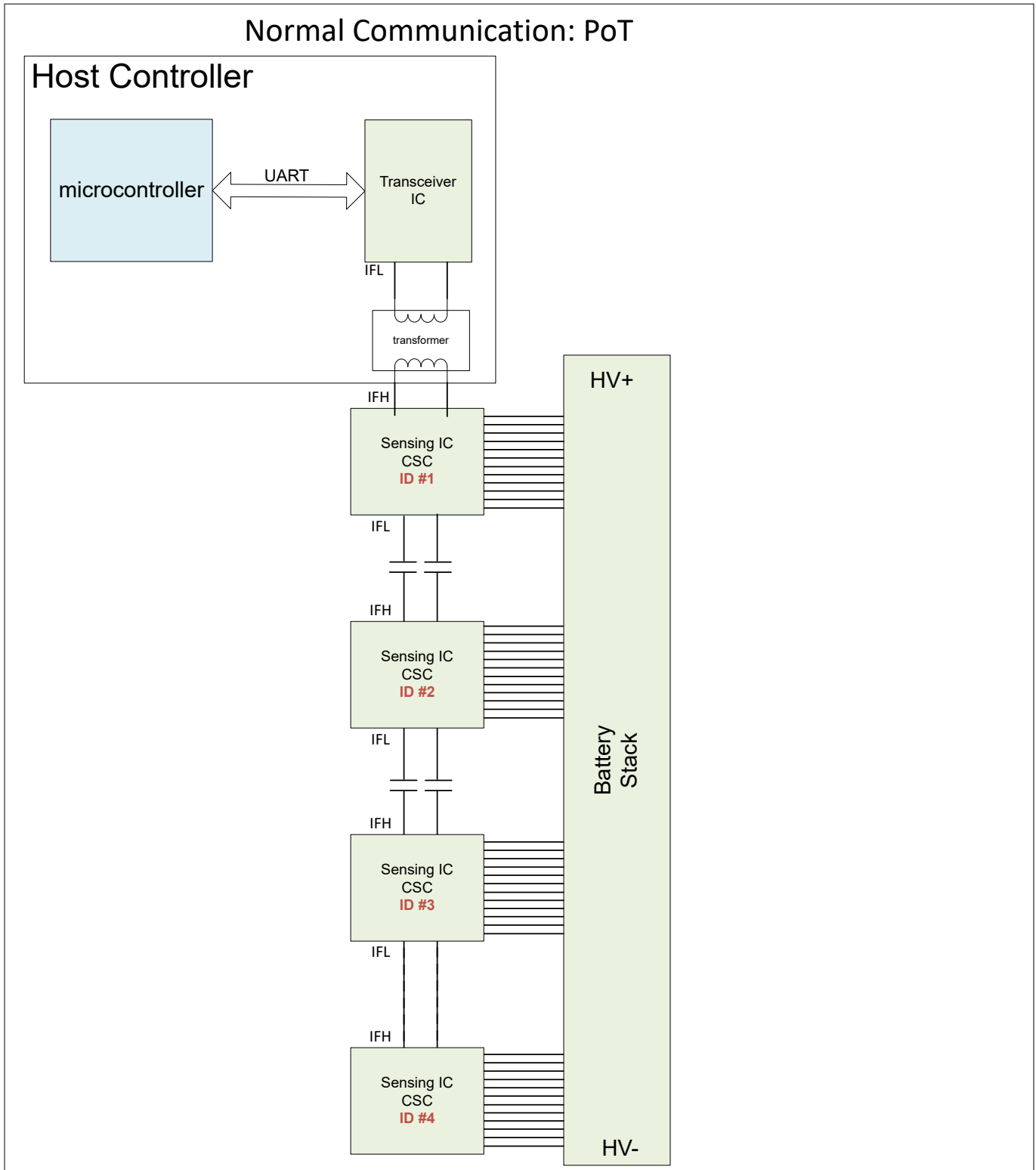


Figure 54 Primary-on-Top application (wake-up via low-side interface)

3.1.1 CRC

The CRC for the CRC frame is compliant to the SAE-J1850 standard and is calculated according to the following equation:

$$G(z) = z^8 + z^4 + z^3 + z^2 + 1 \text{ (initial value = FF}_{\text{H}}\text{; XOR value = FF}_{\text{H}}\text{)}$$

3 Software guideline

3.1.2 Read back of configuration registers

The host controller should read back the register content after writing to a configuration register to check if the write command was successful. The following example shows the read back of the CONFIG 36_H register:

Table 11 Read back CONFIG register of the first IC

Frame-type	Value	Comment
Synchronization	1E _H	Fixed synchronization frame; necessary to start the communication with a defined scheme.
ID	01 _H	MSB = 0 indicates a read command; 6-bit device ID = 000001 _B .
Address	36 _H	Address of CONFIG register.
CRC	A8 _H	CRC-code is based on 8-bit polynomial shown in CRC .

3.2 Configuration

3.2.1 Partitioning config

The PART_CONFIG 01_H register defines how many cells are connected to the sensing IC. This register determines which ADCs are activated during the primary cell voltage measurement (PCVM) and monitored during the round robin scheme. The following frame sequence activates all 12 PCVM channels for the sensing IC with the NODE_ID = 000001_B:

Table 12 Write PART_CONFIG register for the first IC

Frame-type	Value	Comment
Synchronization	1E _H	Fixed synchronization frame; necessary to start the communication with a defined scheme.
ID	81 _H	MSB = 1 indicates a write command; 6-bit device ID = 000001 _B .
Address	01 _H	Address of PART_CONFIG register.
Data	0FFF _H	Enables cell monitoring for all 12 cells.
CRC	A8 _H	CRC-code is based on 8-bit polynomial shown in CRC .

Note: In general, this command can be sent as a broadcast write command if it should affect all IC's in the daisy chain. This applies for all other registers as well. An example for a broadcast write command is shown in [Primary cell voltage measurement](#).

3.2.2 Cell voltage thresholds

The cell voltages checked via comparators and a digital-to-analog converter (DAC). The thresholds for the comparators are configured in the overvoltage OL_OV_THR 02_H and undervoltage OL_UV_THR 03_H registers. The following frame sequence configures an undervoltage threshold of e.g. 1.5 V and an overvoltage threshold of e.g. 4.6 V for the first sensing IC:

3 Software guideline

Table 13 **Overvoltage OL_OV_THR set to 4.6 V**

Frame-type	Value	Comment
Synchronization	1E _H	Fixed synchronization frame; necessary to start the communication with a defined scheme.
ID	81 _H	MSB = 1 indicates a write command; 6-bit device ID = 000001 _B .
Address	02 _H	Address of OL_OV_THR register.
Data	FFAE _H	Sets OL_OV_THR = FFAE _H <ul style="list-style-type: none"> • Calculation OV_THR: 4.6 V / V_{OVUV_LSB} = 3AE_H • Default value for OL_THR_MAX used = 3F_H
CRC	05 _H	CRC-code is based on 8-bit polynomial shown in CRC .

Table 14 **Undervoltage OL_UV_THR set to 1.5 V**

Frame-type	Value	Comment
Synchronization	1E _H	Fixed synchronization frame; necessary to start the communication with a defined scheme.
ID	81 _H	MSB = 1 indicates a write command; 6-bit device ID = 000001 _B .
Address	03 _H	Address of OL_UV_THR register.
Data	0134 _H	Sets OL_UV_THR = 0134 _H <ul style="list-style-type: none"> • Calculation UV_THR: 1.5 V / V_{OVUV_LSB} = 134_H • Default value for OL_THR_MIN used = 00_H
CRC	BE _H	CRC-code is based on 8-bit polynomial shown in CRC .

3.2.3 **Open load diagnostics**

The open load diagnostics offers the possibility to automatically detect open wires on Un and Gn pins. Therefore, the open load thresholds needs to be set to define the minimum and maximum voltage drop while open load diagnostics. The configuration of the thresholds depends on the used filter resistor R_F . With the recommended filter resistor of 10 Ω and I_{OL_DIAG} (with $I_{OL_DIAG_min}$, $I_{OL_DIAG_max}$), the minimum voltage drop is 0.1 V (= 10 Ω \times $I_{OL_DIAG_min}$) and the maximum voltage drop is 0.183 V (= 10 Ω \times $I_{OL_DIAG_max}$) (disregarding the variation of the filter resistor). To prevent false triggering of the OL error (due to noise), an additional buffer can be added e.g. 40 mV. The following frame sequences sets the OL_OV_THR.OL_THR_MAX = 0.223 V and the OL_UV_THR.OL_THR_MIN = 0.06 V for the first sensing IC:

Table 15 **Open load maximum voltage drop threshold OL_THR_MAX = 0.223 V**

Frame-type	Value	Comment
Synchronization	1E _H	Fixed synchronization frame; necessary to start the communication with a defined scheme.
ID	81 _H	MSB = 1 indicates a write command; 6-bit device ID = 000001 _B .
Address	02 _H	Address of OL_OV_THR register.

(table continues...)

3 Software guideline

Table 15 (continued) Open load maximum voltage drop threshold $OL_THR_MAX = 0.223\text{ V}$

Frame-type	Value	Comment
Data	2FFF _H	Sets $OL_OV_THR = 2FFF_H$ <ul style="list-style-type: none"> Calculation $OL_THR_MAX: 0.223\text{ V} / OL_{thr_LSB} = B_H$ Default value for OV_THR used = 3FF_H
CRC	51 _H	CRC-code is based on 8-bit polynomial shown in CRC .

Table 16 Open load minimum voltage drop threshold $OL_THR_MIN = 0.06\text{ V}$

Frame-type	Value	Comment
Synchronization	1E _H	Fixed synchronization frame; necessary to start the communication with a defined scheme.
ID	81 _H	MSB = 1 indicates a write command; 6-bit device ID = 000001 _B .
Address	03 _H	Address of OL_UV_THR register.
Data	0C00 _H	Sets $OL_UV_THR = 0C00_H$ <ul style="list-style-type: none"> Calculation $OL_THR_MIN: 0.06\text{ V} / OL_{thr_LSB} = 3_H$ Default value for UV_THR used = 000_H
CRC	BB _H	CRC-code is based on 8-bit polynomial shown in CRC .

3.2.4 NTC temperature measurement configuration

The sensing IC can measure up to 5 external temperature sensors. As part of the round robin (RR) scheme, up to two temperature measurements can be performed in every RR cycle. The number of external temperature sensors is configured in the $TEMP_CONF$ 04_H register. As an example, all temperature channels are activated for sensing IC 1:

Table 17 Number of external temperature sensors NR_TEMP_SENSE

Frame-type	Value	Comment
Synchronization	1E _H	Fixed synchronization frame; necessary to start the communication with a defined scheme.
ID	81 _H	MSB = 1 indicates a write command; 6-bit device ID = 000001 _B .
Address	04 _H	Address of $TEMP_CONF$ register.
Data	5000 _H	Sets $TEMP_CONF.NR_TEMP_SENSE = 101_B$; default values for I_NTC and EXT_OT_THR used.
CRC	18 _H	CRC-code is based on 8-bit polynomial shown in CRC .

3.2.5 Balancing current thresholds

A balancing overcurrent OC_THR or undercurrent UC_THR check is performed during the round robin cycle. If the balancing current is lower than the UC_THR or higher than the OC_THR , the corresponding error counter will be incremented. The example shows a threshold configuration for sensing IC 1 with a maximum balancing current $I_{BAL_max} = 4.3\text{ V} / (R_F + R_{BAL} + R_{BAL_on_min}) \Omega = 83\text{ mA}$ at 4.3V and a minimum balancing current $I_{BAL_min} = 2.7\text{ V} / (R_F + R_{BAL} + R_{BAL_on_max}) \Omega = 48\text{ mA}$ at 2.7 V (disregarding the variation of the external components). A filter resistor R_F of 10 Ω and a balancing resistor of 41 Ω is assumed and the balancing switch on-state resistance R_{BAL_on} is considered. A voltage of $\pm 100\text{ mV}$ is used as voltage drop ($I_{BAL} \times R_F$) buffer, the balancing

3 Software guideline

current voltage drop must be within minimum $(I_{BAL_min} \times R_F - 0.1 V) = 0.38 V$ and maximum $(I_{BAL_max} \times R_F + 0.1 V) = 0.93 V$.

Table 18 Balancing current thresholds BAL_CURR_THR 15_H

Frame-type	Value	Comment
Synchronization	1E _H	Fixed synchronization frame; necessary to start the communication with a defined scheme.
ID	81 _H	MSB = 1 indicates a write command; 6-bit device ID = 000001 _B .
Address	15 _H	Address of BAL_CURR_THR register.
Data	1330 _H	Set BAL_CURR_THR = 1330 _H <ul style="list-style-type: none"> Calculation UC_THR: $0.38 V / CD_{thr_LSB} = 13_H$ Calculation OC_THR: $0.93 V / CD_{thr_LSB} = 30_H$
CRC	FB _H	CRC-code is based on 8-bit polynomial shown in CRC .

3.3 Cell voltage measurement

3.3.1 Primary cell voltage measurement

To initiate a primary cell voltage measurement of the connected cells, the bit-field MEAS_CTRL.PCVM_START needs to be set. The measurement starts after the configurable delay time t_{VM_del} . The delay time allows the external filter to settle to e.g. avoid errors due to prior balancing. t_{VM_del} is active independent of the balancing status. After the measurement, the PCVM_START bit-field is automatically cleared and the result is available in the PCVM_0 - PCVM_11 result registers. The PCVM_0 - PCVM_11 registers will be cleared during the measurement until the measurement is finished. To avoid measurement errors due to passive balancing current, the PBOFF bit-field is by default 1_B to automatically deactivate the passive balancing switches during the cell voltage measurement. The following example shows the initiation of the cell voltage measurement with 16-bit for sensing IC 1:

Table 19 Measurement control MEAS_CTRL 18_H

Frame-type	Value	Comment
Synchronization	1E _H	Fixed synchronization frame; necessary to start the communication with a defined scheme.
ID	81 _H	MSB = 1 indicates a write command; 6-bit device ID = 000001 _B .
Address	18 _H	Address of MEAS_CTRL register.
Data	E021 _H	Sets MEAS_CTRL = E021 _H <ul style="list-style-type: none"> PCVM_START = 1_B CVM_MODE = 110_B (16-bit) Default for BVM_START, BVM_MODE, AVM_START, SCVM_START, PBOFF, CVM_DEL
CRC	98 _H	CRC-code is based on 8-bit polynomial shown in CRC .

A broadcast write command can be used to start the measurement for all ICs in the chain with a single command at the same time. The following example starts the voltage measurements for IC #1 to IC #4 (see [Primary-on-Top application \(wake-up via low-side interface\)](#)):

3 Software guideline

Table 20 Broadcast write to measurement control MEAS_CTRL 18_H

Frame-type	Value	Comment
Synchronization	1E _H	Fixed synchronization frame; necessary to start the communication with a defined scheme.
ID	BF _H	MSB = 1 indicates a write command; 6-bit device ID = 111111 _B indicates a broadcast command.
Address	18 _H	Address of MEAS_CTRL register.
Data	E021 _H	Sets MEAS_CTRL = E021 _H <ul style="list-style-type: none"> PCVM_START = 1_B CVM_MODE = 110_B (16-bit) Default for BVM_START, BVM_MODE, AVM_START, SCVM_START, PBOFF, CVM_DEL
CRC	02 _H	CRC-code is based on 8-bit polynomial shown in CRC .

3.3.2 Block voltage measurement

The 13th ADC can perform different auxiliary voltage measurements including a block voltage measurement (BVM). The voltage is measured between U12P and GND. A BVM measurement is initiated by setting the bit-field MEAS_CTRL.BVM_START and starts after t_{VM_prop} . The measurement result is stored in the BVM 28_H register and the BVM_START bit is automatically cleared after the measurement. The following example shows the initiation of the block voltage measurement with 16-bit for sensing IC 1:

Table 21 Measurement control MEAS_CTRL 18_H

Frame-type	Value	Comment
Synchronization	1E _H	Fixed synchronization frame; necessary to start the communication with a defined scheme.
ID	81 _H	MSB = 1 indicates a write command; 6-bit device ID = 000001 _B .
Address	18 _H	Address of MEAS_CTRL register.
Data	0E21 _H	Sets MEAS_CTRL = 0E21 _H <ul style="list-style-type: none"> BVM_START = 1_B BVM_MODE = 110_B (16-bit) Default for PCVM_START, PCVM_MODE, AVM_START, SCVM_START, PBOFF, CVM_DEL
CRC	21 _H	CRC-code is based on 8-bit polynomial shown in CRC .

3.3.3 Bipolar auxiliary voltage measurement

Additionally, the device can be configured to measure a bipolar voltage. The voltage is measured between TMP4 and TMP3. A BAVM measurement is enabled by setting the AVM_CONFIG.AUX_BIPOLAR bitfield.

3 Software guideline

Table 22 Auxiliary voltage measurement configuration AVM_CONFIG 17_H

Frame-type	Value	Comment
Synchronization	1E _H	Fixed synchronization frame; necessary to start the communication with a defined scheme.
ID	81 _H	MSB = 1 indicates a write command; 6-bit device ID = 000001 _B .
Address	17 _H	Address of AVM_CONFIG register.
Data	0107 _H	Sets AVM_CONFIG = 0107 _H <ul style="list-style-type: none"> AUX_BIPOLAR = 1_B Default for TEMP_MUX_DIAG_SEL, AVM_TMPx_MASK, R_DIAG, R_DIAG_SEL_0, R_DIAG_SEL_1, R_DIAG_CUR_SRC
CRC	85 _H	CRC-code is based on 8-bit polynomial shown in CRC .

The resolution is set by the MEAS_CTRL.BVM_MODE bitfield and the measurement is triggered by the MEAS_CTRL.BVM_START bitfield after t_{VM_prop} . The following example shows the initiation of the bipolar auxiliary voltage measurement with 16-bit for sensing IC 1:

Table 23 Measurement control MEAS_CTRL 18_H

Frame-type	Value	Comment
Synchronization	1E _H	Fixed synchronization frame; necessary to start the communication with a defined scheme.
ID	81 _H	MSB = 1 indicates a write command; 6-bit device ID = 000001 _B .
Address	18 _H	Address of MEAS_CTRL register.
Data	0E21 _H	Sets MEAS_CTRL = 0E21 _H <ul style="list-style-type: none"> BVM_START = 1_B BVM_MODE = 110_B (16-bit) Default for PCVM_START, PCVM_MODE, AVM_START, SCVM_START, PBOFF, CVM_DEL
CRC	21 _H	CRC-code is based on 8-bit polynomial shown in CRC .

The measurement result is stored in the BVM 28_H register and the BVM_START bit is automatically cleared after the measurement.

3.4 Calculations

3.4.1 Voltage, PCVM, SCVM, BVM

After a primary cell voltage measure command (PCVM), an unsigned value is stored in the RESULT bit-fields of the PCVM_0 - PCVM_11 (Offset Address: 19_H - 24_H) registers. The equation to calculate the cell voltage is:

$$V_{PCVM} [V] = (FSR_{PCVM} / 2^{16}) \times RESULT[LSB16]$$

e.g. PCVM_0 = ABCD_H

$$V_{PCVM} [V] = (5 V / 2^{16}) \times ABCD_H = 3.355 V$$

Using the [PCVM formula](#), a voltage of 3.355 V for cell 0 (PCVM_0) is calculated.

3 Software guideline

To calculate the block voltage after a block voltage measurement (BVM), a similar formula is used. The RESULT stored in the BVM register (Offset Address: 28_H) is converted to a voltage with [BVM formula](#).

$$V_{BVM} [V] = (FSR_{BVM} / 2^{16}) \times RESULT_BVM [LSB16]$$

e.g. BVM = ABCD_H

$$V_{BVM} [V] = (60 V / 2^{16}) \times ABCD_H = 40.266 V$$

Using the formula [BVM formula](#), a voltage of 40.266 V for the block voltage is calculated.

To calculate the secondary cell voltage after a secondary cell voltage measurement (SCVM), a similar formula is used. The RESULT stored in the SCVM_HIGH and SCVM_LOW registers (Offset Address: 25_H, 26_H) is converted to a voltage with [SCVM formula](#).

$$V_{SCVM} [V] = (FSR_{SCVM} / 2^{11}) \times RESULT [LSB11]$$

e.g. SCVM_HIGH = ABE0_H

$$V_{SCVM} [V] = (5 V / 2^{11}) \times 1010101111_B = 1.677 V$$

Using the [SCVM formula](#), a voltage of 1.677 V for the secondary cell voltage SCVM_HIGH is calculated.

To calculate the bipolar auxiliary voltage after a bipolar auxiliary voltage measurement (BAVM), a similar formula is used. The RESULT stored in the BVM register (Offset Address: 28_H) is converted to a voltage with [BAVM formula](#).

$$V_{BAVM} [V] = (BVM.RESULT [signed LSB15] \times 2 V) / 2^{15} [LSB15]$$

e.g. BVM = 6000_H

$$V_{BAVM} [V] = (6000_H \times 2 V) / 2^{15} = 1.5 V$$

Using the [BAVM formula](#) a voltage of 1.5 V for V_{BAVM} is calculated.

Please note: For BVM_MODE smaller than 16-bit mode, the host controller can set the LSBs of the BVM register value to 0_B for positive results (MSB = 0_B) and 1_B for negative results (MSB = 1_B).

3.4.2 Temperature measurement unit

The results of the NTC resistance measurement are stored in the EXT_TEMP_0 - EXT_TEMP_4 (29_H - 2D_H) registers. The NTC resistor value is calculated with the following [TMP formula](#):

$$R_{NTC} [\Omega] = EXT_TEMP_z.RESULT [LSB10] \times FSR_{TMP} [V] \times 4^{EXT_TEMP_z.INTC} / (2^{10} \times 320 \mu A) - R_{TMP}; INTC = 0 \text{ to } 3 \text{ (used current source)}$$

e.g. EXT_TEMP_0 = 2747_H (RESULT[LSB10] = 347_H; INTC=1_H), $R_{TMP} = 100 \Omega$

$$R_{NTC} [\Omega] = (347_H * 2 V * 4^1) / (2^{10} * 320 \mu A) - 100 \Omega = 20.4 k\Omega$$

3.5 Balancing

Passive balancing can be activated to equalize the voltage levels of the connected battery cells. In the configuration register BAL_SETTINGS 16_H, the cells to be balanced can be selected in any combination including for all channels at the same time. To automatically switch off balancing during a cell voltage measurement and to delay the cell voltage measurement after balancing, see [Cell voltage measurement](#). To select all 12 cell for the first sensing IC in the chain, the following sequence must be send:

Table 24 Write register BAL_SETTINGS 16_H

Frame-type	Value	Comment
Synchronization	1E _H	Fixed synchronization frame; necessary to start the communication with a defined scheme.

(table continues...)

3 Software guideline

Table 24 (continued) Write register BAL_SETTINGS 16_H

Frame-type	Value	Comment
ID	81 _H	MSB = 1 indicates a write command; 6-bit device ID = 000001 _B .
Address	16 _H	Address of BAL_SETTINGS register.
Data	0FFF _H	Sets BAL_SETTINGS = 0FFF _H to switch on the balancing drivers for cell 0 to 11.
CRC	3A _H	CRC-code is based on 8-bit polynomial shown in CRC .

3.6 Sleep mode and register reset

3.6.1 Sleep mode

The IC can be send into sleep mode by setting the sleep mode bit PD in the OP_MODE register. The registers that are supplied in sleep mode are not reset.

Table 25 Write register OP_MODE 14_H

Frame-type	Value	Comment
Synchronization	1E _H	Fixed synchronization frame; necessary to start the communication with a defined scheme.
ID	81 _H	MSB = 1 indicates a write command; 6-bit device ID = 000001 _B .
Address	14 _H	Address of OP_MODE register.
Data	C401 _H	Sets PD = 1 _H activate sleep mode (using default values for the remaining bitfields).
CRC	4D _H	CRC-code is based on 8-bit polynomial shown in CRC .

3.6.2 Sleep mode registers reset

The bit SLEEP_REG_RESET in the OP_MODE register resets all registers (including registers that are supplied in sleep mode) and activates sleep mode.

Table 26 Write register OP_MODE 14_H

Frame-type	Value	Comment
Synchronization	1E _H	Fixed synchronization frame; necessary to start the communication with a defined scheme.
ID	81 _H	MSB = 1 indicates a write command; 6-bit device ID = 000001 _B .
Address	14 _H	Address of OP_MODE register.
Data	C404 _H	Sets SLEEP_REG_RESET = 1 _H resets all registers and activates sleep mode (using default values for the remaining bitfields).
CRC	24 _H	CRC-code is based on 8-bit polynomial shown in CRC .

To reset the sleep mode register for all devices in the daisy chain, the following command sequence must be sent:

1. Set SLEEP_REG_RESET bit in the OP_MODE register for the IC with the highest node ID

3 Software guideline

- 2.** After 4 ms, check whether the highest NODE_ID has performed the reset and is in sleep mode. To do this, send a read command to this node ID. This wake up the device.
- 3.** The highest node is now configured as NODE_ID = 0 (default) and must therefore be configured with the correct NODE_ID.
- 4.** Repeat the process with the second highest NODE_ID, etc.

Note: The PS_ERR_SLEEP bit in the GEN_DIAG register might be set after a sleep mode register reset. The bit must be manually set to 0_H.

4 Registers

4 Registers

4.1 Registers overview

This chapter gives an overview of the registers of the TLE9012DQU. Empty register bitfields or bitfields labeled “RES” (reserved for future use) are as the name indicates reserved for potential future use. When writing into a register, the “RES” part of the register must always be written with “0”. The same applies for read-only bitfields.

When reading, the contents of the “RES” fields should be masked out since the value is not defined.

- r = read access
- w = write access
- wo = write access only one time
- h = the IC hardware can change the contents of the field
- rocw = read-only, clear bit by writing a “0” to the respective bit position
- roctl = read-only, clear bit by writing a “0”, linked register is reset to default state
- rocr = read-only, clearing bit by reading

4.2 Registers overview - REG (ascending offset address)

Table 27 Registers overview - REG (ascending offset address)

Short name	Long name	Offset address	Access mode		Reset	Page number
			Read	Write		
PART_CONFIG	Partitioning config (supplied in sleep)	0001 _H	U	U	Reset	64
OL_OV_THR	Cell voltage thresholds (supplied in sleep)	0002 _H	U	U	Reset	65
OL_UV_THR	Cell voltage thresholds (supplied in sleep)	0003 _H	U	U	Reset	66
TEMP_CONF	Temperature measurement configuration (supplied in sleep)	0004 _H	U	U	Reset	67
INT_OT_WARN_CONF	Internal temperature measurement configuration (supplied in sleep)	0005 _H	U	U	Reset	68
RR_ERR_CNT	Round robin ERR counters (supplied in sleep)	0008 _H	U	U	Reset	69
RR_CONFIG	Round robin configuration (supplied in sleep)	0009 _H	U	U	Reset	70
FAULT_MASK	ERR pin / EMM mask (supplied in sleep)	000A _H	U	U	Reset	72
GEN_DIAG	General diagnostics (supplied in sleep)	000B _H	U	U	Reset	74
CELL_UV	Cell voltage supervision warning flags UV (supplied in sleep)	000C _H	U	U	Reset	77

(table continues...)

4 Registers

Table 27 (continued) Registers overview - REG (ascending offset address)

Short name	Long name	Offset address	Access mode		Reset	Page number
			Read	Write		
CELL_OV	Cell voltage supervision warning flags OV (supplied in sleep)	000D _H	U	U	Reset	78
EXT_TEMP_DIAG	External overtemperature warning flags (supplied in sleep)	000E _H	U	U	Reset	79
DIAG_OL	Diagnostics open load (supplied in sleep)	0010 _H	U	U	Reset	81
REG_CRC_ERR	REG_CRC_ERR (supplied in sleep)	0011 _H	U	U	Reset	82
CELL_UV_DAC_C OMP	Cell voltage supervision warning flags UV (supplied in sleep)	0012 _H	U	U	Reset	83
CELL_OV_DAC_C OMP	Cell voltage supervision warning flags OV (supplied in sleep)	0013 _H	U	U	Reset	84
OP_MODE	Operation mode	0014 _H	U	U	Reset	85
BAL_CURR_THR	Balancing current thresholds	0015 _H	U	U	Reset	86
BAL_SETTINGS	Balance settings	0016 _H	U	U	Reset	87
AVM_CONFIG	Auxiliary voltage measurement configuration	0017 _H	U	U	Reset	88
MEAS_CTRL	Measurement control	0018 _H	U	U	Reset	90
PCVM_i	Primary cell voltage measurement i	0019 _{H+i}	U	nBE	Reset	92
SCVM_HIGH	SCVM highest cell voltage	0025 _H	U	nBE	Reset	93
SCVM_LOW	SCVM lowest cell voltage	0026 _H	U	nBE	Reset	94
STRESS_PCVM	Stress correction PCVM	0027 _H	U	nBE	Reset	95
BVM	Block voltage measurement	0028 _H	U	nBE	Reset	96
EXT_TEMP_0	Temp result 0	0029 _H	U	U	Reset	97
EXT_TEMP_1	Temp result 1	002A _H	U	U	Reset	98
EXT_TEMP_2	Temp result 2	002B _H	U	U	Reset	99
EXT_TEMP_3	Temp result 3	002C _H	U	U	Reset	100
EXT_TEMP_4	Temp result 4	002D _H	U	U	Reset	101
EXT_TEMP_R_DIAG AG	Temp result R diagnose	002F _H	U	nBE	Reset	102
INT_TEMP	Chip temperature	0030 _H	U	nBE	Reset	103
MULTI_READ	Multiread command	0031 _H	U	nBE	Reset	104
MULTI_READ_CFG	Multiread configuration	0032 _H	U	U	Reset	105

(table continues...)

4 Registers

Table 27 (continued) Registers overview - REG (ascending offset address)

Short name	Long name	Offset address	Access mode		Reset	Page number
			Read	Write		
BAL_DIAG_OC	Passive balancing diagnostics OVERCURRENT	0033 _H	U	U	Reset	106
BAL_DIAG_UC	Passive balancing diagnostics UNDERCURRENT	0034 _H	U	U	Reset	107
INT_TEMP_2	Chip temperature 2	0035 _H	U	nBE	Reset	108
CONFIG	Configuration	0036 _H	U	U	Reset	109
GPIO	General purpose input / output	0037 _H	U	U	Reset	110
GPIO_PWM	PWM settings	0038 _H	U	U	Reset	112
ICVID	IC version and manufacturing ID	0039 _H	U	nBE	Reset	113
MAILBOX	Mailbox register	003A _H	U	U	Reset	114
CUSTOMER_ID_0	Customer ID 0	003B _H	U	nBE	Reset	115
CUSTOMER_ID_1	Customer ID 1	003C _H	U	nBE	Reset	116
WDOG_CNT	Watchdog counter	003D _H	U	U	Reset	117
SCVM_CONFIG	SCVM configuration	003E _H	U	U	Reset	118
STRESS_AUX	Stress correction AUX	003F _H	U	nBE	Reset	119
BAL_PWM	Balancing PWM	005B _H	U	U	Reset	120
BAL_CNT_0	Balancing counter register 0	005C _H	U	U	Reset	121
BAL_CNT_1	Balancing counter register 1	005D _H	U	U	Reset	122
BAL_CNT_2	Balancing counter register 2	005E _H	U	U	Reset	123
BAL_CNT_3	Balancing counter register 3	005F _H	U	U	Reset	124

4 Registers

4.3 Partitioning config (supplied in sleep)

PART_CONFIG

Offset address: 0001_H

Partitioning config [supplied in sleep)

Reset value: 0800_H

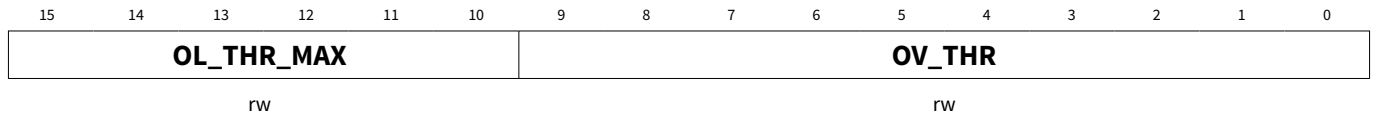
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
				EN_C ELL1 1	EN_C ELL1 0	EN_C ELL9	EN_C ELL8	EN_C ELL7	EN_C ELL6	EN_C ELL5	EN_C ELL4	EN_C ELL3	EN_C ELL2	EN_C ELL1	EN_C ELL0
				rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw

Field	Bits	Type	Description
EN_CELLi (i=0-10)	i	rw	Enable cell monitoring for cell i 0 _B NO_CELL_ATTACHED : No cell attached (default) 1 _B CELL_ATTACHED : Cell attached
EN_CELL11	11	rw	Enable cell monitoring for cell 11 0 _B NO_CELL_ATTACHED : No cell attached 1 _B CELL_ATTACHED : Cell attached (default)

4 Registers

4.4 Cell voltage thresholds (supplied in sleep)

OL_OV_THR Offset address: 0002_H
Cell voltage thresholds [supplied in sleep] Reset value: FFFF_H

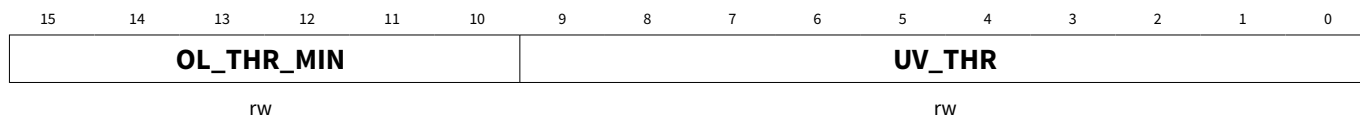


Field	Bits	Type	Description
OV_THR	9:0	rw	<p>Overvoltage fault threshold</p> <p>10-bit overvoltage fault threshold. Battery input voltages (U0 to U11) are tested for overvoltage with given value. OV error is detected and indicated in GEN_DIAG register if cell voltage is higher than OV fault threshold.</p> <p>3FF_H THRESHOLD: Threshold (default)</p>
OL_THR_MAX	15:10	rw	<p>Open load maximum voltage drop threshold (LSB8)</p> <p>6-bit (LSB8) to define the maximum threshold for the voltage drop while OL-diagnostics ($I_{OL_DIAG} * R_F$). If voltage drop > OL_THR_MAX, the OLx bit of channel x is set.</p> <p>3F_H THRESHOLD: Threshold (default)</p>

4 Registers

4.5 Cell voltage thresholds (supplied in sleep)

OL_UV_THR Offset address: 0003_H
Cell voltage thresholds [supplied in sleep] Reset value: 0000_H



Field	Bits	Type	Description
UV_THR	9:0	rw	<p>Undervoltage fault threshold</p> <p>10-bit undervoltage fault threshold. Battery input voltages (U0 to U11) are tested for undervoltage with given value. UV error is detected and indicated in GEN_DIAG register if cell voltage is lower than UV fault threshold.</p> <p>000_H THRESHOLD: Threshold (default)</p>
OL_THR_MIN	15:10	rw	<p>Open load minimum voltage drop threshold (LSB8)</p> <p>6-bit (LSB8) to define the minimum threshold for the voltage drop while OL-diagnostics ($I_{OL_DIAG} * R_F$). If voltage drop < OL_THR_MIN, the OLx bit of channel x is set.</p> <p>00_H THRESHOLD: Threshold (default)</p>

4 Registers

4.6 Temperature measurement configuration (supplied in sleep)

TEMP_CONF

Temperature measurement configuration [supplied in sleep)

Offset address: 0004_H

Reset value: 0000_H

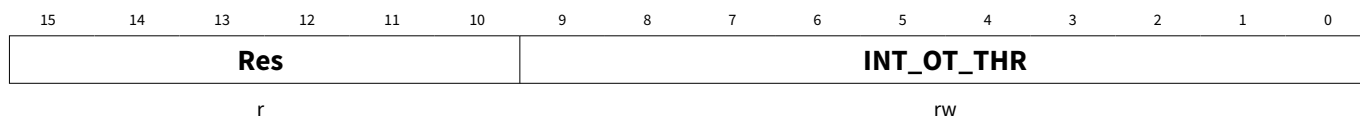
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Res		NR_TEMP_SENSE		I_NTC		EXT_OT_THR									
r		rw		rw		rw									

Field	Bits	Type	Description
EXT_OT_THR	9:0	rw	<p>External overtemperature threshold</p> <p>10-bit overtemperature fault threshold. Overtemperature error is detected and indicated in GEN_DIAG register if the external temperature result is lower than the fault threshold. Balancing is deactivated.</p> <p>000_H THRESHOLD: Threshold (default)</p>
I_NTC	11:10	rw	<p>Current source used for OT fault</p> <p>00_B I_0: ITMPz_0 used (default) 01_B I_1: ITMPz_1 used 10_B I_2: ITMPz_2 used 11_B I_3: ITMPz_3 used</p>
NR_TEMP_SENSE	14:12	rw	<p>Number of external temperature sensors</p> <p>000_B NO_EXT_SENSOR: No external TMP sensor (default) 001_B TMP0: TMP0 active 010_B TMP0_1: TMP0 + TMP1 active 011_B TMP0_2: TMP0 + TMP1 + TMP2 active 100_B TMP0_3: TMP0 + TMP1 + TMP2 + TMP3 active 101_B TMP0_4: TMP0 + TMP1 + TMP2 + TMP3 + TMP4 active</p>

4 Registers

4.7 Internal temperature measurement configuration (supplied in sleep)

INT_OT_WARN_CONF Offset address: 0005_H
Internal temperature measurement configuration [supplied in sleep] Reset value: 0000_H

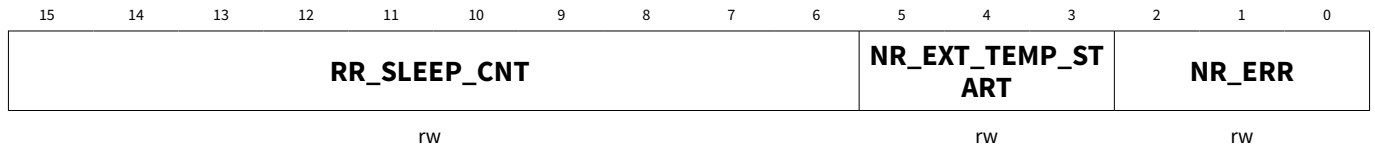


Field	Bits	Type	Description
INT_OT_THR	9:0	rw	<p>Internal overtemperature threshold</p> <p>10-bit overtemperature fault threshold. Overtemperature error is detected and indicated in GEN_DIAG register if the internal temperature result is LOWER than the fault threshold. Balancing is deactivated.</p> <p>000_H THRESHOLD: Threshold (default)</p>

4 Registers

4.8 Round robin ERR counters (supplied in sleep)

RR_ERR_CNT Offset address: 0008_H
Round robin ERR counters [supplied in sleep] Reset value: 0002_H



Field	Bits	Type	Description
NR_ERR	2:0	rw	<p>Number of errors</p> <p>Number of consecutive detected errors before error is valid and set in GEN_DIAG and individual fault registers. Only used for faults where counter NR_ERR is active (this can be set in register NR_ERR_MASK). Please note: The register CRC errors as well as the internal IC errors do not have an error counter.</p> <p>000_B ERR_0: 0 001_B ERR_1: 1 010_B ERR_2: 2 (default) 011_B ERR_3: 3 100_B ERR_4: 4 101_B ERR_5: 5 110_B ERR_6: 6 111_B ERR_7: 7</p>
NR_EXT_TEMP_START	5:3	rw	<p>External temperature triggering in round robin</p> <p>000_B EVERY_RR: Every RR (default) 001_B 1RR_1RR_NO_MES: 1 RR measurement, 1 RR no measurement 010_B 1RR_2RR_NO_MES: 1 RR measurement, 2 RR no measurement 011_B 1RR_3RR_NO_MES: 1 RR measurement, 3 RR no measurement 100_B 1RR_4RR_NO_MES: 1 RR measurement, 4 RR no measurement 101_B 1RR_5RR_NO_MES: 1 RR measurement, 5 RR no measurement 110_B 1RR_6RR_NO_MES: 1 RR measurement, 6 RR no measurement 111_B 1RR_7RR_NO_MES: 1 RR measurement, 7 RR no measurement</p>
RR_SLEEP_CNT	15:6	rw	<p>Round robin timing in sleep mode</p> <p>000_H DEACT: RR in sleep mode is deactivated (default). 001_H RR_SLEEP_1: tRR_sleep_LSB 3FF_H RR_SLEEP_1023: tRR_sleep_LSB*1023</p>

4 Registers

4.9 Round robin configuration (supplied in sleep)

RR_CONFIG

Round robin configuration [supplied in sleep]

Offset address: 0009_H

Reset value: 8024_H

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
M_NR_ERR_BAL_OC	M_NR_ERR_BAL_UC	M_NR_ERR_CE_LL_OV	M_NR_ERR_CE_LL_UV	M_NR_ERR_IN_T_OT	M_NR_ERR_EX_T_T_ERR	M_NR_ERR_OL_ERR	M_NR_ERR_RAD_C_ER	RR_SYNC	RR_CNT						
rw	rw	rw	rw	rw	rw	rw	rw	rw	rw						

Field	Bits	Type	Description
RR_CNT	6:0	rw	Round robin counter 00 _H RR_0 : Round robin starts every tRR_min. 24 _H RR_36 : Round robin starts every tRR_min + 36 * tRR_LSB (default). 7F _H RR_127 : Round robin starts every tRR_max.
RR_SYNC	7	rw	Round robin synchronization 0 _B NO_SYNC : No synch with WD_CNT write access (default). 1 _B SYNC : Synch with WD_CNT write access (RR will be started by write access, if RR is already running the RR will be restarted from beginning again).
M_NR_ERR_A DC_ERR	8	rw	Mask NR_ERR counter for ADC error 0 _B DISABLE : No masking of NR_ERR. Counter is active (default). 1 _B ENABLE : NR_ERR counter masked. Fault valid after first detection.
M_NR_ERR_O L_ERR	9	rw	Mask NR_ERR counter for open load error 0 _B DISABLE : No masking of NR_ERR. Counter is active (default). 1 _B ENABLE : NR_ERR counter masked. Fault valid after first detection.
M_NR_ERR_EX T_T_ERR	10	rw	Mask NR_ERR counter for external temperature error 0 _B DISABLE : No masking of NR_ERR. Counter is active (default). 1 _B ENABLE : NR_ERR counter masked. Fault valid after first detection.
M_NR_ERR_IN T_OT	11	rw	Mask NR_ERR counter for internal temperature error 0 _B DISABLE : No masking of NR_ERR. Counter is active (default). 1 _B ENABLE : NR_ERR counter masked. Fault valid after first detection.
M_NR_ERR_CE LL_UV	12	rw	Mask NR_ERR counter for undervoltage error 0 _B DISABLE : No masking of NR_ERR. Counter is active (default). 1 _B ENABLE : NR_ERR counter masked. Fault valid after first detection.
M_NR_ERR_CE LL_OV	13	rw	Mask NR_ERR counter for overvoltage error 0 _B DISABLE : No masking of NR_ERR. Counter is active (default). 1 _B ENABLE : NR_ERR counter masked. Fault valid after first detection.

(table continues...)

4 Registers

(continued)

Field	Bits	Type	Description
M_NR_ERR_B AL_UC	14	rw	Mmask NR_ERR counter for balancing error undercurrent 0 _B DISABLE: No masking of NR_ERR. Counter is active (default). 1 _B ENABLE: NR_ERR counter masked. Fault valid after first detection.
M_NR_ERR_B AL_OC	15	rw	Mask NR_ERR counter for balancing error overcurrent 0 _B DISABLE: No masking of NR_ERR. Counter is active. 1 _B ENABLE: NR_ERR counter masked. Fault valid after first detection (default).

4 Registers

4.10 ERR pin / EMM mask (supplied in sleep)

FAULT_MASK

ERR pin / EMM mask [supplied in sleep]

Offset address: 000A_H

Reset value: 0000_H

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
M_BA L_ER R_OC	M_B AL_E RR_ UC	M_C ELL_ OV	M_C ELL_ UV	M_IN T_OT	M_E XT_T _ERR	M_R EG_C RC_E RR	M_IN T_IC _ERR	M_O L_ER R	M_A DC_E RR	ERR_ PIN	Res				
rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	r				

Field	Bits	Type	Description
ERR_PIN	5	rw	Enable Error PIN functionality 0 _B DISABLE: ERR pin deactivated, EMM signal active. Device goes back to the mode as it was before the EMM (default). 1 _B ENABLE: ERR Pin function enabled. Fault indication only via ERR Pin. EMM signal deactivated. If ERR PIN triggered, pin stays high (device is then in normal mode) until watchdog runs out or pin is cleared.
M_ADC_ERR	6	rw	EMM/ERR mask for ADC error 0 _B DISABLE: ERR/EMM will NOT be set if this type of error occurs (default). 1 _B ENABLE: ERR/EMM will be set for this type of error.
M_OL_ERR	7	rw	EMM/ERR mask for open load error 0 _B DISABLE: ERR/EMM will NOT be set if this type of error occurs (default). 1 _B ENABLE: ERR/EMM will be set for this type of error.
M_INT_IC_ERR	8	rw	EMM/ERR mask for internal IC error 0 _B DISABLE: ERR/EMM will NOT be set if this type of error occurs (default). 1 _B ENABLE: ERR/EMM will be set for this type of error.
M_REG_CRC_E RR	9	rw	EMM/ERR mask for register CRC error 0 _B DISABLE: ERR/EMM will NOT be set if this type of error occurs (default). 1 _B ENABLE: ERR/EMM will be set for this type of error.
M_EXT_T_ERR	10	rw	EMM/ERR mask for external temperature error 0 _B DISABLE: ERR/EMM will NOT be set if this type of error occurs (default). 1 _B ENABLE: ERR/EMM will be set for this type of error.
M_INT_OT	11	rw	EMM/ERR mask for internal temperature error 0 _B DISABLE: ERR/EMM will NOT be set if this type of error occurs (default). 1 _B ENABLE: ERR/EMM will be set for this type of error.

(table continues...)

4 Registers

(continued)

Field	Bits	Type	Description
M_CELL_UV	12	rw	EMM/ERR mask for cell undervoltage error 0 _B DISABLE: ERR/EMM will NOT be set if this type of error occurs (default). 1 _B ENABLE: ERR/EMM will be set for this type of error.
M_CELL_OV	13	rw	EMM/ERR mask for cell overvoltage error 0 _B DISABLE: ERR/EMM will NOT be set if this type of error occurs (default). 1 _B ENABLE: ERR/EMM will be set for this type of error.
M_BAL_ERR_U C	14	rw	EMM/ERR mask for balancing error undercurrent 0 _B DISABLE: ERR/EMM will NOT be set if this type of error occurs (default). 1 _B ENABLE: ERR/EMM will be set for this type of error.
M_BAL_ERR_O C	15	rw	EMM/ERR mask for balancing error overcurrent 0 _B DISABLE: ERR/EMM will NOT be set if this type of error occurs (default). 1 _B ENABLE: ERR/EMM will be set for this type of error.

4 Registers

4.11 General diagnostics (supplied in sleep)

GEN_DIAG

General diagnostics [supplied in sleep)

Offset address: 000B_H

Reset value: 0000_H

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
BAL_ERR_OC	BAL_ERR_UC	CELL_OV	CELL_UV	INT_OT	EXT_T_ER	REG_CRC_ERR	INT_I_C_ER	OL_E RR	ADC_ERR	PS_E RR_S LEEP	RR_A CTIV E	LOC K_M EAS	BAL_ACTI VE	MOT _MO B_N	UAR T_W AKE UP
rocwl	rocwl	rocwl	rocwl	rocw	rocwl	rocwl	rocw	rocwl	rocw	rocw	rh	rh	rh	rh	rh

Field	Bits	Type	Description
UART_WAKEUP	0	rh	Wake-up via UART 0 _B ISOUART : Wake-up via iso UART (default) 1 _B UART : Wake-up via UART (GPIO)
MOT_MOB_N	1	rh	Primary on Top/Bottom configuration 0 _B BOTTOM : Configured as primary on bottom (default) 1 _B TOP : Configured as primary on top
BAL_ACTIVE	2	rh	Balancing active 0 _B OFF : No balancing ongoing (default) 1 _B ON : Balancing ongoing, at least one channel is on
LOCK_MEAS	3	rh	Lock measurement This bit indicates an ongoing PCVM, SCVM, BVM or AVM measurement or a delayed RR. 0 _B MEAS_OFF : No measurement ongoing (default) 1 _B MEAS_ON : PCVM, SCVM, BVM or AVM measurement ongoing
RR_ACTIVE	4	rh	Round robin active This bit indicates if the round robin was active during read. 0 _B OFF : No round robin active (default) 1 _B ON : Round robin active
PS_ERR_SLEEP	5	rocw	Power supply error induced sleep 0 _B NO_ERR : No power supply error induced sleep (default) 1 _B ERR_OCCURED : Power supply error induced sleep occurred
ADC_ERR	6	rocw	ADC Error 0 _B NO_ERR : No ADC mismatch between sum of PCVM and BVM (default) 1 _B ERR_OCCURED : ERROR of ADC-result comparison. Balancing deactivated.

(table continues...)

4 Registers

(continued)

Field	Bits	Type	Description
OL_ERR	7	rocwl	<p>Open load error</p> <p>Please note: Resetting the error here resets also the respective detailed error register.</p> <p>0_B NO_ERR: No open load error (default)</p> <p>1_B ERR_OCCURED: Open load error occurred. Detailed information in the respective error register. Balancing deactivated.</p>
INT_IC_ERR	8	rocw	<p>Internal IC error</p> <p>0_B NO_ERR: No internal error (default)</p> <p>1_B ERR_OCCURED: Internal IC check error occurred. Balancing is deactivated.</p>
REG_CRC_ERR	9	rocwl	<p>Register CRC error</p> <p>Please note: Resetting the error here resets also the respective detailed error register.</p> <p>0_B NO_ERR: No CRC check error (default)</p> <p>1_B ERR_OCCURED: CRC check error occurred. Detailed information in the respective error register. Balancing deactivated.</p>
EXT_T_ERR	10	rocwl	<p>External temperature error</p> <p>Please note: Resetting the error here resets also the respective detailed error register.</p> <p>0_B NO_ERR: No external temperature error (default)</p> <p>1_B ERR_OCCURED: External temperature error occurred. Detailed information in the respective error register. Balancing is deactivated.</p>
INT_OT	11	rocw	<p>Internal temperature (OT) error</p> <p>0_B NO_ERR: No internal OT error (default)</p> <p>1_B ERR_OCCURED: Internal OT error occurred. Balancing is deactivated.</p>
CELL_UV	12	rocwl	<p>Cell undervoltage (UV) error</p> <p>Please note: Resetting the error here resets also the respective detailed error register.</p> <p>0_B NO_ERR: No UV error (default)</p> <p>1_B ERR_OCCURED: UV error occurred. Detailed information in the respective error register.</p>
CELL_OV	13	rocwl	<p>Cell overvoltage (OV) error</p> <p>Please note: Resetting the error here resets also the respective detailed error register.</p> <p>0_B NO_ERR: No OV error (default)</p> <p>1_B ERR_OCCURED: OV error occurred. Detailed information in the respective error register.</p>
BAL_ERR_UC	14	rocwl	<p>Balancing error undercurrent (will be reset in sleep mode)</p> <p>Please note: Resetting the error here resets also the respective detailed error register.</p> <p>0_B NO_ERR: No balancing error (default)</p> <p>1_B ERR_OCCURED: Balancing error occurred. Detailed information in the respective error register.</p>

(table continues...)

4 Registers

(continued)

Field	Bits	Type	Description
BAL_ERR_OC	15	rocwl	Balancing error overcurrent (will be reset in sleep mode) Please Note: Resetting the error here resets also the respective detailed error register. 0 _B NO_ERR : No balancing error (default) 1 _B ERR_OCCURED : Balancing error occurred. Detailed information in the respective error register.

4 Registers

4.12 Cell voltage supervision warning flags UV (supplied in sleep)

CELL_UV

Offset address: 000C_H

Cell voltage supervision warning flags UV [supplied in sleep)

Reset value: 0000_H

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
				UV_1 1	UV_1 0	UV_9	UV_8	UV_7	UV_6	UV_5	UV_4	UV_3	UV_2	UV_1	UV_0
				rocw	rocw	rocw	rocw	rocw	rocw	rocw	rocw	rocw	rocw	rocw	rocw

Field	Bits	Type	Description
UV_i (i=0-11)	i	rocw	<p>Undervoltage in cell i</p> <p>Can also be cleared on write '0' to connected GEN_DIAG register bit.</p> <p>0_B NO_UV: No undervoltage detected in respective cell (default)</p> <p>1_B UV: Undervoltage detected in respective cell. Balancing is deactivated.</p>

4 Registers

4.13 Cell voltage supervision warning flags OV (supplied in sleep)

CELL_OV

Offset address: 000D_H

Cell voltage supervision warning flags OV [supplied in sleep)

Reset value: 0000_H

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
				OV_1 1	OV_1 0	OV_9	OV_8	OV_7	OV_6	OV_5	OV_4	OV_3	OV_2	OV_1	OV_0
				rocw	rocw	rocw	rocw	rocw	rocw	rocw	rocw	rocw	rocw	rocw	rocw

Field	Bits	Type	Description
OV_i (i=0-11)	i	rocw	<p>Overvoltage in cell i</p> <p>Can also be cleared on write '0' to connected GEN_DIAG register bit.</p> <p>0_B NO_OV: No overvoltage detected in respective cell (default)</p> <p>1_B OV: Overvoltage detected in respective cell. Balancing is deactivated.</p>

4 Registers

4.14 External overtemperature warning flags (supplied in sleep)

EXT_TEMP_DIAG

External overtemperature warning flags [supplied in sleep)

Offset address: 000E_H

Reset value: 0000_H

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Res	OT4	SHO RT4	OPE N4	OT3	SHO RT3	OPE N3	OT2	SHO RT2	OPE N2	OT1	SHO RT1	OPE N1	OT0	SHO RT0	OPE N0
r	rocw	rocw	rocw	rocw	rocw	rocw	rocw	rocw	rocw	rocw	rocw	rocw	rocw	rocw	rocw

Field	Bits	Type	Description
OPEN0	0	rocw	Open load in external temp 0 Can also be cleared on write '0' to connected GEN_DIAG register bit. 0 _B NO_OL : No open load in external temp 0 (default) 1 _B OL_OCCURED : Open load in external temp 0
SHORT0	1	rocw	Short in external temp 0 Can also be cleared on write '0' to connected GEN_DIAG register bit. 0 _B NO_SHORT : No short in external temp 0 (default) 1 _B SHORT_OCCURED : Short in external temp 0
OT0	2	rocw	Overtemperature in external temp 0 Can also be cleared on write '0' to connected GEN_DIAG register bit. 0 _B NO_OT : No overtemperature in external temp 0 (default) 1 _B OT_OCCURED : ADC conversion of external temp 0 measurement < overtemperature threshold EXT_OT_THR
OPEN1	3	rocw	Open load in external temp 1 Can also be cleared on write '0' to connected GEN_DIAG register bit. 0 _B NO_OL : No open load in external temp 1 (default) 1 _B OL_OCCURED : Open load in external temp 1
SHORT1	4	rocw	Short in external temp 1 Can also be cleared on write '0' to connected GEN_DIAG register bit. 0 _B NO_SHORT : No short in external temp 1 (default) 1 _B SHORT_OCCURED : Short in external temp 1
OT1	5	rocw	Overtemperature in external temp 1 Can also be cleared on write '0' to connected GEN_DIAG register bit. 0 _B NO_OT : No overtemperature in external temp 1 (default) 1 _B OT_OCCURED : ADC conversion of external temp 1 measurement < overtemperature threshold EXT_OT_THR
OPEN2	6	rocw	Open load in external temp 2 Can also be cleared on write '0' to connected GEN_DIAG register bit. 0 _B NO_OL : No open load in external temp 2 (default) 1 _B OL_OCCURED : Open load in external temp 2

(table continues...)

4 Registers

(continued)

Field	Bits	Type	Description
SHORT2	7	rocw	Short in external temp 2 Can also be cleared on write '0' to connected GEN_DIAG register bit. 0 _B NO_SHORT : No short in external temp 2 (default) 1 _B SHORT_OCCURED : Short in external temp 2
OT2	8	rocw	Overtemperature in external temp 2 Can also be cleared on write '0' to connected GEN_DIAG register bit. 0 _B NO_OT : No overtemperature in external temp 2 (default) 1 _B OT_OCCURED : ADC conversion of external temp 2 measurement < overtemperature threshold EXT_OT_THR
OPEN3	9	rocw	Open load in external temp 3 Can also be cleared on write '0' to connected GEN_DIAG register bit. 0 _B NO_OL : No open load in external temp 3 (default) 1 _B OL_OCCURED : Open load in external temp 3
SHORT3	10	rocw	Short in external temp 3 Can also be cleared on write '0' to connected GEN_DIAG register bit. 0 _B NO_SHORT : No short in external temp 3 (default) 1 _B SHORT_OCCURED : Short in external temp 3
OT3	11	rocw	Overtemperature in external temp 3 Can also be cleared on write '0' to connected GEN_DIAG register bit. 0 _B NO_OT : No overtemperature in external temp 3 (default) 1 _B OT_OCCURED : ADC conversion of external temp 3 measurement < overtemperature threshold EXT_OT_THR
OPEN4	12	rocw	Open load in external temp 4 Can also be cleared on write '0' to connected GEN_DIAG register bit. 0 _B NO_OL : No open load in external temp 4 (default) 1 _B OL_OCCURED : Open load in external temp 4
SHORT4	13	rocw	Short in external temp 4 Can also be cleared on write '0' to connected GEN_DIAG register bit. 0 _B NO_SHORT : No short in external temp 4 (default) 1 _B SHORT_OCCURED : Short in external temp 4
OT4	14	rocw	Overtemperature in external temp 4 Can also be cleared on write '0' to connected GEN_DIAG register bit. 0 _B NO_OT : No overtemperature in external temp 4 (default) 1 _B OT_OCCURED : ADC conversion of external temp 4 measurement < overtemperature threshold EXT_OT_THR

4 Registers

4.15 Diagnostics open load (supplied in sleep)

DIAG_OL Offset address: 0010_H
Diagnostics open load [supplied in sleep] Reset value: 0000_H

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
				OL_1 1	OL_1 0	OL_9	OL_8	OL_7	OL_6	OL_5	OL_4	OL_3	OL_2	OL_1	OL_0
				rocw	rocw	rocw	rocw	rocw	rocw	rocw	rocw	rocw	rocw	rocw	rocw

Field	Bits	Type	Description
OL _i (i=0-11)	i	rocw	<p>Open load channel i</p> <p>Can also be cleared on write '0' to connected GEN_DIAG register bit.</p> <p>0_B NO_OL: No open load detected for respective channel (default)</p> <p>1_B OL: Open load detected for respective channel</p>

4 Registers

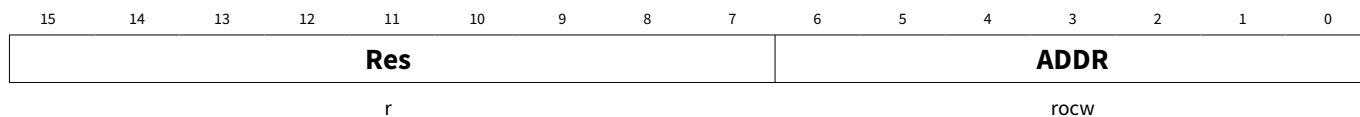
4.16 REG_CRC_ERR (supplied in sleep)

REG_CRC_ERR

Offset address: 0011_H

REG_CRC_ERR [supplied in sleep]

Reset value: 0000_H



Field	Bits	Type	Description
ADDR	6:0	roCW	<p>Register address of register where CRC check failed</p> <p>Register address of CRC check fail, can also be cleared on write '0' to connected GEN_DIAG register bit.</p> <p>00_H DEFAULT: Register address</p>

4 Registers

4.17 Cell voltage supervision warning flags UV (supplied in sleep)

CELL_UV_DAC_COMP

Offset address: 0012_H

Cell voltage supervision warning flags UV [supplied in sleep)

Reset value: 0000_H

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
				UV_1 1	UV_1 0	UV_9	UV_8	UV_7	UV_6	UV_5	UV_4	UV_3	UV_2	UV_1	UV_0
				rocw	rocw	rocw	rocw	rocw	rocw	rocw	rocw	rocw	rocw	rocw	rocw

Field	Bits	Type	Description
UV_i (i=0-11)	i	rocw	<p>Undervoltage in cell i</p> <p>Can also be cleared on write '0' to connected GEN_DIAG register bit.</p> <p>0_B NO_UV: No undervoltage detected in respective cell (default)</p> <p>1_B UV: Undervoltage detected in respective cell</p>

4 Registers

4.18 Cell voltage supervision warning flags OV (supplied in sleep)

CELL_OV_DAC_COMP

Offset address: 0013_H

Cell voltage supervision warning flags OV [supplied in sleep)

Reset value: 0000_H

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
				OV_1 1	OV_1 0	OV_9	OV_8	OV_7	OV_6	OV_5	OV_4	OV_3	OV_2	OV_1	OV_0
				rocw	rocw	rocw	rocw	rocw	rocw	rocw	rocw	rocw	rocw	rocw	rocw

Field	Bits	Type	Description
OV_i (i=0-11)	i	rocw	<p>Overvoltage in cell i</p> <p>Can also be cleared on write '0' to connected GEN_DIAG register bit.</p> <p>0_B NO_OV: No overvoltage detected in respective cell (default)</p> <p>1_B OV: Overvoltage detected in respective cell</p>

4 Registers

4.19 Operation mode

OP_MODE

Operation mode

Offset address:

0014_H

Reset value:

C400_H

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
LR_TIME						Res						I_DIA G_E N	SLEE P_RE G_RE SET	EXT_ WD	PD
rw						r						rw	rwh	rw	rw

Field	Bits	Type	Description
PD	0	rw	Activate sleep mode 0 _B NORMAL_OP : Chip operating in normal mode (default) 1 _B PWD_OP : Chip is set to sleep mode. No further communication possible after bit is set to '1'.
EXT_WD	1	rw	Extended watchdog 0 _B NOT_ACTIVE : No extended watchdog (default) 1 _B ACTIVE : Extended watchdog active
SLEEP_REG_R ESET	2	rwh	Sleep mode registers reset 0 _B NORMAL_OP : Chip operating in normal mode (default) 1 _B SLEEP_REG_RESET_OP : Resets all registers that are supplied in sleep mode. No further communication possible after bit is set to '1'.
I_DIAG_EN	3	rw	Force OL diagnostics currents 0 _B OFF : Diagnostics currents switched via round robin (default) 1 _B ON : Diagnostics currents enabled for all channels
LR_TIME	15:10	rw	Long-running mode measurement restart time 00 _H MIN : Minimum (1.17ms) 31 _H DEFAULT : 6.25 ms

4 Registers

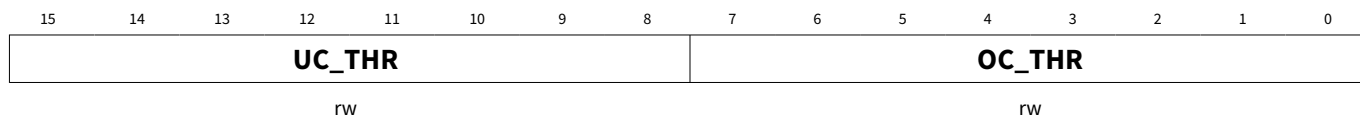
4.20 Balancing current thresholds

BAL_CURR_THR

Balancing current thresholds

Offset address: 0015_H

Reset value: 00AC_H



Field	Bits	Type	Description
OC_THR	7:0	rw	<p>Overcurrent fault threshold</p> <p>8-bit to define the maximum voltage drop during balancing diagnostics. If the voltage drop ($I_{Bal} * R_F$) > OC_THR the overcurrent is detected.</p> <p>AC_H DEFAULT: Default</p>
UC_THR	15:8	rw	<p>Undercurrent fault threshold</p> <p>8-bit to define the minimum voltage drop during balancing diagnostics. If the voltage drop ($I_{Bal} * R_F$) < UC_THR the undercurrent is detected.</p> <p>00_H DEFAULT: Default</p>

4 Registers

4.21 Balance settings

BAL_SETTINGS

Offset address: 0016_H

Balance settings

Reset value: 0000_H

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
				ON1 1	ON1 0	ON9	ON8	ON7	ON6	ON5	ON4	ON3	ON2	ON1	ON0
				rwh	rwh	rwh	rwh	rwh	rwh	rwh	rwh	rwh	rwh	rwh	rwh

Field	Bits	Type	Description
ON _i (i=0-11)	i	rwh	Switching state of balancing switch i 0 _B OFF : Respective balancing switch off (default) 1 _B ON : Respective balancing switch on

4 Registers

4.22 Auxiliary voltage measurement configuration

AVM_CONFIG

Auxiliary voltage measurement configuration

Offset address: 0017_H

Reset value: 0007_H

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
R_DI AG_C UR_S RC	R_DIAG_SE L_1	R_DIAG_SE L_0	Res	R_DI AG	AUX_ BIPO LAR	AVM_ _TM P4_ MAS K	AVM_ _TM P3_ MAS K	AVM_ _TM P2_ MAS K	AVM_ _TM P1_ MAS K	AVM_ _TM P0_ MAS K	TEMP_MUX_DIAG_ SEL				
rw	rw	rw	r	rw	rwh	rw	rw	rw	rw	rw	rw	rw	rw		

Field	Bits	Type	Description
TEMP_MUX_DIAG_SEL	2:0	rw	Selector for external temp diagnose 000 _B PD_EXT_TEMP_0 : Pulldown for external temp 0 measurement is active. 001 _B PD_EXT_TEMP_1 : Pulldown for external temp 1 measurement is active. 010 _B PD_EXT_TEMP_2 : Pulldown for external temp 2 measurement is active. 011 _B PD_EXT_TEMP_3 : Pulldown for external temp 3 measurement is active. 100 _B PD_EXT_TEMP_4 : Pulldown for external temp 4 measurement is active. 111 _B NO_PD : No pulldown is active (default),
AVM_TMP0_MASK	3	rw	Activate auxiliary measurement via deactive TMP0 as part of AVM 0 _B MASKED : Manual AVM TMP0 measurement masked out when AVM_START bit triggered (default). 1 _B PERFORMED : Manual AVM TMP0 measurement performed when AVM_START bit triggered.
AVM_TMP1_MASK	4	rw	Activate auxiliary measurement via deactive TMP1 as part of AVM 0 _B MASKED : Manual AVM TMP1 measurement masked out when AVM_START bit triggered (default). 1 _B PERFORMED : Manual AVM TMP1 measurement performed when AVM_START bit triggered.
AVM_TMP2_MASK	5	rw	Activate auxiliary measurement via deactive TMP2 as part of AVM 0 _B MASKED : Manual AVM TMP2 measurement masked out when AVM_START bit triggered (default). 1 _B PERFORMED : Manual AVM TMP2 measurement performed when AVM_START bit triggered.
AVM_TMP3_MASK	6	rw	Activate auxiliary measurement via deactive TMP3 as part of AVM 0 _B MASKED : Manual AVM TMP3 measurement masked out when AVM_START bit triggered (default). 1 _B PERFORMED : Manual AVM TMP3 measurement performed when AVM_START bit triggered.

(table continues...)

4 Registers

(continued)

Field	Bits	Type	Description
AVM_TMP4_MASK	7	rw	Activate auxiliary measurement via deactive TMP4 as part of AVM 0 _B MASKED : Manual AVM TMP4 measurement masked out when AVM_START bit triggered (default). 1 _B PERFORMED : Manual AVM TMP4 measurement performed when AVM_START bit triggered.
AUX_BIPOLAR	8	rwh	Bipolar AUX measurement instead of BVM 0 _B BVM : Normal BVM measurement 1 _B AUX : Bipolar AUX measurement instead of BVM (Bit is reset when NR_TEMP_SENSE > 3, this can cause a REG_CRC_ERR).
R_DIAG	9	rw	Masking diagnostics resistor as part of AVM 0 _B MASKED : Manual AVM diagnostics resistor measurement masked out when AVM_START bit triggered (default) 1 _B PERFORMED : Manual AVM diagnostics resistor measurement performed when AVM_START bit triggered
R_DIAG_SEL_0	12:11	rw	R_DIAG current source 0 00 _B I_0 : Source ITMP0_0: 320uA (default) 01 _B I_1 : Source ITMP0_1: 80uA 10 _B I_2 : Source ITMP0_2: 20uA 11 _B I_3 : Source ITMP0_3: 5uA
R_DIAG_SEL_1	14:13	rw	R_DIAG current source 1 00 _B I_0 : Source ITMP1_0: 320uA (default) 01 _B I_1 : Source ITMP1_1: 80uA 10 _B I_2 : Source ITMP1_2: 20uA 11 _B I_3 : Source ITMP1_3: 5uA
R_DIAG_CUR_SRC	15	rw	R_DIAG current source selection 0 _B SRC_0 : Current source 0 (default) 1 _B SRC_1 : Current source 1

4 Registers

4.23 Measurement control

MEAS_CTRL

Measurement control

Offset address: 0018_H

Reset value: 0021_H

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
PCVM _STA RT	CVM_MODE			BVM _STA RT	BVM_MODE			AVM _STA RT	SCV M_S TART	PBO FF	CVM_DEL				
rw	rw			rw	rw			rw	rw	rw	rw				

Field	Bits	Type	Description
CVM_DEL	4:0	rw	Wait time before CVM and/or BVM is started when PBOFF=1 00 _H NO_SETTLING_TIME : No settling time 01 _H 1 : tVM_del_LSB (default) 1F _H 31 : 31 x tVM_del_LSB
PBOFF	5	rw	Enable PBOFF 0 _B BAL_CONTINUE : Keep balancing state for PCVM/SCVM/BVM, no CVM_DEL. 1 _B BAL_INTERRUPT : Switch off balancing before conversion starts (default).
SCVM_START	6	rw	Start secondary cell voltage measurement Bit cleared if conversion done 0 _B NO_MEAS : No measurement ongoing (default) 1 _B TRIG_MEAS : Trigger measurement
AVM_START	7	rw	Start auxillary voltage measurement Bit cleared if conversion done 0 _B NO_MEAS : No measurement ongoing (default) 1 _B TRIG_MEAS : Trigger measurement if BVM_START=0
BVM_MODE	10:8	rw	Block voltage measurement mode 000 _B 10_BIT : 10 bit (default) 001 _B 11_BIT : 11 bit 110 _B 16_BIT : 16 bit 111 _B LONG : Long-running mode
BVM_START	11	rw	Start block voltage measurement Bit cleared if conversion done 0 _B NO_MEAS : No measurement ongoing (default) 1 _B TRIG_MEAS : Trigger measurement
CVM_MODE	14:12	rw	Cell voltage measurement mode 000 _B 10_BIT : 10 bit (default) 001 _B 11_BIT : 11 bit 110 _B 16_BIT : 16 bit 111 _B LONG : Long-running mode

(table continues...)

4 Registers

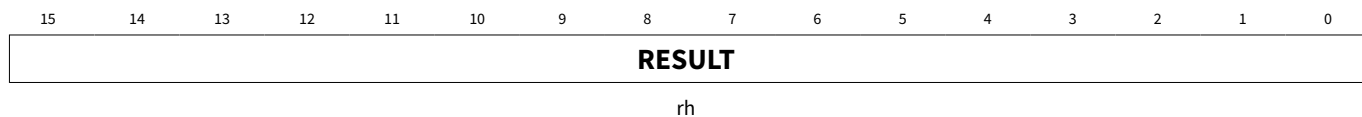
(continued)

Field	Bits	Type	Description
PCVM_START	15	rwh	Start primary cell voltage measurement Bit cleared if conversion done 0 _B NO_MEAS : No measurement ongoing (default) 1 _B TRIG_MEAS : Trigger measurement

4 Registers

4.24 Primary cell voltage measurement i

PCVM_i (i=0-11) Offset address: 0019_H+i
 Primary cell voltage measurement i Reset value: 0000_H



Field	Bits	Type	Description
RESULT	15:0	rh	Result of cell voltage measurement 0000 _H DEFAULT: Default

4 Registers

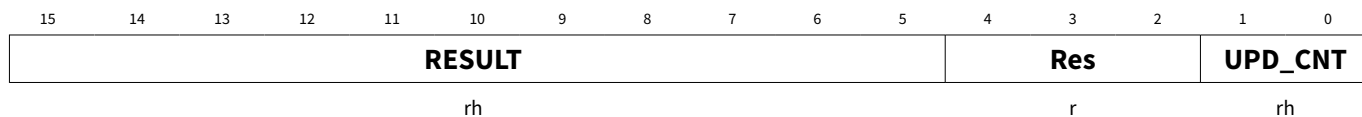
4.25 SCVM highest cell voltage

SCVM_HIGH

SCVM highest cell voltage

Offset address: 0025_H

Reset value: 0000_H



Field	Bits	Type	Description
UPD_CNT	1:0	rh	Update counter
RESULT	15:5	rh	Result of SCVM measurement (highest cell voltage)

4 Registers

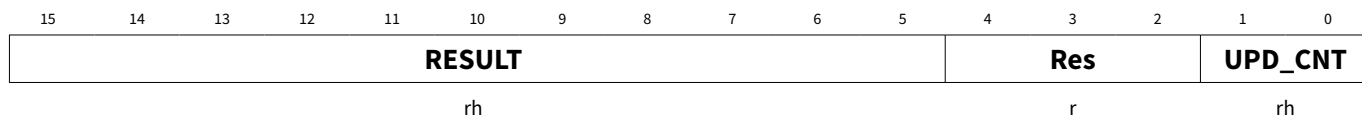
4.26 SCVM lowest cell voltage

SCVM_LOW

SCVM lowest cell voltage

Offset address: 0026_H

Reset value: 0000_H



Field	Bits	Type	Description
UPD_CNT	1:0	rh	Update counter
RESULT	15:5	rh	Result of SCVM measurement (lowest cell voltage)

4 Registers

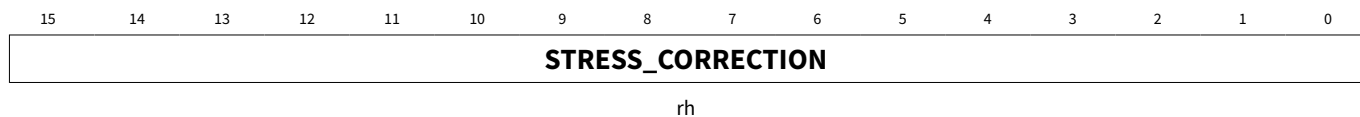
4.27 Stress correction PCVM

STRESS_PCVM

Stress correction PCVM

Offset address: 0027_H

Reset value: 0000_H



Field	Bits	Type	Description
STRESS_CORRECTION	15:0	rh	Stress correction value PCVM 0000 _H DEFAULT: Default

4 Registers

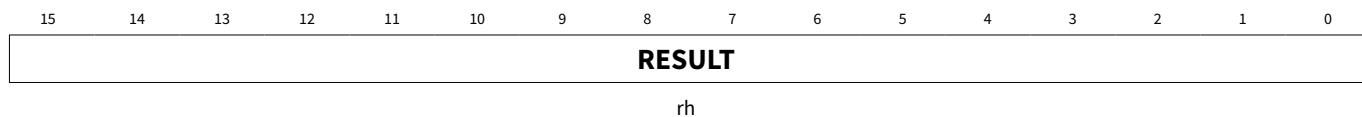
4.28 Block voltage measurement

BVM

Block voltage measurement

Offset address: 0028_H

Reset value: 0000_H



Field	Bits	Type	Description
RESULT	15:0	rh	Result of block voltage measurement 0000 _H DEFAULT: Default

4 Registers

4.29 Temp result 0

EXT_TEMP_0

Temp result 0

Offset address: 0029_H

Reset value: 0000_H

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Res	PD_ERR	VALID	PULLDOWN	INTC		RESULT									
r	rocw	rocr	rh	rh		rh									

Field	Bits	Type	Description
RESULT	9:0	rh	Result of external temp measurement SD-ADC result of resistance or voltage measurement. 000 _H DEFAULT : Default
INTC	11:10	rh	Indicates which current source was used Number of current source that was active for latest measurement. 00 _B I_0 : Source ITMPz_0 used (default) 01 _B I_1 : Source ITMPz_1 used 10 _B I_2 : Source ITMPz_2 used 11 _B I_3 : Source ITMPz_3 used
PULLDOWN	12	rh	Indicating pull-down switch state 0 _B NORMAL_MEAS : Normal measurement done (default) 1 _B PULL_DOWN : Pull-down for Mux-test was active during conversion.
VALID	13	rocr	Indicating a valid result 0 _B NO_NEW_RESULT : No new result available (default) 1 _B NEW_RESULT_STORED : A new result is stored in the register, cleared automatically after readout of the result register.
PD_ERR	14	rocw	Pull-down error Can also be cleared on write '0' to GEN_DIAG.EXT_T_ERR register bit. 0 _B NO_ERR : No pulldown error 1 _B ERR : Pulldown error

4 Registers

4.30 Temp result 1

EXT_TEMP_1

Temp result 1

Offset address: 002A_H

Reset value: 0000_H

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Res	PD_ERR	VALID	PULLDOWN	INTC		RESULT									
r	rocw	rocr	rh	rh		rh									

Field	Bits	Type	Description
RESULT	9:0	rh	Result of external temp measurement SD-ADC result of resistance or voltage measurement. 000 _H DEFAULT: Default
INTC	11:10	rh	Indicates which current source was used Number of current source that was active for latest measurement. 00 _B I_0: Source ITMPz_0 used (default) 01 _B I_1: Source ITMPz_1 used 10 _B I_2: Source ITMPz_2 used 11 _B I_3: Source ITMPz_3 used
PULLDOWN	12	rh	Indicating pull-down switch state 0 _B NORMAL_MEAS: Normal measurement done (default) 1 _B PULL_DOWN: Pull-down for Mux-test was active during conversion.
VALID	13	rocr	Indicating a valid result 0 _B NO_NEW_RESULT: No new result available (default) 1 _B NEW_RESULT_STORED: A new result is stored in the register, cleared automatically after readout of the result register.
PD_ERR	14	rocw	Pull-down error Can also be cleared on write '0' to GEN_DIAG.EXT_T_ERR register bit. 0 _B NO_ERR: No pulldown error 1 _B ERR: Pulldown error

4 Registers

4.31 Temp result 2

EXT_TEMP_2

Temp result 2

Offset address: 002B_H

Reset value: 0000_H

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Res	PD_ERR	VALID	PULLDOWN	INTC		RESULT									
r	rocw	rocr	rh	rh		rh									

Field	Bits	Type	Description
RESULT	9:0	rh	Result of external temp measurement SD-ADC result of resistance or voltage measurement. 000 _H DEFAULT: Default
INTC	11:10	rh	Indicates which current source was used Number of current source that was active for latest measurement. 00 _B I_0: Source ITMPz_0 used (default) 01 _B I_1: Source ITMPz_1 used 10 _B I_2: Source ITMPz_2 used 11 _B I_3: Source ITMPz_3 used
PULLDOWN	12	rh	Indicating pull-down switch state 0 _B NORMAL_MEAS: Normal measurement done (default) 1 _B PULL_DOWN: Pull-down for Mux-test was active during conversion.
VALID	13	rocr	Indicating a valid result 0 _B NO_NEW_RESULT: No new result available (default) 1 _B NEW_RESULT_STORED: A new result is stored in the register, cleared automatically after readout of the result register.
PD_ERR	14	rocw	Pull-down error Can also be cleared on write '0' to GEN_DIAG.EXT_T_ERR register bit. 0 _B NO_ERR: No pulldown error 1 _B ERR: Pulldown error

4 Registers

4.32 Temp result 3

EXT_TEMP_3

Temp result 3

Offset address: 002C_H

Reset value: 0000_H

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Res	PD_ERR	VALID	PULLDOWN	INTC		RESULT									
r	rocw	rocr	rh	rh		rh									

Field	Bits	Type	Description
RESULT	9:0	rh	Result of external temp measurement SD-ADC result of resistance or voltage measurement. 000 _H DEFAULT: Default
INTC	11:10	rh	Indicates which current source was used Number of current source that was active for latest measurement. 00 _B I_0: Source ITMPz_0 used (default) 01 _B I_1: Source ITMPz_1 used 10 _B I_2: Source ITMPz_2 used 11 _B I_3: Source ITMPz_3 used
PULLDOWN	12	rh	Indicating pull-down switch state 0 _B NORMAL_MEAS: Normal measurement done (default) 1 _B PULL_DOWN: Pull-down for Mux-test was active during conversion.
VALID	13	rocr	Indicating a valid result 0 _B NO_NEW_RESULT: No new result available (default) 1 _B NEW_RESULT_STORED: A new result is stored in the register, cleared automatically after readout of the result register.
PD_ERR	14	rocw	Pull-down error Can also be cleared on write '0' to GEN_DIAG.EXT_T_ERR register bit. 0 _B NO_ERR: No pulldown error 1 _B ERR: Pulldown error

4 Registers

4.33 Temp result 4

EXT_TEMP_4

Temp result 4

Offset address: 002D_H

Reset value: 0000_H

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Res	PD_ERR	VALID	PULLDOWN	INTC		RESULT									
r	rocw	rocr	rh	rh		rh									

Field	Bits	Type	Description
RESULT	9:0	rh	Result of external temp measurement SD-ADC result of resistance or voltage measurement. 000 _H DEFAULT: Default
INTC	11:10	rh	Indicates which current source was used Number of current source that was active for latest measurement. 00 _B I_0: Source ITMPz_0 used (default) 01 _B I_1: Source ITMPz_1 used 10 _B I_2: Source ITMPz_2 used 11 _B I_3: Source ITMPz_3 used
PULLDOWN	12	rh	Indicating pull-down switch state 0 _B NORMAL_MEAS: Normal measurement done (default) 1 _B PULL_DOWN: Pull-down for Mux-test was active during conversion.
VALID	13	rocr	Indicating a valid result 0 _B NO_NEW_RESULT: No new result available (default) 1 _B NEW_RESULT_STORED: A new result is stored in the register, cleared automatically after readout of the result register2.
PD_ERR	14	rocw	Pull-down error Can also be cleared on write '0' to GEN_DIAG.EXT_T_ERR register bit. 0 _B NO_ERR: No pulldown error 1 _B ERR: Pulldown error

4 Registers

4.34 Temp result R diagnose

EXT_TEMP_R_DIAG

Offset address: 002F_H

Temp result R diagnose

Reset value: 0000_H

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Res	VALID	CUR	INTC			RESULT									
r	rocr	rh	rh			rh									

Field	Bits	Type	Description
RESULT	9:0	rh	Result of diagnostics resistor measurement SD-ADC result of diagnostics resistor measurement. 000 _H DEFAULT: Default
INTC	11:10	rh	Indicates which current source was used Number of current source that was active for latest measurement. 00 _B I_0: Source ITMPz_0 used (default) 01 _B I_1: Source ITMPz_1 used 10 _B I_2: Source ITMPz_2 used 11 _B I_3: Source ITMPz_3 used
CUR_SRC	12	rh	Indicates which current source was used 0 _B SRC_0: Source 0 (default) 1 _B SRC_1: Source 1
VALID	13	rocr	Indicating a valid result 0 _B NO_NEW_RESULT: No new result available (default) 1 _B NEW_RESULT_STORED: A new result is stored in the register, cleared automatically after readout of the result register.

4 Registers

4.35 Chip temperature

INT_TEMP

Chip temperature

Offset address: 0030_H

Reset value: 0000_H

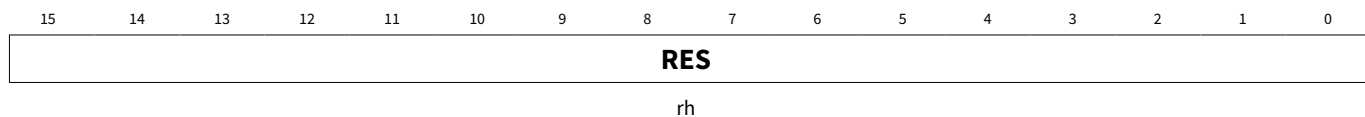
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Res		VALID				Res			RESULT						
r		rocr				r			rh						

Field	Bits	Type	Description
RESULT	9:0	rh	Result of internal temperatur measurement SD-ADC result of internal temperature measurement. 000 _H DEFAULT: Default
VALID	13	rocr	Indicating a valid result 0 _B NO_NEW_RESULT: No new result available (default) 1 _B NEW_RESULT_STORED: A new result is stored in the register, cleared automatically after readout of the result register.

4 Registers

4.36 Multiread command

MULTI_READ Offset address: 0031_H
Multiread command Reset value: 0000_H



Field	Bits	Type	Description
RES	15:0	rh	<p>Used in combination with MULTI_READ_CFG</p> <p>Reading this register by the host starts the multiple register read routine which got define in the MULTI_READ_CFG register.</p> <p>0000_H DEFAULT: Not defined (default)</p>

4 Registers

4.37 Multiread configuration

This register must be written with a broadcast write command.

MULTI_READ_CFG

Multiread configuration

Offset address: 0032_H

Reset value: 0000_H

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Res		STRESS_PCVM_SEL	SCVM_SEL	INT_TEMP_SEL	EXT_TEMP_SEL	EXT_TEMP_SEL			BVM_SEL	PCVM_SEL					
r		rw	rw	rw	rw	rw			rw	rw					

Field	Bits	Type	Description
PCVM_SEL	3:0	rw	Selects which PCVM results are part of the multiread No PCVM result for 1101 _B ...1111 _B 0 _H NO_PCVM : No PCVM result (default) 1 _H RES_CELL_11 : Only result for cell 11 2 _H RES_CELL_11_10 : Result of Cell 11-10 3 _H RES_CELL_11_9 : Result of Cell 11-9 C _H RES_CELL_11_0 : Result of Cell 11-0
BVM_SEL	4	rw	Selects if BVM result is part of multiread 0 _B NO_RESULT : No BVM result (default) 1 _B RESULT : Result of BVM
EXT_TEMP_SEL	7:5	rw	Selects which TEMP result is part of the multiread 000 _B NO_TEMP : No TEMP result (default) 001 _B RES_TMP0 : Result of TEMP_0 010 _B RES_TMP0_1 : Result of TEMP_0 & TEMP_1 011 _B RES_TMP0_2 : Result of TEMP_0 & TEMP_1 & TEMP_2 100 _B RES_TMP0_3 : Result of TEMP_0 & TEMP_1 & TEMP_2 & TEMP_3 101 _B RES_TMP0_4 : Result of TEMP_0 & TEMP_1 & TEMP_2 & TEMP_3 & TEMP_4
EXT_TEMP_R_SEL	8	rw	Selects if R_DIAG result is part of the multiread 0 _B NO_R_DIAG_RES : No R_DIAG result (default) 0 _B R_DIAG_RES : Result of R_DIAG
INT_TEMP_SEL	9	rw	0 _B NO_INT_TMP_RES : No INT_TEMP result (default) 1 _B INT_TMP_RES : Result of INT_TEMP
SCVM_SEL	10	rw	Selects if SCVM results are part of the multiread 0 _B NO_RESULT : No SCVM result (default) 1 _B RESULT : Result of SCVM_HIGH and SCVM_LOW
STRESS_PCVM_SEL	11	rw	Selects if PCVM stress correction value is part of the multiread 0 _B NO_RESULT : No STRESS_PCVM result (default) 1 _B RESULT : Result of STRESS_PCVM

4 Registers

4.38 Passive balancing diagnostics OVERCURRENT

BAL_DIAG_OC

Offset address: 0033_H

Passive balancing diagnostics OVERCURRENT

Reset value: 0000_H

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
				OC_1 1	OC_1 0	OC_9	OC_8	OC_7	OC_6	OC_5	OC_4	OC_3	OC_2	OC_1	OC_0
				rocw	rocw	rocw	rocw	rocw	rocw	rocw	rocw	rocw	rocw	rocw	rocw

Field	Bits	Type	Description
OC _i (i=0-11)	i	rocw	<p>Balancing overcurrent in cell i</p> <p>Can also be cleared on write '0' to connected GEN_DIAG register bit.</p> <p>0_B NO_OC: No balancing overcurrent detected in respective cell (default)</p> <p>1_B OC: Balancing overcurrent detected in respective cell. Balancing is deactivated for this cell.</p>

4 Registers

4.39 Passive balancing diagnostics UNDERCURRENT

BAL_DIAG_UC

Offset address: 0034_H

Passive balancing diagnostics UNDERCURRENT

Reset value: 0000_H

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
				UC_1 1	UC_1 0	UC_9	UC_8	UC_7	UC_6	UC_5	UC_4	UC_3	UC_2	UC_1	UC_0
				rocw	rocw	rocw	rocw	rocw	rocw	rocw	rocw	rocw	rocw	rocw	rocw

Field	Bits	Type	Description
UC _i (i=0-11)	i	rocw	<p>Balancing undercurrent in cell i</p> <p>Can also be cleared on write '0' to connected GEN_DIAG register bit.</p> <p>0_B NO_UC: No balancing undercurrent detected in respective cell (default)</p> <p>1_B UC: Balancing undercurrent detected in respective cell. Balancing is deactivated for this cell.</p>

4 Registers

4.40 Chip temperature 2

INT_TEMP_2

Chip temperature 2

Offset address: 0035_H

Reset value: 0000_H

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Res		VALID	Res			RESULT									
r		rocr	r			rh									

Field	Bits	Type	Description
RESULT	9:0	rh	Result of internal temperatur 2 measurement SD-ADC result of internal temperature 2 measurement. 000 _H DEFAULT: Default
VALID	13	rocr	Indicating a valid result 0 _B NO_NEW_RESULT: No new result available (default) 1 _B NEW_RESULT_STORED: A new result is stored in the register, cleared automatically after readout of the result register.

4 Registers

4.41 Configuration

CONFIG

Configuration

Offset address: 0036_H

Reset value: 0000_H

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Res			FN	Res	EN_A LL_A DC	Res			NODE_ID						
r			rwo	r	rw	r			rwo						

Field	Bits	Type	Description
NODE_ID	5:0	rwo	Address (ID) of the node, distributed during enumeration NODE_ID = 0 --> iso UART signals are not forwarded NODE_ID = 63 --> reserved for broadcast commands
EN_ALL_ADC	9	rw	Enable all ADCs If this bit is set, PCVM is done for each channel, independent of PART_CONFIG setup. 0 _B SEL_ADC : Only ADCs enabled which are defined in PART_CONFIG as active cell 1 _B ALL_ADC : All ADCs enabled
FN	11	rwo	Final Node The final node in stack must have this bit set. If final node does not have FN set, no reply frame on broadcast will be sent. 0 _B NOT_FN : Not the final node (default) 1 _B FN : Final node

4 Registers

4.42 General purpose input / output

GPIO

General purpose input / output

Offset address: 0037_H

Reset value: 0000_H

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
VIO_UV	Res	DIR_PWM0	OUT_PWM0	PWM_PWM0	IN_PWM0	DIR_PWM1	OUT_PWM1	PWM_PWM1	IN_PWM1	DIR_GPIO1	OUT_GPIO1	IN_GPIO1	DIR_GPIO0	OUT_GPIO0	IN_GPIO0
rocv	r	rw	rw	rw	rh	rw	rw	rw	rh	rw	rw	rh	rw	rw	rh

Field	Bits	Type	Description
IN_GPIO0	0	rh	GPIO 0 input state (ignored if communication over GPIO pins) 0 _B LOW: Pin reads L (default) Also active for DIR_GPIO0 =1 (reading back driven value). 1 _B HIGH: Pin reads H
OUT_GPIO0	1	rw	GPIO 0 output setting (ignored if communication over GPIO pins) 0 _B LOW: Drive L (default) 1 _B HIGH: Drive H
DIR_GPIO0	2	rw	GPIO 0 direction (ignored if communication over GPIO pins) 0 _B INPUT: Input (output stage = HiZ) (default) 1 _B OUTPUT: Output (output stage enabled)
IN_GPIO1	3	rh	GPIO 1 input state (ignored if communication over GPIO pins) 0 _B LOW: Pin reads L (default) Also active for DIR_GPIO1 =1 (reading back driven value). 1 _B HIGH: Pin reads H
OUT_GPIO1	4	rw	GPIO 1 output setting (ignored if communication over GPIO pins) 0 _B LOW: Drive L (default) 1 _B HIGH: Drive H
DIR_GPIO1	5	rw	GPIO 1 direction (ignored if communication over GPIO pins) 0 _B INPUT: Input (output stage = HiZ) (default) 1 _B OUTPUT: Output (output stage enabled)
IN_PWM1	6	rh	PWM 1 input state 0 _B LOW: Pin reads L (default) Also active for DIR_PWM1 =1 (reading back driven value). 1 _B HIGH: Pin reads H
PWM_PWM1	7	rw	PWM 1 enable PWM function 0 _B DISABLE: No PWM function (default) 1 _B ENABLE: If DIR_PWM1 = 1, then PWM output regarding PWM_GPIO register and OUT_PWM1 is ignored. If DIR_PWM1 = 0, GPIO input and no PWM function.

(table continues...)

4 Registers

(continued)

Field	Bits	Type	Description
OUT_PWM1	8	rw	PWM 1 output setting 0 _B LOW : Drive L (default) 1 _B HIGH : Drive H
DIR_PWM1	9	rw	PWM 1 direction 0 _B INPUT : Input (output stage = HiZ) (default) 1 _B OUTPUT : Output (output stage enabled)
IN_PWM0	10	rh	PWM 0 input state 0 _B LOW : Pin reads L (default) Also active for DIR_PWM0 = 1 (reading back driven value). 1 _B HIGH : Pin reads H
PWM_PWM0	11	rw	PWM 0 enable PWM function 0 _B DISABLE : No PWM function (default) 1 _B ENABLE : If DIR_PWM0 = 1, then PWM output regarding PWM_GPIO register and OUT_PWM0 is ignored. If DIR_PWM0 = 0, GPIO input and no PWM function.
OUT_PWM0	12	rw	PWM 0 Output Setting 0 _B LOW : Drive L (default) 1 _B HIGH : Drive H
DIR_PWM0	13	rw	PWM 0 direction 0 _B INPUT : Input (output stage = HiZ) (default) 1 _B OUTPUT : Output (output stage enabled)
VIO_UV	15	rocw	VIO undervoltage error 0 _B NO_ERR : No VIO undervoltage error (default) 1 _B ERR : VIO undervoltage error occurred

4 Registers

4.43 PWM settings

GPIO_PWM

PWM settings

Offset address: 0038_H

Reset value: 0000_H

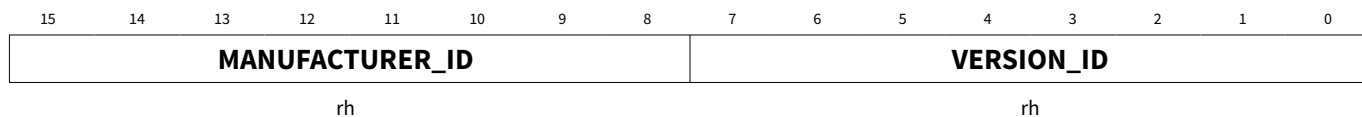
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Res		PWM_PERIOD						Res		PWM_DUTY_CYCLE					
r		rw						r		rw					

Field	Bits	Type	Description
PWM_DUTY_CYCLE	4:0	rw	PWM duty cycle 0 - 100% 00 _H OFF : No PWM (default) 01 _H 3_5 : 3.57% 02 _H 7_1 : 7.14% 1C _H 100 : 100% 1F _H 100_ : 100%
PWM_PERIOD	12:8	rw	PWM period time setting 2μs - 62μs 00 _H OFF : No PWM (default) 01 _H 2us : 2μs 02 _H 4us : 4 μs 1F _H 62us : 62μs

4 Registers

4.44 IC version and manufacturing ID

ICVID Offset address: 0039_H
IC version and manufacturing ID Reset value: C140_H



Field	Bits	Type	Description
VERSION_ID	7:0	rh	Version ID Read only version ID. 40 _H DEFAULT: Default
MANUFACTURER_ID	15:8	rh	Manufacturer ID Read only manufacture ID. C1 _H DEFAULT: Default

4 Registers

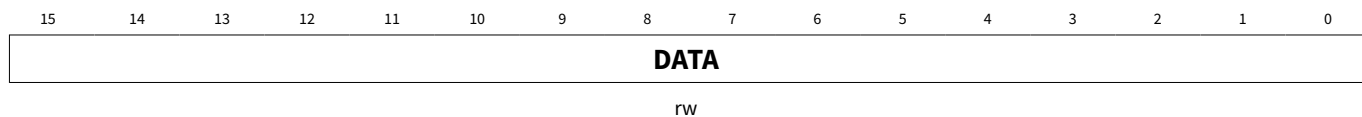
4.45 Mailbox register

MAILBOX

Mailbox register

Offset address: 003A_H

Reset value: 0000_H



Field	Bits	Type	Description
DATA	15:0	rw	Data storage register 2 data byte data storage

4 Registers

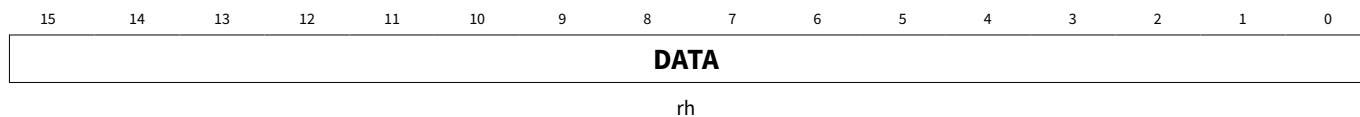
4.46 Customer ID 0

CUSTOMER_ID_0

Customer ID 0

Offset address: 003B_H

Reset value: 0000_H



Field	Bits	Type	Description
DATA	15:0	rh	Unique ID part 1

4 Registers

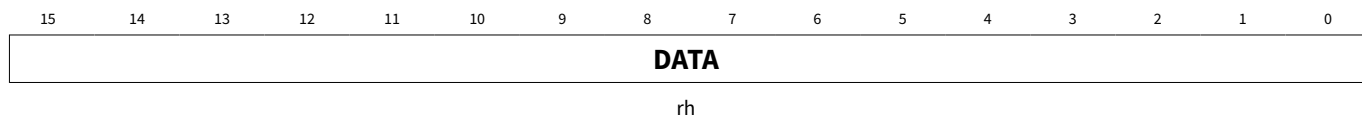
4.47 Customer ID 1

CUSTOMER_ID_1

Offset address: 003C_H

Customer ID 1

Reset value: 0000_H



Field	Bits	Type	Description
DATA	15:0	rh	Unique ID part 2

4 Registers

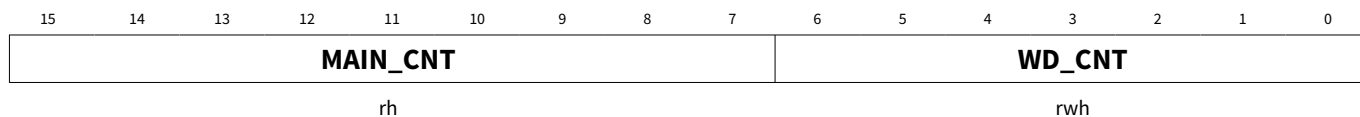
4.48 Watchdog counter

WDOG_CNT

Watchdog counter

Offset address: 003D_H

Reset value: 007F_H



Field	Bits	Type	Description
WD_CNT	6:0	rwh	<p>Watchdog counter</p> <p>00_H SLEEP: Device goes to sleep</p> <p>01_H 1: tWD_LSB (EXT_WD = 0) / tWD_EXT_LSB (EXT_WD = 1)</p> <p>7F_H 127: tWD_LSB * 127 (EXT_WD = 0) / tWD_EXT_LSB * 127 (EXT_WD = 1) (default)</p>
MAIN_CNT	15:7	rh	<p>Main counter</p> <p>Used to enable host controller to measure the main oscillator frequency. LSB = t_{Count_LSB}. Reset by write access to WD_CNT if RR_SYNC=1.</p> <p>000_H DEFAULT: Default</p>

4 Registers

4.49 SCVM configuration

SCVM_CONFIG

Offset address: 003E_H

SCVM configuration

Reset value: 0FFF_H

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
				EN_S CVM 11	EN_S CVM 10	EN_S CVM 9	EN_S CVM 8	EN_S CVM 7	EN_S CVM 6	EN_S CVM 5	EN_S CVM 4	EN_S CVM 3	EN_S CVM 2	EN_S CVM 1	EN_S CVM 0
				rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw	rw

Field	Bits	Type	Description
EN_SCVMi (i=0-11)	i	rw	Enable SCVM for cell i 0 _B DIS: SCVM disabled 1 _B EN: SCVM enabled (default)

4 Registers

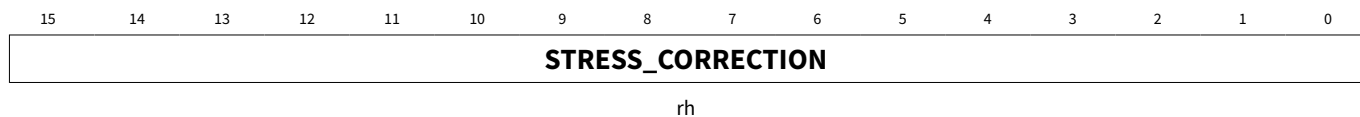
4.50 Stress correction AUX

STRESS_AUX

Stress correction AUX

Offset address: 003F_H

Reset value: 0000_H



Field	Bits	Type	Description
STRESS_CORRECTION	15:0	rh	Stress correction value PCVM 0000 _H DEFAULT: Default

4 Registers

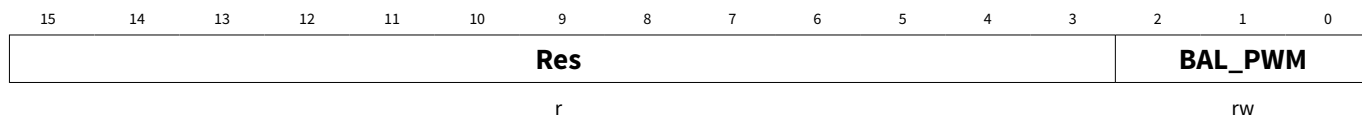
4.51 Balancing PWM

BAL_PWM

Balancing PWM

Offset address: 005B_H

Reset value: 0000_H



Field	Bits	Type	Description
BAL_PWM	2:0	rw	PWM balancing, starts with off-phase 000 _B VAL_0 : 100% duty cycle (function disabled) 001 _B VAL_1 : 87,5% duty cycle 111 _B VAL_7 : 12.5% duty cycle

4 Registers

4.52 Balancing counter register 0

BAL_CNT_0

Balancing counter register 0

Offset address: 005C_H

Reset value: 0000_H

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Res	BAL_CNT_2				BAL_CNT_1				BAL_CNT_0						
r	rw				rw				rw						

Field	Bits	Type	Description
BAL_CNT_0	4:0	rw	<p>Balancing counter to switch off balancing after a certain time, counter is (re-)started by a write access to WDOG_CNT when EXT_WD=1.</p> <p>01_H VAL_1: 7.5 min 1F_H VAL_31: 3.87 h</p>
BAL_CNT_1	9:5	rw	<p>Balancing counter to switch off balancing after a certain time, counter is (re-)started by a write access to WDOG_CNT when EXT_WD=1.</p> <p>01_H VAL_1: 7.5 min 1F_H VAL_31: 3.87 h</p>
BAL_CNT_2	14:10	rw	<p>Balancing counter to switch off balancing after a certain time, counter is (re-)started by a write access to WDOG_CNT when EXT_WD=1.</p> <p>01_H VAL_1: 7.5 min 1F_H VAL_31: 3.87 h</p>

4 Registers

4.53 Balancing counter register 1

BAL_CNT_1

Balancing counter register 1

Offset address: 005D_H

Reset value: 0000_H

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Res	BAL_CNT_5				BAL_CNT_4				BAL_CNT_3						
r	rw				rw				rw						

Field	Bits	Type	Description
BAL_CNT_3	4:0	rw	<p>Balancing counter to switch off balancing after a certain time, counter is (re-)started by a write access to WDOG_CNT when EXT_WD=1.</p> <p>01_H VAL_1: 7.5 min 1F_H VAL_31: 3.87 h</p>
BAL_CNT_4	9:5	rw	<p>Balancing counter to switch off balancing after a certain time, counter is (re-)started by a write access to WDOG_CNT when EXT_WD=1.</p> <p>01_H VAL_1: 7.5 min 1F_H VAL_31: 3.87 h</p>
BAL_CNT_5	14:10	rw	<p>Balancing counter to switch off balancing after a certain time, counter is (re-)started by a write access to WDOG_CNT when EXT_WD=1.</p> <p>01_H VAL_1: 7.5 min 1F_H VAL_31: 3.87 h</p>

4 Registers

4.54 Balancing counter register 2

BAL_CNT_2

Balancing counter register 2

Offset address: 005E_H

Reset value: 0000_H

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0	
Res	BAL_CNT_8				BAL_CNT_7				BAL_CNT_6							
r	rw				rw				rw							

Field	Bits	Type	Description
BAL_CNT_6	4:0	rw	<p>Balancing counter to switch off balancing after a certain time, counter is (re-)started by a write access to WDOG_CNT when EXT_WD=1.</p> <p>01_H VAL_1: 7.5 min 1F_H VAL_31: 3.87 h</p>
BAL_CNT_7	9:5	rw	<p>Balancing counter to switch off balancing after a certain time, counter is (re-)started by a write access to WDOG_CNT when EXT_WD=1.</p> <p>01_H VAL_1: 7.5 min 1F_H VAL_31: 3.87 h</p>
BAL_CNT_8	14:10	rw	<p>Balancing counter to switch off balancing after a certain time, counter is (re-)started by a write access to WDOG_CNT when EXT_WD=1.</p> <p>01_H VAL_1: 7.5 min 1F_H VAL_31: 3.87 h</p>

4 Registers

4.55 Balancing counter register 3

BAL_CNT_3

Balancing counter register 3

Offset address: 005F_H

Reset value: 0000_H

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Res	BAL_CNT_11				BAL_CNT_10				BAL_CNT_9						
r	rw				rw				rw						

Field	Bits	Type	Description
BAL_CNT_9	4:0	rw	<p>Balancing counter to switch off balancing after a certain time, counter is (re-)started by a write access to WDOG_CNT when EXT_WD=1.</p> <p>01_H VAL_1: 7.5 min 1F_H VAL_31: 3.87 h</p>
BAL_CNT_10	9:5	rw	<p>Balancing counter to switch off balancing after a certain time, counter is (re-)started by a write access to WDOG_CNT when EXT_WD=1.</p> <p>01_H VAL_1: 7.5 min 1F_H VAL_31: 3.87 h</p>
BAL_CNT_11	14:10	rw	<p>Balancing counter to switch off balancing after a certain time, counter is (re-)started by a write access to WDOG_CNT when EXT_WD=1.</p> <p>01_H VAL_1: 7.5 min 1F_H VAL_31: 3.87 h</p>

Revision history

Revision history

Revision	Date	Changes
1.0	2022-01-24	Initial release

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